RX110 Group
Renesas MCUs

R01DS0202EJ0120
Rev.1.20
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32 MHz 32-bit RX MCUs, 50 DMIPS, up to 128 Kbytes of flash memory, up to 5 comms channels, 12-bit A/D, RTC

Features

■ 32-bit RX CPU core

- 32 MHz maximum operating frequency
  Capable of 50 DMIPS when operating at 32 MHz
- Accumulator handles 64-bit results (for a single instruction) from 32-bit × 32-bit operations
- Multiplication and division unit handles 32-bit × 32-bit operations (multiplication instructions take one CPU clock cycle)
- Fast interrupt
- CISC Harvard architecture with five-stage pipeline
- Variable-length instruction format, ultra-compact code
- On-chip debugging circuit

■ Low power consumption functions

- Operation from a single 1.8 to 3.6 V supply
- Three low power modes
- Supply current
  High-speed operating mode: 0.1 mA/MHz
  Software standby mode: 0.35 µA
- Recovery time from software standby mode: 4.8 µs

■ On-chip flash memory for code, no wait states

- Operation at 32 MHz, read cycle of 31.25 ns
- No wait states for reading at full CPU speed
- 8 to 128 Kbyte capacities
- Programmable at 1.8 V
- For instructions and operands

■ On-chip SRAM, no wait states

- 8 to 16 Kbyte capacities

■ Data transfer controller (DTC)

- Four transfer modes
- Transfer can be set for each interrupt source.

■ Reset and power supply voltage management

- Six types including the power-on reset (POR)
- Low voltage detection (LVD) with voltage settings

■ Clock functions

- External clock input frequency: Up to 20 MHz
- Main clock oscillator frequency: 1 to 20 MHz
- Sub-clock oscillator frequency: 32.768 kHz
- Low-speed on-chip oscillator: 4 MHz
- High-speed on-chip oscillator: 32 MHz±1% (–20 to 85°C)
- IWDT-dedicated on-chip oscillator: 15 kHz
- Generate a dedicated 32.768-kHz clock for the RTC
- On-chip clock frequency accuracy measurement circuit (CAC)

■ Real-time clock (RTC)

- 30-second, leap year, and error adjustment functions
- Calendar count mode or binary count mode selectable
- Capable initiating exit from software standby mode



PLQP0064KB-A 10 × 10 mm, 0.5 mm pitch
PLQP0064GA-A 14 × 14 mm, 0.8 mm pitch
PLQP0048KB-A 7 × 7 mm, 0.5 mm pitch

PWQN0048KB-A 7 × 7 mm, 0.5 mm pitch
PWQN0040KC-A 6 × 6 mm, 0.5 mm pitch

PWLG0064KA-A 5 × 5 mm, 0.5 mm pitch
PWLG0036KA-A 4 × 4 mm, 0.5 mm pitch

■ Independent watchdog timer (WDT)

- 15-kHz on-chip oscillator produces a dedicated clock signal to drive IWDT operation.

■ On-chip functions for IEC 60730 compliance

- Clock frequency accuracy measurement circuit, IWDT, functions to assist in RAM testing, etc.

■ Up to five channels for communication

- SCI: Asynchronous mode, clock synchronous mode, smart card interface (up to seven channels)
- I^2C bus interface: Transfer at up to 400 kbps, capable of SMBus operation (one channel)
- RSPI: Up to 16 Mbps (one channel)

■ Up to 6 extended-function timers

- 16-bit MTU: Input capture/output compare, phase counting mode (four channels)
- 16-bit CMT (two channels)

■ 12-bit A/D converter

- Up to 14 channels
- 1.0 µs minimum conversion speed
- Double trigger (data duplication) function for motor control

■ Temperature sensor

■ General I/O ports

- 5-V tolerant, open drain, input pull-up

■ Multi-function pin controller (MPC)

- Multiple I/O pins can be selected for peripheral functions.

■ Unique ID

- 32-byte ID code for the MCU

■ Operating temperature range

- –40 to +85°C
- –40 to +105°C

1. Overview

1.1 Outline of Specifications

Table 1.1 lists the specifications, and Table 1.2 gives a comparison of the functions of the products in different packages.
Table 1.1 is for products with the greatest number of functions, so the number of peripheral modules and channels will differ in accordance with the package type. For details, see Table 1.2, Comparison of Functions for Different Packages.

Table 1.1 Outline of Specifications (1/3)

Classification	Module/Function	Description
CPU	CPU	• Maximum operating frequency: 32 MHz • 32-bit RX CPU • Minimum instruction execution time: One instruction per one clock cycle • Address space: 4-Gbyte linear • Register set General purpose: Sixteen 32-bit registers Control: Eight 32-bit registers Accumulator: One 64-bit register • Basic instructions: 73 • DSP instructions: 9 • Addressing modes: 10 • Data arrangement Instructions: Little endian Data: Selectable as little endian or big endian • On-chip 32-bit multiplier: 32-bit × 32-bit → 64-bit • On-chip divider: 32-bit ÷ 32-bit → 32 bits • Barrel shifter: 32 bits
Memory	ROM	• Capacity: 8 K /16 K /32 K /64 K /96 K /128 Kbytes • 32 MHz, no-wait memory access • Programming/erasing method: Serial programming (asynchronous serial communication), self-programming
	RAM	• Capacity: 8 K /10 K /16 Kbytes • 32 MHz, no-wait memory access
MCU operating mode		Single-chip mode
Clock	Clock generation circuit	• Main clock oscillator, sub-clock oscillator, low-speed on-chip oscillator, high-speed on-chip oscillator, and IWDT-dedicated on-chip oscillator • Oscillation stop detection: Available • Clock frequency accuracy measurement circuit (CAC) • Independent settings for the system clock (ICLK), peripheral module clock (PCLK), and FlashIF clock (FCLK) The CPU and system sections such as other bus masters run in synchronization with the system clock (ICLK): 32 MHz (at max.) Peripheral modules run in synchronization with the PCLK: 32 MHz (at max.) The flash peripheral circuit runs in synchronization with the FCLK: 32 MHz (at max.) • The ICLK frequency can only be set to FCLK, PCLKB, or PCLKD multiplied by n (n: 1, 2, 4, 8, 16, 32, 64).
Resets		RES# pin reset, power-on reset, voltage monitoring reset, independent watchdog timer reset, and software reset
Voltage detection	Voltage detection circuit (LVDAa)	• When the voltage on VCC falls below the voltage detection level, an internal reset or internal interrupt is generated. Voltage detection circuit 1 is capable of selecting the detection voltage from 10 levels Voltage detection circuit 2 is capable of selecting the detection voltage from 4 levels
Low power consumption	Low power consumption functions	• Module stop function • Three low power consumption modes Sleep mode, deep sleep mode, and software standby mode
	Function for lower operating power consumption	• Operating power control modes High-speed operating mode, middle-speed operating mode, and low-speed operating mode
Interrupt	Interrupt controller (ICUb)	• Interrupt vectors: 65 • External interrupts: 9 (NMI, IRQ0 to IRQ7 pins) • Non-maskable interrupts: 4 (NMI pin, voltage monitoring 1 interrupt, voltage monitoring 2 interrupt, and IWDT interrupt) • 16 levels specifiable for the order of priority
DMA	Data transfer controller (DTCa)	• Transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: Interrupts • Chain transfer function

Table 1.1 Outline of Specifications (2/3)

Classification	Module/Function	Description
I/O ports	General I/O ports	64-pin /48-pin /40-pin /36-pin • I/O: 50/34/28/24 • Input: 2/2/1/1 • Pull-up resistors: 42/28/23/20 • Open-drain outputs: 38/28/23/20 • 5-V tolerance: 4/4/4/4
Multi-function pin controller (MPC)		Capable of selecting the input/output function from multiple pins
Timers	Multi-function timer pulse unit 2 (MTU2b)	• (16 bits × 4 channels) × 1 unit • Time bases for the four 16-bit timer channels can be provided via up to 8 pulse-input/output lines and three pulse-input lines • Select from among eight or seven counter-input clock signals for each channel (PCLK/1, PCLK/4, PCLK/16, PCLK/64, PCLK/256, PCLK/1024, MTCLKA, MTCLKB, MTCLKC, MTCLKD) other than channel 5, for which only four signals are available. • Input capture function • 13 output compare/input capture registers • Pulse output mode • Phase counting mode • Generation of triggers for A/D converter conversion
	Compare match timer (CMT)	• (16 bits × 2 channels) × 1 unit • Select from among four clock signals (PCLK/8, PCLK/32, PCLK/128, PCLK/512)
	Independent watchdog timer (IWDTa)	• 14 bits × 1 channel • Count clock: Dedicated low-speed on-chip oscillator for the IWDT Frequency divided by 1, 16, 32, 64, 128, or 256
	Realtime clock (RTCA)	• Clock source: Sub-clock • Calendar count mode or binary count mode selectable • Interrupts: Alarm interrupt, periodic interrupt, and carry interrupt
Communication functions	Serial communications interfaces (SCIe, SCIf)	• 3 channels (channel 1, 5: SCIe, channel 12: SCIf) • Serial communications modes: Asynchronous, clock synchronous, and smart card interface • On-chip baud rate generator allows selection of the desired bit rate • Choice of LSB first or MSB first transfer • Average transfer rate clock can be input from MTU2 timers • Simple I^2C • Simple SPI • Master/slave mode supported (SCIf only) • Start frame and information frame are included (SCIf only) • Start-bit detection in asynchronous mode: Low level or falling edge is selectable (SCIe/SCIf)
	I^2C bus interface (RIIC)	• 1 channel • Communications formats: I^2C bus format/SMBus format • Master mode or slave mode selectable • Supports fast mode
	Serial peripheral interface (RSPI)	• 1 channel • Transfer facility Using the MOSI (master out, slave in), MISO (master in, slave out), SSL (slave select), and RSPI clock (RSPCK) signals enables serial transfer through SPI operation (four lines) or clock-synchronous operation (three lines) • Capable of handling serial transfer as a master or slave • Data formats • Choice of LSB first or MSB first transfer The number of bits in each transfer can be changed to 8, 9, 10, 11, 12, 13, 14, 15, 16, 20, 24, or 32 bits. 128-bit buffers for transmission and reception Up to four frames can be transmitted or received in a single transfer operation (with each frame having up to 32 bits) • Double buffers for both transmission and reception
12-bit A/D converter (S12ADb)		• 1 unit (1 unit × 14 channels) • 12-bit resolution • Minimum conversion time: 1.0 µs per channel when the ADCLK is operating at 32 MHz • Operating modes Scan mode (single scan mode, continuous scan mode, and group scan mode) • Double trigger mode (duplication of A/D conversion data) • A/D conversion start conditions A software trigger, a trigger from a timer (MTU), or an external trigger signal
Temperature sensor (TEMPSA)		• 1 channel • The voltage of the temperature is converted into a digital value by the 12-bit A/D converter.
CRC calculator (CRC)		• CRC code generation for arbitrary amounts of data in 8-bit units • Select any of three generating polynomials: $X^8 + X^2 + X + 1$, $X^{16} + X^{15} + X^2 + 1$, or $X^{16} + X^{12} + X^5 + 1$ • Generation of CRC codes for use with LSB first or MSB first communications is selectable.

Table 1.1 Outline of Specifications (3/3)

Classification	Module/Function	Description
Data operation circuit (DOC)		Comparison, addition, and subtraction of 16-bit data
Unique ID		32-byte ID code for the MCU
Power supply voltages/Operating frequencies		VCC = 1.8 to 2.4 V: 8 MHz, VCC = 2.4 to 2.7 V: 16 MHz, VCC = 2.7 to 3.6 V: 32 MHz
Supply current		3.2 mA at 32 MHz (typ.)
Operating temperatures		D version: –40 to +85°C, G version: –40 to +105°C
Packages		64-pin LFQFP (PLQP0064KB-A) 10 × 10 mm, 0.5 mm pitch 64-pin LQFP (PLQP0064GA-A) 14 × 14 mm, 0.8 mm pitch 64-pin WFLGA (PWLG0064KA-A) 5 × 5 mm, 0.5 mm pitch 48-pin LFQFP (PLQP0048KB-A) 7 × 7 mm, 0.5 mm pitch 48-pin HWQFN (PWQN0048KB-A) 7 × 7 mm, 0.5 mm pitch 40-pin HWQFN (PWQN0040KC-A) 6 × 6 mm, 0.5 mm pitch 36-pin WFLGA (PWLG0036KA-A) 4 × 4 mm, 0.5 mm pitch
On-chip debugging system		E1 emulator (FINE interface)

Table 1.2 Comparison of Functions for Different Packages

Module/Functions		RX110 Group			
		64 Pins	48 Pins	40 Pins	36 Pins
Interrupts	External interrupts	NMI, IRQ0 to IRQ7			
DMA	Data transfer controller	Supported			
Timers	Multi-function timer pulse unit 2	4 channels (MTU0 to MTU2, MTU5)			
	Compare match timer	2 channels × 1 unit			
	Realtime clock	Supported		Not supported	
	Independent watchdog timer	Supported			
Communication functions	Serial communications interfaces [simple I2C, simple SPI]	2 channels (SCI1, SCI5)			
	Serial communications interface [simple I2C, simple SPI]	1 channel (SCI12)			
	I2C bus interface	1 channel			
	Serial peripheral interface	1 channel	1 channel (SSLA1 and SSLA3 are not supported)		1 channel (SSLA1 to SSLA3 are not supported)
12-bit A/D converter (including high-precision channels)		14 channels (6 channels)	10 channels (4 channels)	8 channels (3 channels)	7 channels (2 channels)
Temperature sensor		Supported			
CRC calculator		Supported			
Packages		64-pin LFQFP 64-pin LQFP 64-pin WFLGA	48-pin LFQFP 48-pin HWQFN	40-pin HWQFN	36-pin WFLGA

1.2 List of Products

Table 1.3 is a list of products, and Figure 1.1 shows how to read the product part no., memory capacity, and package type.

Table 1.3 List of Products (1/2)

Group	Part No.	Orderable Part No.	Package	ROM Capacity	RAM Capacity	Maximum Operating Frequency	Operating Temperature
RX110	R5F51105AGFM	R5F51105AGFM#30	PLQP0064KB-A	128 Kbytes	16 Kbytes	32 MHz	–40 to +105°C
	R5F51105AGFK	R5F51105AGFK#30	PLQP0064GA-A				
	R5F51105AGFL	R5F51105AGFL#30	PLQP0048KB-A				
	R5F51105AGNE	R5F51105AGNE#U0	PWQN0048KB-A				
	R5F51104AGFM	R5F51104AGFM#30	PLQP0064KB-A	96 Kbytes			
	R5F51104AGFK	R5F51104AGFK#30	PLQP0064GA-A				
	R5F51104AGFL	R5F51104AGFL#30	PLQP0048KB-A				
	R5F51104AGNE	R5F51104AGNE#U0	PWQN0048KB-A				
	R5F51103AGFM	R5F51103AGFM#30	PLQP0064KB-A	64 Kbytes	10 Kbytes		
	R5F51103AGFK	R5F51103AGFK#30	PLQP0064GA-A				
	R5F51103AGFL	R5F51103AGFL#30	PLQP0048KB-A				
	R5F51103AGNE	R5F51103AGNE#U0	PWQN0048KB-A				
	R5F51103AGNF	R5F51103AGNF#U0	PWQN0040KC-A				
	R5F51101AGFM	R5F51101AGFM#30	PLQP0064KB-A	32 Kbytes			
	R5F51101AGFK	R5F51101AGFK#30	PLQP0064GA-A				
	R5F51101AGFL	R5F51101AGFL#30	PLQP0048KB-A				
	R5F51101AGNE	R5F51101AGNE#U0	PWQN0048KB-A				
	R5F51101AGNF	R5F51101AGNF#U0	PWQN0040KC-A				
	R5F5110JAGFM	R5F5110JAGFM#30	PLQP0064KB-A	16 Kbytes	8 Kbytes		
	R5F5110JAGFK	R5F5110JAGFK#30	PLQP0064GA-A				
	R5F5110JAGFL	R5F5110JAGFL#30	PLQP0048KB-A				
	R5F5110JAGNE	R5F5110JAGNE#U0	PWQN0048KB-A				
	R5F5110JAGNF	R5F5110JAGNF#U0	PWQN0040KC-A				
	R5F5110HAGNF	R5F5110HAGNF#U0	PWQN0040KC-A	8 Kbytes			

Table 1.3 List of Products (2/2)

Group	Part No.	Orderable Part No.	Package	ROM Capacity	RAM Capacity	Maximum Operating Frequency	Operating Temperature
RX110	R5F51105ADFM	R5F51105ADFM#30	PLQP0064KB-A	128 Kbytes	16 Kbytes	32MHz	–40 to +85°C
	R5F51105ADFK	R5F51105ADFK#30	PLQP0064GA-A				
	R5F51105ADLF	R5F51105ADLF#U0	PWLG0064KA-A				
	R5F51105ADFL	R5F51105ADFL#30	PLQP0048KB-A				
	R5F51105ADNE	R5F51105ADNE#U0	PWQN0048KB-A				
	R5F51104ADFM	R5F51104ADFM#30	PLQP0064KB-A	96 Kbytes			
	R5F51104ADFK	R5F51104ADFK#30	PLQP0064GA-A				
	R5F51104ADLF	R5F51104ADLF#U0	PWLG0064KA-A				
	R5F51104ADFL	R5F51104ADFL#30	PLQP0048KB-A				
	R5F51104ADNE	R5F51104ADNE#U0	PWQN0048KB-A				
	R5F51103ADFM	R5F51103ADFM#30	PLQP0064KB-A	64 Kbytes	10 Kbytes		
	R5F51103ADFK	R5F51103ADFK#30	PLQP0064GA-A				
	R5F51103ADLF	R5F51103ADLF#U0	PWLG0064KA-A				
	R5F51103ADFL	R5F51103ADFL#30	PLQP0048KB-A				
	R5F51103ADNE	R5F51103ADNE#U0	PWQN0048KB-A				
	R5F51103ADLM	R5F51103ADLM#U0	PWLG0036KA-A				
	R5F51103ADNF	R5F51103ADNF#U0	PWQN0040KC-A				
	R5F51101ADFM	R5F51101ADFM#30	PLQP0064KB-A	32 Kbytes			
	R5F51101ADFK	R5F51101ADFK#30	PLQP0064GA-A				
	R5F51101ADLF	R5F51101ADLF#U0	PWLG0064KA-A				
	R5F51101ADFL	R5F51101ADFL#30	PLQP0048KB-A				
	R5F51101ADNE	R5F51101ADNE#U0	PWQN0048KB-A				
	R5F51101ADLM	R5F51101ADLM#U0	PWLG0036KA-A				
	R5F51101ADNF	R5F51101ADNF#U0	PWQN0040KC-A				
	R5F5110JADFM	R5F5110JADFM#30	PLQP0064KB-A	16 Kbytes	8 Kbytes		
	R5F5110JADFK	R5F5110JADFK#30	PLQP0064GA-A				
	R5F5110JADLF	R5F5110JADLF#U0	PWLG0064KA-A				
	R5F5110JADFL	R5F5110JADFL#30	PLQP0048KB-A				
	R5F5110JADNE	R5F5110JADNE#U0	PWQN0048KB-A				
	R5F5110JADLM	R5F5110JADLM#U0	PWLG0036KA-A				
	R5F5110JADNF	R5F5110JADNF#U0	PWQN0040KC-A				
	R5F5110HADLM	R5F5110HADLM#U0	PWLG0036KA-A	8 Kbytes			
	R5F5110HADNF	R5F5110HADNF#U0	PWQN0040KC-A				

Note: Orderable part numbers are current as of when this manual was published. Please make sure to refer to the relevant product page on the Renesas website for the latest part numbers.

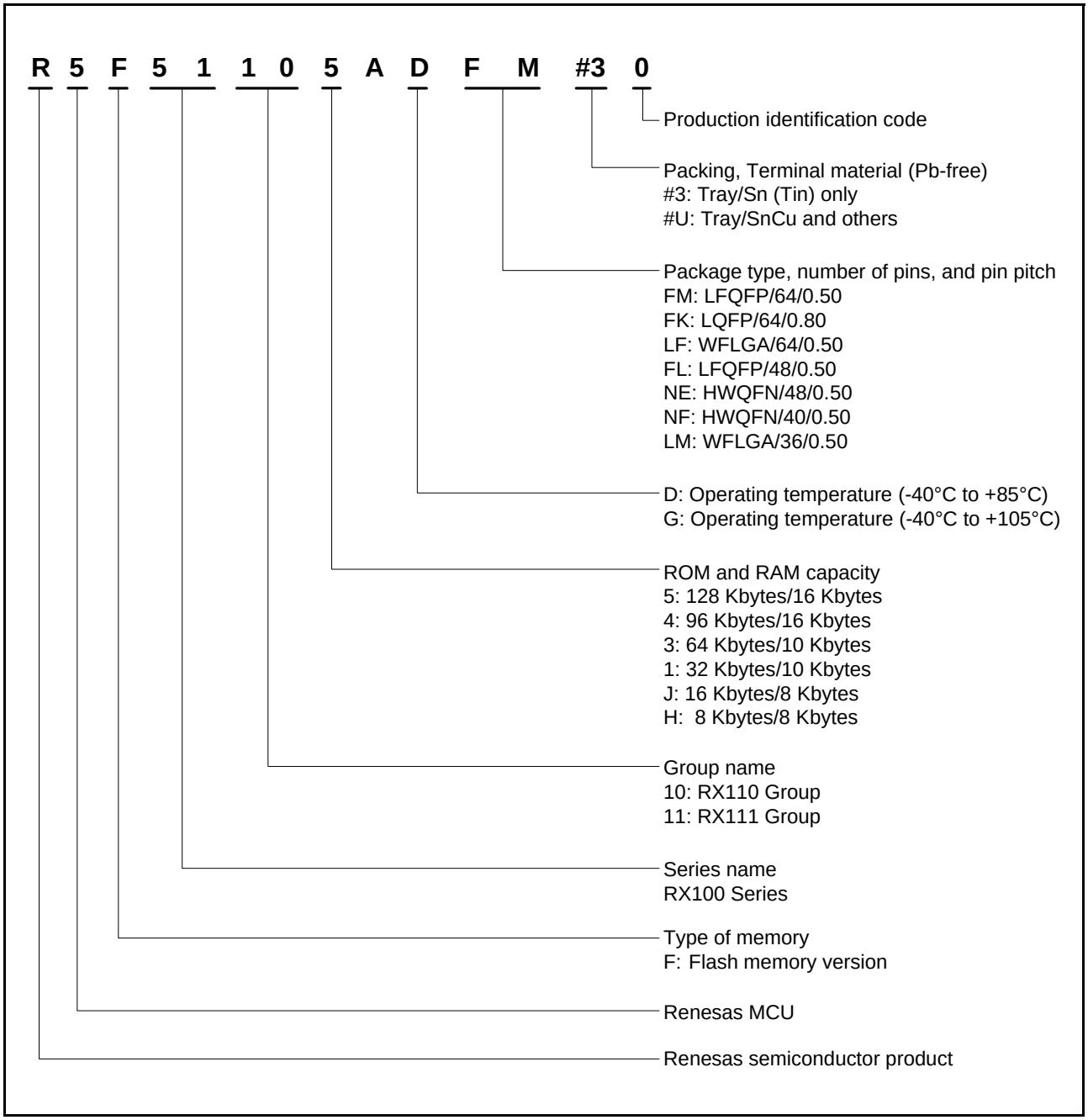
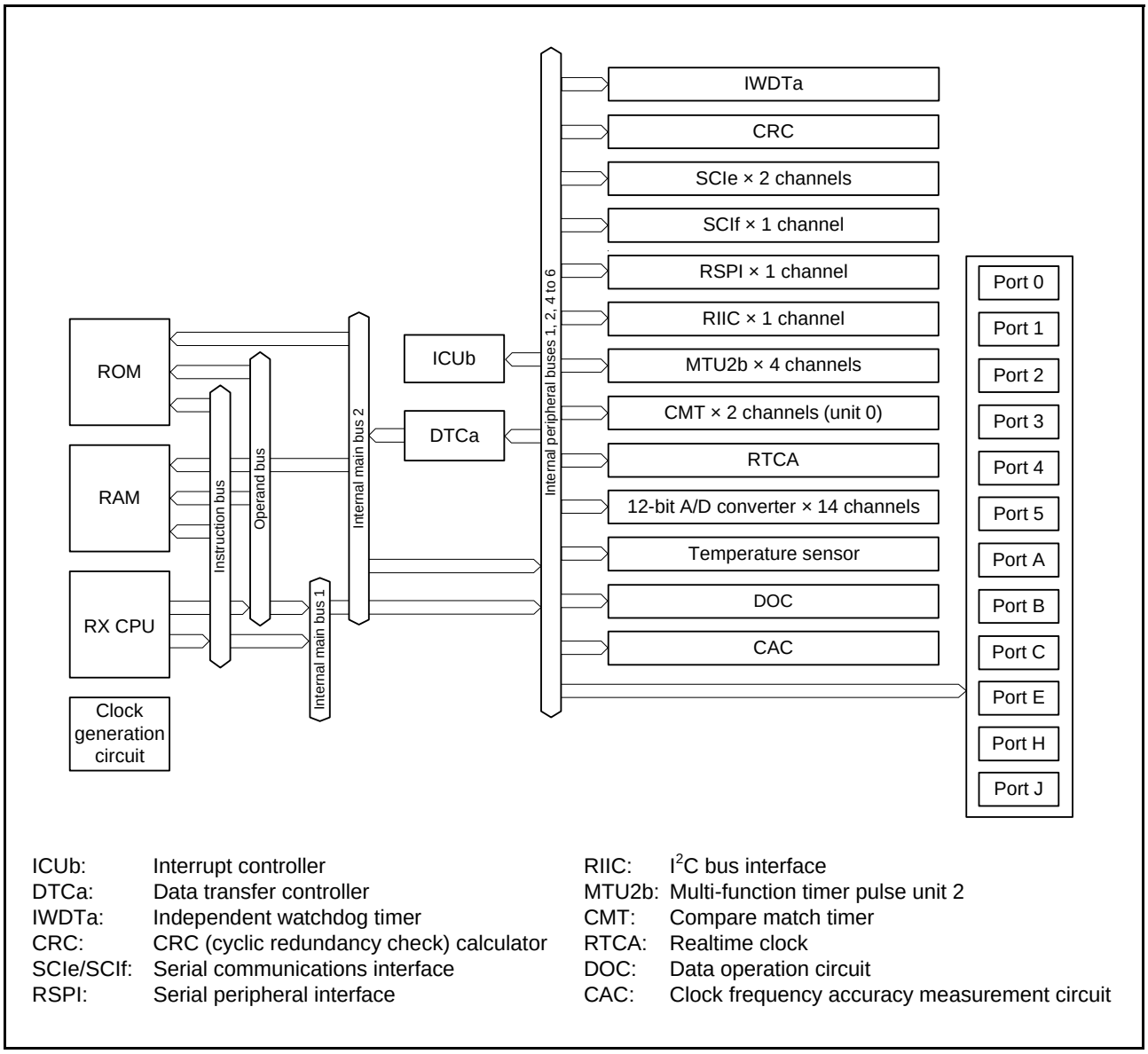


Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type

1.3 Block Diagram

Figure 1.2 shows a block diagram.



ICUb:	Interrupt controller	RIIC:	I^2C bus interface
DTCa:	Data transfer controller	MTU2b:	Multi-function timer pulse unit 2
IWDTa:	Independent watchdog timer	CMT:	Compare match timer
CRC:	CRC (cyclic redundancy check) calculator	RTCA:	Realtime clock
SCIe/SCIf:	Serial communications interface	DOC:	Data operation circuit
RSPI:	Serial peripheral interface	CAC:	Clock frequency accuracy measurement circuit

Figure 1.2 Block Diagram

1.4 Pin Functions

Table 1.4 lists the pin functions.

Table 1.4 Pin Functions (1/3)

Classifications	Pin Name	I/O	Description
Power supply	VCC	Input	Power supply pin. Connect it to the system power supply.
	VCL	—	Connect this pin to the VSS pin via the 4.7 µF smoothing capacitor used to stabilize the internal power supply. Place the capacitor close to the pin.
	VSS	Input	Ground pin. Connect it to the system power supply (0 V).
Analog power supply	AVCC0	Input	Analog voltage supply pin for the 12-bit A/D converter. Connect this pin to VCC when not using the 12-bit A/D converter.
	AVSS0	Input	Analog ground pin for the 12-bit A/D converter. Connect this pin to VSS when not using the 12-bit A/D converter.
	VREFH0	Input	Analog reference voltage supply pin for the 12-bit A/D converter. Connect this pin to VCC when not using the 12-bit A/D converter.
	VREFL0	Input	Analog reference ground pin for the 12-bit A/D converter. Connect this pin to VSS when not using the 12-bit A/D converter.
Clock	XTAL	Output/ Input *1	Pins for connecting a crystal resonator. An external clock can be input through the XTAL pin.
	EXTAL	Input	
	XCIN	Input	Input/output pins for the sub-clock oscillator. Connect a crystal resonator between XCIN and XCOUT.
	XCOUT	Output	
	CLKOUT	Output	Clock output pin.
Operating mode control	MD	Input	Pin for setting the operating mode. The signal levels on this pin must not be changed during operation.
System control	RES#	Input	Reset pin. This LSI enters the reset state when this signal goes low.
CAC	CACREF	Input	Input pin for the clock frequency accuracy measurement circuit.
On-chip emulator	FINED	I/O	FINE interface pin.
LVD	CMPA2	Input	Detection target voltage pin for voltage detection 2.
Interrupts	NMI	Input	Non-maskable interrupt request pin.
	IRQ0 to IRQ7	Input	Interrupt request pins.
Multi-function timer pulse unit 2	MTIOC0A, MTIOC0B MTIOC0C, MTIOC0D	I/O	The TGRA0 to TGRD0 input capture input/output compare output/PWM output pins.
	MTIOC1A, MTIOC1B	I/O	The TGRA1 and TGRB1 input capture input/output compare output/PWM output pins.
	MTIOC2A, MTIOC2B	I/O	The TGRA2 and TGRB2 input capture input/output compare output/PWM output pins.
	MTIC5U, MTIC5V, MTIC5W	Input	The TGRU5, TGRV5, and TGRW5 input capture input/external pulse input pins.
	MTCLKA, MTCLKB, MTCLKC, MTCLKD	Input	Input pins for the external clock.
Realtime clock	RTCOUT	Output	Output pin for the 1-Hz/64-Hz clock.
Serial communications interface (SCIe)	• Asynchronous mode/clock synchronous mode		
	SCK1, SCK5	I/O	Input/output pins for the clock.
	RXD1, RXD5	Input	Input pins for receiving data.
	TXD1, TXD5	Output	Output pins for transmitting data.
	CTS1#, CTS5#	Input	Input pins for controlling the start of transmission and reception.
	RTS1#, RTS5#	Output	Output pins for controlling the start of transmission and reception.

Table 1.4 Pin Functions (2/3)

Classifications	Pin Name	I/O	Description
Serial communications interface (SCIe)	• Simple I2C mode		
	SSCL1, SSCL5	I/O	Input/output pins for the I2C clock.
	SSDA1, SSDA5	I/O	Input/output pins for the I2C data.
	• Simple SPI mode		
	SCK1, SCK5	I/O	Input/output pins for the clock.
	SMISO1, SMISO5	I/O	Input/output pins for slave transmit data.
	SMOSI1, SMOSI5	I/O	Input/output pins for master transmit data.
	SS1#, SS5#	Input	Chip-select input pins.
Serial communications interface (SCIf)	• Asynchronous mode/clock synchronous mode		
	SCK12	I/O	Input/output pin for the clock.
	RXD12	Input	Input pin for receiving data.
	TXD12	Output	Output pin for transmitting data.
	CTS12#	Input	Input pin for controlling the start of transmission and reception.
	RTS12#	Output	Output pin for controlling the start of transmission and reception.
	• Simple I2C mode		
	SSCL12	I/O	Input/output pin for the I2C clock.
	SSDA12	I/O	Input/output pin for the I2C data.
	• Simple SPI mode		
	SCK12	I/O	Input/output pin for the clock.
	SMISO12	I/O	Input/output pin for slave transmit data.
	SMOSI12	I/O	Input/output pin for master transmit data.
	SS12#	Input	Chip-select input pin.
	• Extended serial mode		
	RXDX12	Input	Input pin for data reception by SCIf.
	TXDX12	Output	Output pin for data transmission by SCIf.
	SIOX12	I/O	Input/output pin for data reception or transmission by SCIf.
I2C bus interface	SCL0	I/O	Input/output pin for I2C bus interface clocks. Bus can be directly driven by the N-channel open drain output.
	SDA0	I/O	Input/output pin for I2C bus interface data. Bus can be directly driven by the N-channel open drain output.
Serial peripheral interface	RSPCKA	I/O	Input/output pin for the RSPI clock.
	MOSIA	I/O	Input/output pin for transmitting data from the RSPI master.
	MISOA	I/O	Input/output pin for transmitting data from the RSPI slave.
	SSLA0	I/O	Input/output pin to select the slave for the RSPI.
	SSLA1 to SSLA3	Output	Output pins to select the slave for the RSPI.
12-bit A/D converter	AN000 to AN004, AN006, AN008 to AN015	Input	Input pins for the analog signals to be processed by the A/D converter.
	ADTRG0#	Input	Input pin for the external trigger signals that start the A/D conversion.
I/O ports	P03, P05	I/O	2-bit input/output pins.
	P14 to P17	I/O	4-bit input/output pins.
	P26, P27	I/O	2-bit input/output pins.
	P30 to P32, P35	I/O	4-bit input/output pins (P35 input pin).
	P40 to P44, P46	I/O	6-bit input/output pins.
	P54, P55	I/O	2-bit input/output pins.
	PA0, PA1, PA3, PA4, PA6	I/O	5-bit input/output pins.
	PB0, PB1, PB3, PB5 to PB7	I/O	6-bit input/output pins.

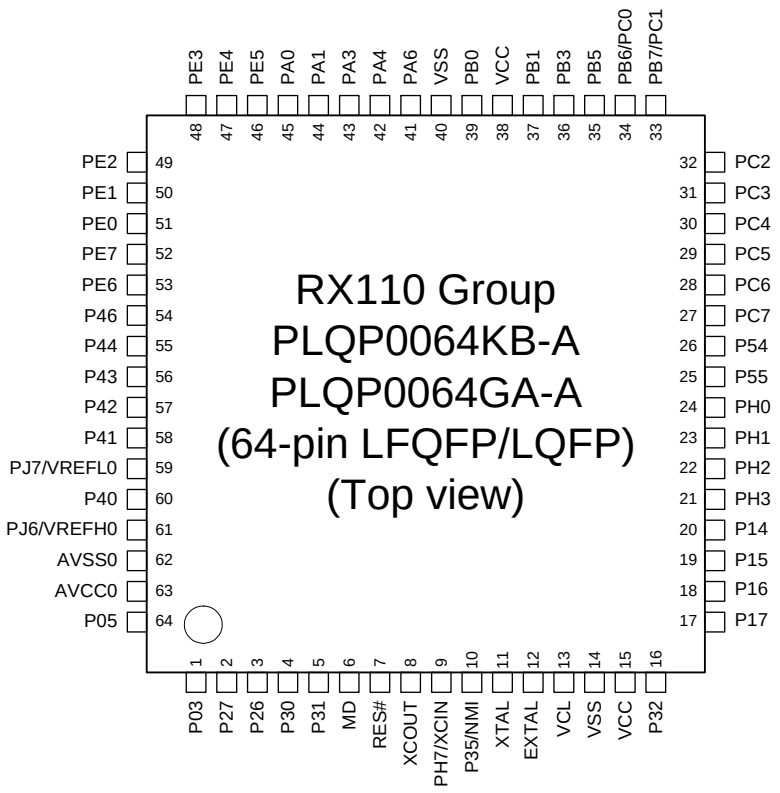
Table 1.4 Pin Functions (3/3)

Classifications	Pin Name	I/O	Description
I/O ports	PC0 to PC7	I/O	8-bit input/output pins.
	PE0 to PE7	I/O	8-bit input/output pins.
	PH0 to PH3	I/O	4-bit input/output pins.
	PH7	Input	1-bit input pin.
	PJ6, PJ7	I/O	2-bit input/output pins.

Note 1. For external clock input.

1.5 Pin Assignments

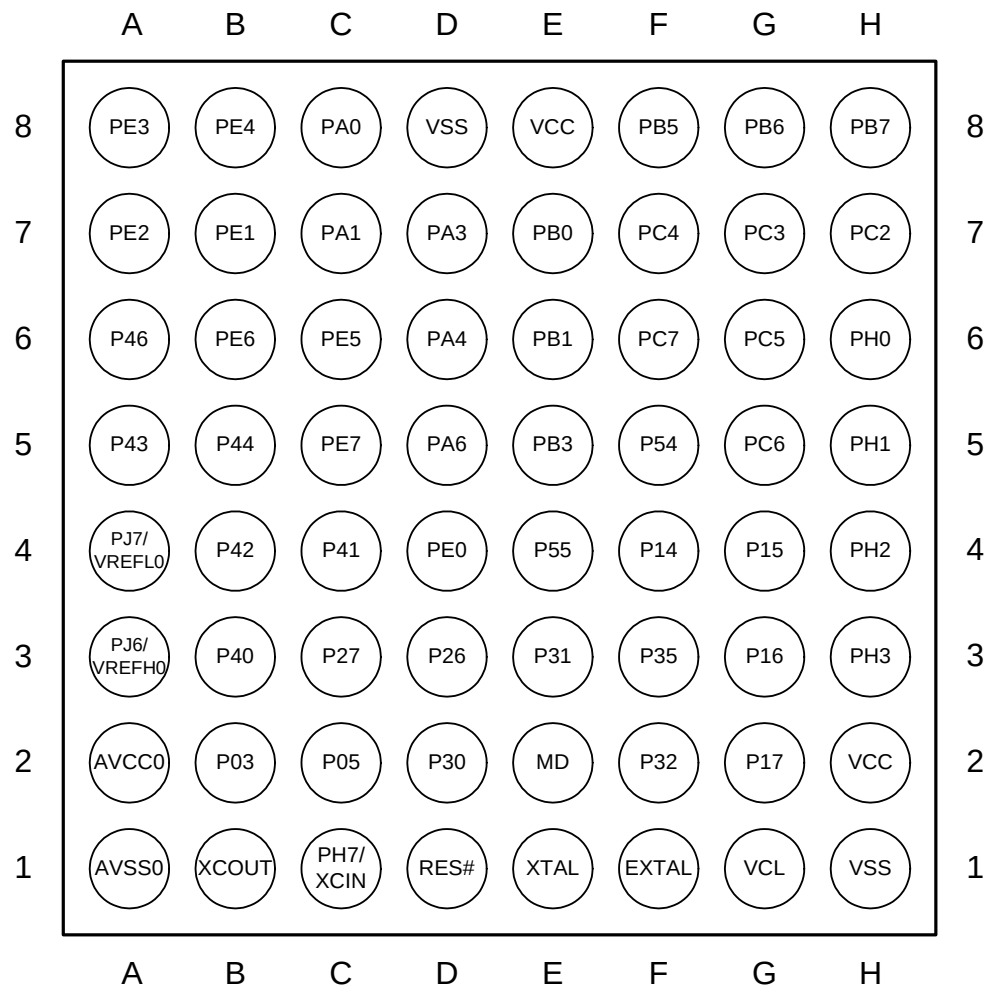
Figure 1.3 to Figure 1.7 show the pin assignments. Table 1.5 to Table 1.9 show the lists of pins and pin functions.



Note: This figure indicates the power supply pins and I/O ports.
For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin LFQFP/LQFP)”.

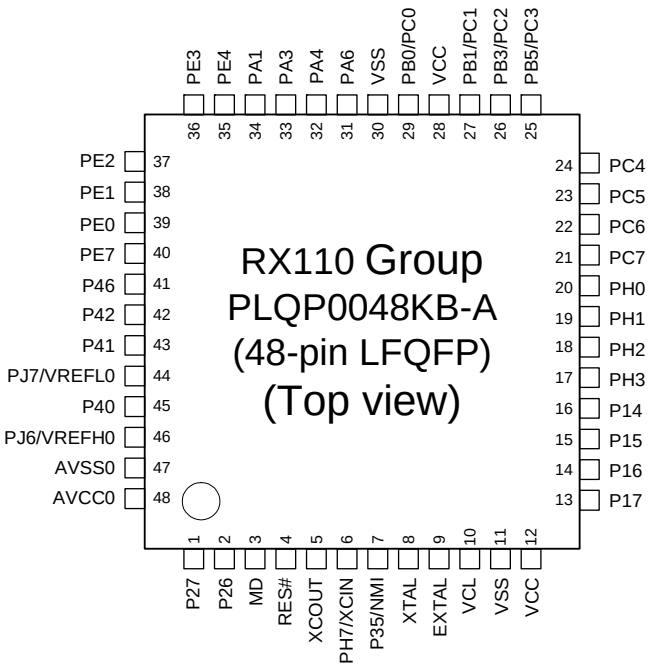
Figure 1.3 Pin Assignments of the 64-Pin LFQFP/LQFP

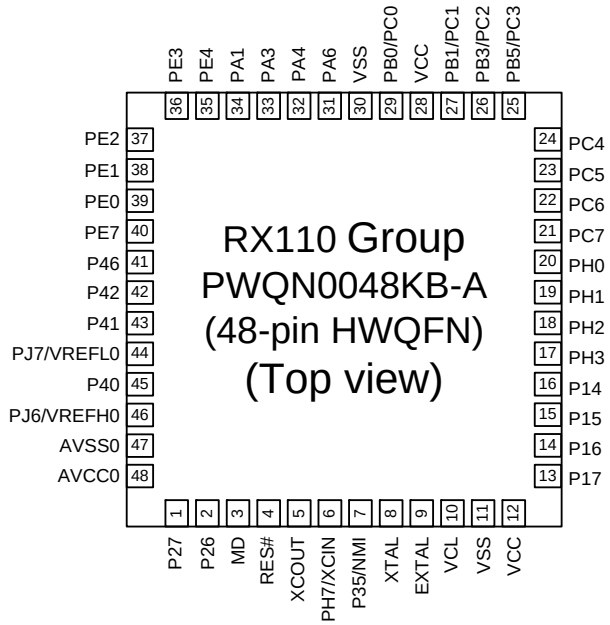
RX110 Group
PWLG0064KA-A
(64-pin WFLGA)
(Upper perspective view)



Note: This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin WFLGA)”.
Note: For the position of A1 pin in the package, see “Package Dimensions”.

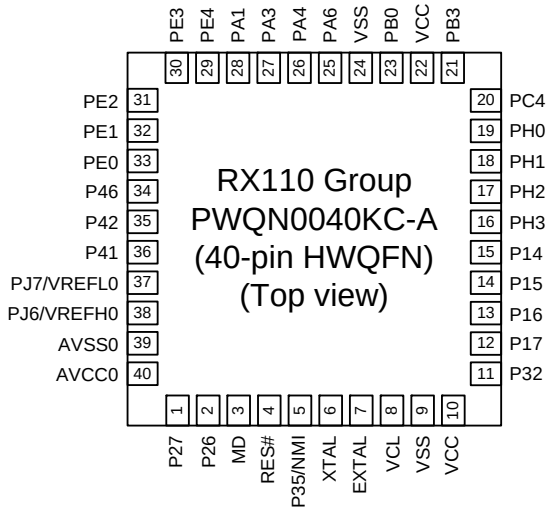
Figure 1.4 Pin Assignments of the 64-Pin WFLGA





Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (48-Pin LFQFP/HWQFN)”.
Note: It is recommended that the exposed die pad of HWQFN should be connected to VSS.

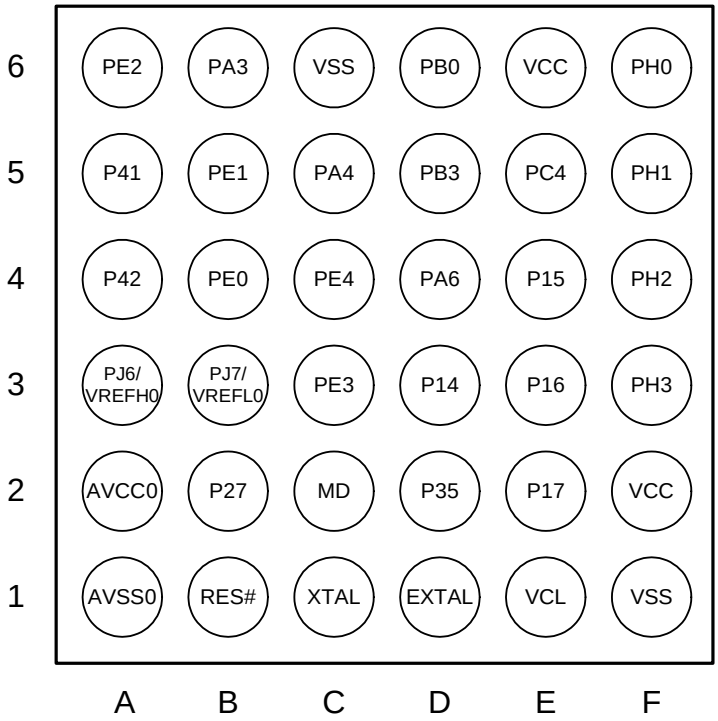
Figure 1.5 Pin Assignments of the 48-Pin LFQFP/HWQFN



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (40-Pin HWQFN)”.
Note: It is recommended that the exposed die pad of HWQFN should be connected to VSS.

Figure 1.6 Pin Assignments of the 40-Pin HWQFN

RX110 Group
PWLG0036KA-A
(36-pin WFLGA)
(Upper perspective view)



Note: This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (36-Pin WFLGA)”.
Note: For the position of A1 pin in the package, see “Package Dimensions”.

Figure 1.7 Pin Assignments of the 36-Pin WFLGA

Table 1.5 List of Pins and Pin Functions (64-Pin LFQFP/LQFP) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
1		P03			
2		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
3		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
4		P30		RXD1/SMISO1/SSCL1	IRQ0
5		P31		CTS1#/RTS1#/SS1#	IRQ1
6	MD				FINED
7	RES#				
8	XCOUT				
9	XCIN	PH7			
10		P35			NMI
11	XTAL				
12	EXTAL				
13	VCL				
14	VSS				
15	VCC				
16		P32	MTIOC0C/RTCOUT		IRQ2
17		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
18		P16	RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/SCL0	IRQ6/ADTRG0#
19		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
20		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12	IRQ4
21		PH3	MTIOC1A		
22		PH2			IRQ1
23		PH1			IRQ0
24		PH0	MTIOC1B		CACREF
25		P55			
26		P54			
27		PC7	MTCLKB	TXD1/SMOSI1/SSDA1/MISOA	CACREF
28		PC6	MTCLKA	RXD1/SMISO1/SSCL1/MOSIA	
29		PC5	MTCLKD	SCK1/RSPCKA	
30		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
31		PC3		TXD5/SMOSI5/SSDA5	
32		PC2		RXD5/SMISO5/SSCL5/SSLA3	
33		PB7/PC1			
34		PB6/PC0			
35		PB5	MTIOC2A/MTIOC1B		
36		PB3	MTIOC0A		
37		PB1	MTIOC0C		IRQ4
38	VCC				
39		PB0	MTIC5W/MTIOC0C/ RTCOUT	SCL0/RSPCKA	IRQ2/ADTRG0#
40	VSS				
41		PA6	MTIC5V/MTCLKB/MTIOC2A	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
42		PA4	MTIC5U/MTCLKA/MTIOC2B	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
43		PA3	MTIOC0D/MTCLKD/ MTIOC1B	RXD5/SMISO5/SSCL5/MISOA	IRQ6
44		PA1	MTIOC0B/MTCLKC/ RTCOUT	SCK5/SSLA2	

Table 1.5 List of Pins and Pin Functions (64-Pin LFQFP/LQFP) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
45		PA0		SSLA1	CACREF
46		PE5	MTIOC2B		IRQ5/AN013
47		PE4	MTIOC1A	MOSIA	IRQ4/AN012
48		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
49		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
50		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
51		PE0	MTIOC2A	SCK12	IRQ0/AN008
52		PE7			IRQ7/AN015
53		PE6			IRQ6/AN014
54		P46*1			AN006
55		P44*1			AN004
56		P43*1			AN003
57		P42*1			AN002
58		P41*1			AN001
59	VREFL0	PJ7*1			
60		P40*1			AN000
61	VREFH0	PJ6*1			
62	AVSS0				
63	AVCC0				
64		P05			

Note 1. The power source of the I/O buffer for these pins is AVCC0.

Table 1.6 List of Pins and Pin Functions (64-Pin WFLGA) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
A1	AVSS0				
A2	AVCC0				
A3	VREFH0	PJ6*1			
A4	VREFL0	PJ7*1			
A5		P43*1			AN003
A6		P46*1			AN006
A7		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
A8		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
B1	XCOUT				
B2		P03			
B3		P40*1			AN000
B4		P42*1			AN002
B5		P44*1			AN004
B6		PE6			IRQ6/AN014
B7		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
B8		PE4	MTIOC1A	MOSIA	IRQ4/AN012
C1	XCIN	PH7			
C2		P05			
C3		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
C4		P41*1			AN001
C5		PE7			IRQ7/AN015
C6		PE5	MTIOC2B		IRQ5/AN013
C7		PA1	MTIOC0B/MTCLKC/ RTCOUT	SCK5/SSLA2	
C8		PA0		SSLA1	CACREF
D1	RES#				
D2		P30		RXD1/SMISO1/SSCL1	IRQ0
D3		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
D4		PE0	MTIOC2A	SCK12	IRQ0/AN008
D5		PA6	MTIC5V/MTIOC2A/MTCLKB	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
D6		PA4	MTIC5U/MTIOC2B/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
D7		PA3	MTIOC0D/MTCLKD/ MTIOC1B	RXD5/SMISO5/SSCL5/MISOA	IRQ6
D8	VSS				
E1	XTAL				
E2	MD				FINED
E3		P31		CTS1#/RTS1#/SS1#	IRQ1
E4		P55			
E5		PB3	MTIOC0A		
E6		PB1	MTIOC0C		IRQ4
E7		PB0	MTIC5W/MTIOC0C/ RTCOUT	SCL0/RSPCKA	IRQ2/ADTRG0#
E8	VCC				
F1	EXTAL				
F2		P32	MTIOC0C/RTCOUT		IRQ2
F3		P35			NMI
F4		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12/ SSLA0	IRQ4

Table 1.6 List of Pins and Pin Functions (64-Pin WFLGA) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
F5		P54			
F6		PC7	MTCLKB	TXD1/SMOSI1/SSDA1/MISOA	CACREF
F7		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
F8		PB5	MTIOC1B/MTIOC2A		
G1	VCL				
G2		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
G3		P16	RTCOUT	TXD1/SMOSI1/SSDA1/SCL0/MOSIA	IRQ6/ADTRG0#
G4		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
G5		PC6	MTCLKA	RXD1/SMISO1/SSCL1/MOSIA	
G6		PC5	MTCLKD	SCK1/RSPCKA	
G7		PC3		TXD5/SMOSI5/SSDA5	
G8		PB6/PC0			
H1	VSS				
H2	VCC				
H3		PH3	MTIOC1A		
H4		PH2			IRQ1
H5		PH1			IRQ0
H6		PH0	MTIOC1B		CACREF
H7		PC2		RXD5/SMISO5/SSCL5/SSLA3	
H8		PB7/PC1			

Note 1. The power source of the I/O buffer for these pins is AVCC0.

Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
1		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
2		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
3	MD				FINED
4	RES#				
5	XCOUT				
6	XCIN	PH7			
7		P35			NMI
8	XTAL				
9	EXTAL				
10	VCL				
11	VSS				
12	VCC				
13		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
14		P16	RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/SCL0	IRQ6/ADTRG0#
15		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
16		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12	IRQ4
17		PH3	MTIOC1A		
18		PH2			IRQ1
19		PH1			IRQ0
20		PH0	MTIOC1B		CACREF
21		PC7	MTCLKB	TXD1/SMOSI1/SSDA1/MISOA	CACREF
22		PC6	MTCLKA	RXD1/SMISO1/SSCL1/MOSIA	
23		PC5	MTCLKD	SCK1/RSPCKA	
24		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
25		PB5/PC3	MTIOC2A/MTIOC1B		
26		PB3/PC2	MTIOC0A		
27		PB1/PC1	MTIOC0C		IRQ4
28	VCC				
29		PB0/PC0	MTIC5W/MTIOC0C/ RTCOUT	SCL0/RSPCKA	IRQ2/ADTRG0#
30	VSS				
31		PA6	MTIC5V/MTCLKB/MTIOC2A	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
32		PA4	MTIC5U/MTCLKA/MTIOC2B	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
33		PA3	MTIOC0D/MTCLKD/ MTIOC1B	RXD5/SMISO5/SSCL5/MISOA	IRQ6
34		PA1	MTIOC0B/MTCLKC/ RTCOUT	SCK5/SSLA2	
35		PE4	MTIOC1A	MOSIA	IRQ4/AN012
36		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
37		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
38		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
39		PE0	MTIOC2A	SCK12	IRQ0/AN008
40		PE7			IRQ7/AN015
41		P46*1			AN006
42		P42*1			AN002
43		P41*1			AN001
44	VREFL0	PJ7*1			

Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
45		P40*1			AN000
46	VREFH0	PJ6*1			
47	AVSS0				
48	AVCC0				

Note 1. The power source of the I/O buffer for these pins is AVCC0.

Table 1.8 List of Pins and Pin Functions (40-Pin HWQFN)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
1		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
2		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
3	MD				FINED
4	RES#				
5		P35			NMI
6	XTAL				
7	EXTAL				
8	VCL				
9	VSS				
10	VCC				
11		P32	MTIOC0C		IRQ2
12		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
13		P16		TXD1/SMOSI1/SSDA1/SCL0/MOSIA	IRQ6/ADTRG0#
14		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
15		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12	IRQ4
16		PH3	MTIOC1A		
17		PH2			IRQ1
18		PH1			IRQ0
19		PH0	MTIOC1B		CACREF
20		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
21		PB3	MTIOC0A		
22	VCC				
23		PB0	MTIOC0C/MTIC5W	SCL0/RSPCKA	IRQ2/ADTRG0#
24	VSS				
25		PA6	MTIOC2A/MTIC5V/MTCLKB	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
26		PA4	MTIOC2B/MTIC5U/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
27		PA3	MTIOC0D/MTIOC1B/ MTCLKD	RXD5/SMISO5/SSCL5/MISOA	IRQ6
28		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	
29		PE4	MTIOC1A	MOSIA	IRQ4/AN012
30		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
31		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
32		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
33		PE0	MTIOC2A	SCK12	IRQ0/AN008
34		P46*1			AN006
35		P42*1			AN002
36		P41*1			AN001
37	VREFL0	PJ7*1			
38	VREFH0	PJ6*1			
39	AVSS0				
40	AVCC0				

Note 1. The power source of the I/O buffer for these pins is AVCC0.

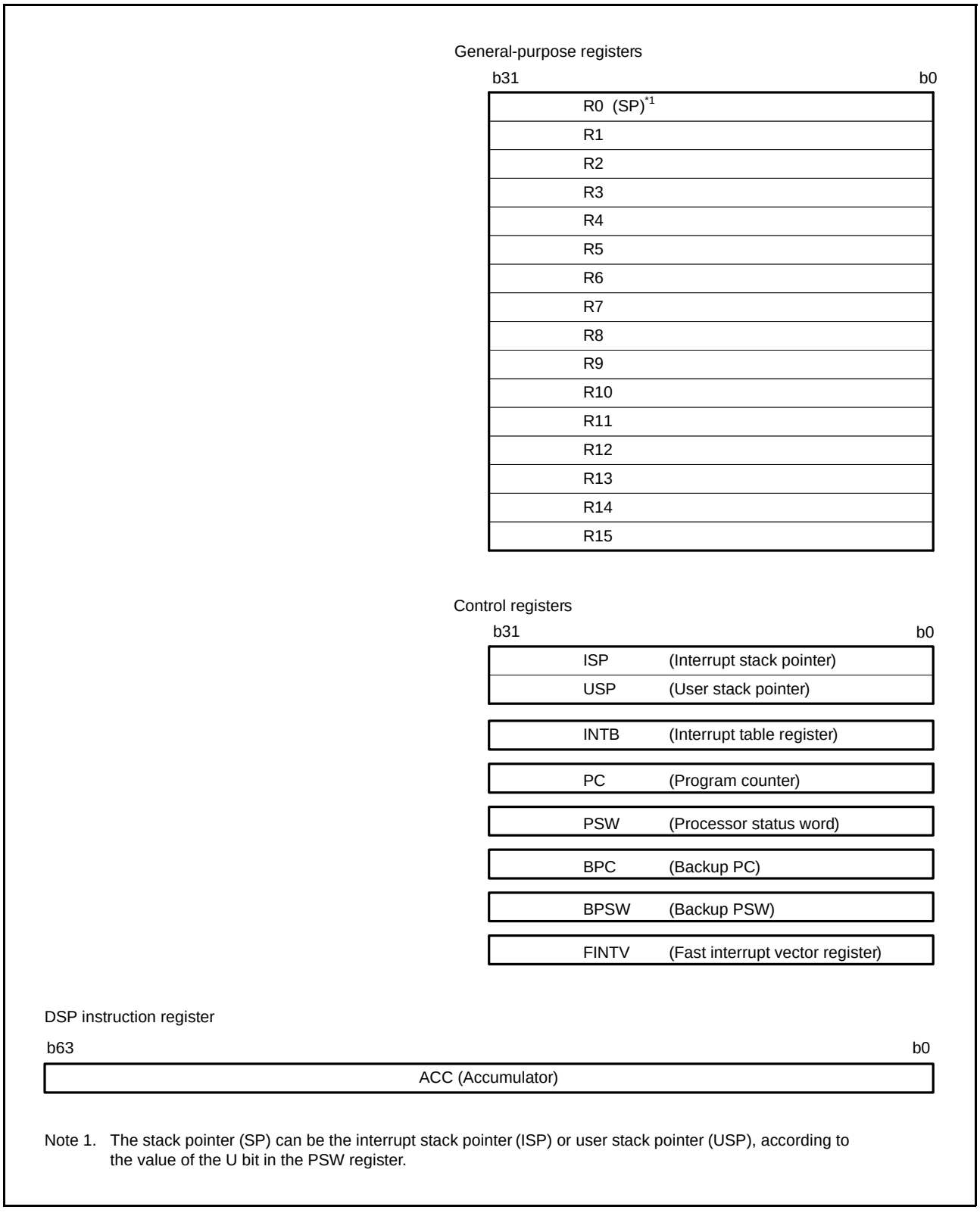
Table 1.9 List of Pins and Pin Functions (36-Pin WFLGA)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
A1	AVSS0				
A2	AVCC0				
A3	VREFH0	PJ6*1			
A4		P42*1			AN002
A5		P41*1			AN001
A6		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
B1	RES#				
B2		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
B3	VREFL0	PJ7*1			
B4		PE0	MTIOC2A	SCK12	IRQ0/AN008
B5		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
B6		PA3	MTIOC0D/MTCLKD/ MTIOC1B	RXD5/SMISO5/SSCL5/MISOA	IRQ6
C1	XTAL				
C2	MD				FINED
C3		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
C4		PE4	MTIOC1A	MOSIA	IRQ4/AN012
C5		PA4	MTIOC2B/MTIC5U/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
C6	VSS				
D1	EXTAL				
D2		P35			NMI
D3		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12	IRQ4
D4		PA6	MTIC5V/MTCLKB/MTIOC2A	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
D5		PB3	MTIOC0A		
D6		PB0	MTIOC0C/MTIC5W	SCL0/RSPCKA	IRQ2/ADTRG0#
E1	VCL				
E2		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
E3		P16		TXD1/SMOSI1/SSDA1/SCL0/MOSIA	IRQ6/ADTRG0#
E4		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
E5		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
E6	VCC				
F1	VSS				
F2	VCC				
F3		PH3	MTIOC1A		
F4		PH2			IRQ1
F5		PH1			IRQ0
F6		PH0	MTIOC1B		CACREF

Note 1. The power source of the I/O buffer for these pins is AVCC0.

2. CPU

Figure 2.1 shows the register set of the CPU.



Note 1. The stack pointer (SP) can be the interrupt stack pointer (ISP) or user stack pointer (USP), according to the value of the U bit in the PSW register.

Figure 2.1 Register Set of the CPU

2.1 General-Purpose Registers (R0 to R15)

This CPU has 16 general-purpose registers (R0 to R15). R0 to R15 can be used as data registers or address registers. R0, a general-purpose register, also functions as the stack pointer (SP). The stack pointer is switched to operate as the interrupt stack pointer (ISP) or user stack pointer (USP) by the value of the stack pointer select bit (U) in the processor status word (PSW).

2.2 Control Registers

(1) Interrupt Stack Pointer (ISP)/User Stack Pointer (USP)

The stack pointer (SP) can be either of two types, the interrupt stack pointer (ISP) or the user stack pointer (USP). Whether the stack pointer operates as the ISP or USP depends on the value of the stack pointer select bit (U) in the processor status word (PSW).
Set the ISP or USP to a multiple of 4, as this reduces the numbers of cycles required to execute interrupt sequences and instructions entailing stack manipulation.

(2) Interrupt Table Register (INTB)

The interrupt table register (INTB) specifies the address where the relocatable vector table starts.

(3) Program Counter (PC)

The program counter (PC) indicates the address of the instruction being executed.

(4) Processor Status Word (PSW)

The processor status word (PSW) indicates the results of instruction execution or the state of the CPU.

(5) Backup PC (BPC)

The backup PC (BPC) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the program counter (PC) are saved in the BPC register.

(6) Backup PSW (BPSW)

The backup PSW (BPSW) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the processor status word (PSW) are saved in the BPSW. The allocation of bits in the BPSW corresponds to that in the PSW.

(7) Fast Interrupt Vector Register (FINTV)

The fast interrupt vector register (FINTV) is provided to speed up response to interrupts.
The FINTV register specifies a branch destination address when a fast interrupt has been generated.

2.3 Register Associated with DSP Instructions

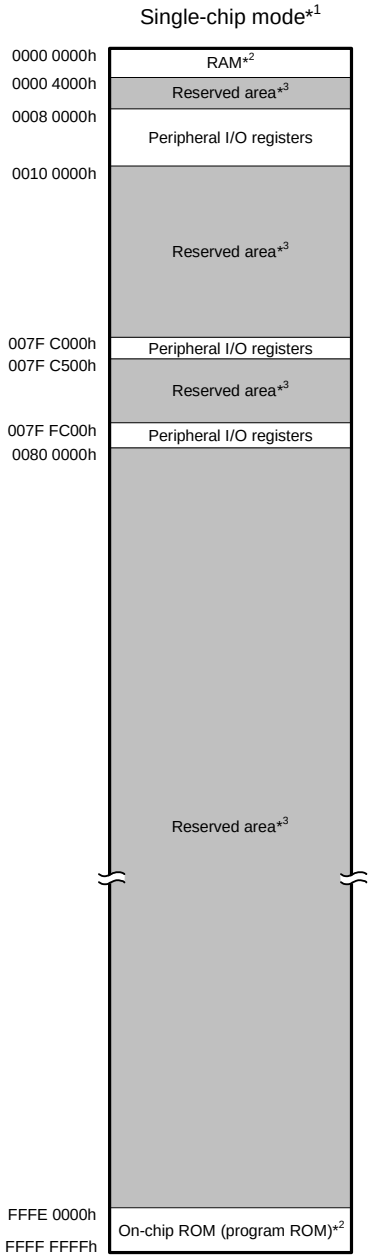
(1) Accumulator (ACC)

The accumulator (ACC) is a 64-bit register used for DSP instructions. The accumulator is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, MUL, and RMPA, in which case the prior value in the accumulator is modified by execution of the instruction.
Use the MVTACHI and MVTACLO instructions for writing to the accumulator. The MVTACHI and MVTACLO instructions write data to the higher-order 32 bits (bits 63 to 32) and the lower-order 32 bits (bits 31 to 0), respectively.
Use the MVFACHI and MVFACMI instructions for reading data from the accumulator. The MVFACHI and MVFACMI instructions read data from the higher-order 32 bits (bits 63 to 32) and the middle 32 bits (bits 47 to 16), respectively.

3. Address Space

3.1 Address Space

This MCU has a 4-Gbyte address space, consisting of the range of addresses from 0000 0000h to FFFF FFFFh. That is, linear access to an address space of up to 4 Gbytes is possible, and this contains program area.
Figure 3.1 shows the memory map.



Note 1. The address space in boot mode is the same as the address space in single-chip mode.
Note 2. The capacity of ROM/RAM differs depending on the products.

ROM (bytes)		RAM (bytes)	
Capacity	**Address**	**Capacity**	**Address**
128 K	FFFE 0000h to FFFF FFFFh	16 K	0000 0000h to 0000 3FFFh
96 K	FFFE 8000h to FFFF FFFFh		
64 K	FFFF 0000h to FFFF FFFFh	10 K	0000 0000h to 0000 27FFh
32 K	FFFF 8000h to FFFF FFFFh		
16 K	FFFF C000h to FFFF FFFFh	8 K	0000 0000h to 0000 1FFFh
8 K	FFFF E000h to FFFF FFFFh		

Note:See Table 1.3, List of Products, for the product type name.

Note 3. Reserved areas should not be accessed.

Figure 3.1 Memory Map

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to I/O registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

While writing to an I/O register, the CPU starts executing subsequent instructions before the I/O register write access is completed. This may cause the subsequent instructions to be executed before the write value is reflected in the operation. The examples below show how subsequent instructions must be executed after a write access to an I/O register is completed.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) set to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

(a) Write to an I/O register.
(b) Read the value in the I/O register and write it to a general register.
(c) Execute the operation using the value read.
(d) Execute the subsequent instruction.

Example of instructions

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

- Longword-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.L  #SFR_DATA, [R1]
CMP    [R1].L, R1
;; Next process
```

When executing an instruction after writing to multiple registers, only read the last I/O register written to and execute the instruction using that value; it is not necessary to execute the instruction using the values written to all the registers.

(3) Number of cycles necessary for accessing I/O registers

See Table 4.1 for details on the number of clock cycles necessary for accessing I/O registers.
The number of access cycles to I/O registers is obtained by following equation.*1

Number of access cycles to I/O registers = Number of bus cycles for internal main bus 1 +
Number of divided clock synchronization cycles +
Number of bus cycles for internal peripheral buses 1, 2, and 4 to 6

The number of bus cycles of internal peripheral buses 1, 2, and 4 to 6 differs according to the register to be accessed. When peripheral functions connected to internal peripheral buses 2, and 4 to 6 or registers for the external bus control unit (except for bus error related registers) are accessed, the number of divided clock synchronization cycles is added. The number of divided clock synchronization cycles differs depending on the frequency ratio between ICLK and PCLK (or FCLK) or bus access timing.
In the peripheral function unit, when the frequency ratio of ICLK is equal to or greater than that of PCLK (or FCLK), the sum of the number of bus cycles for internal main bus 1 and the number of the divided clock synchronization cycles will be one cycle of PCLK (or FCLK) at a maximum. Therefore, one PCLK (or FCLK) has been added to the number of access cycles shown in Table 4.1.
When the frequency ratio of ICLK is lower than that of PCLK (or FCLK), the subsequent bus access is started from the ICLK cycle following the completion of the access to the peripheral functions. Therefore, the access cycles are described on an ICLK basis.

Note 1. This applies to the number of cycles when the access from the CPU does not conflict with the bus access from the different bus master (DTC).

(4) Notes on sleep mode and mode transitions

During sleep mode or mode transitions, do not write to the system control related registers (indicated by ‘SYSTEM’ in the Module Symbol column in Table 4.1, List of I/O Registers (Address Order)).

4.1 I/O Register Addresses (Address Order)

Table 4.1 List of I/O Registers (Address Order) (1/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 0000h	SYSTEM	Mode Monitor Register	MDMONR	16	16	3 ICLK
0008 0008h	SYSTEM	System Control Register 1	SYSCR1	16	16	3 ICLK
0008 000Ch	SYSTEM	Standby Control Register	SBYCR	16	16	3 ICLK
0008 0010h	SYSTEM	Module Stop Control Register A	MSTPCRA	32	32	3 ICLK
0008 0014h	SYSTEM	Module Stop Control Register B	MSTPCRB	32	32	3 ICLK
0008 0018h	SYSTEM	Module Stop Control Register C	MSTPCRC	32	32	3 ICLK
0008 0020h	SYSTEM	System Clock Control Register	SCKCR	32	32	3 ICLK
0008 0026h	SYSTEM	System Clock Control Register 3	SCKCR3	16	16	3 ICLK
0008 0032h	SYSTEM	Main Clock Oscillator Control Register	MOSCCR	8	8	3 ICLK
0008 0033h	SYSTEM	Sub-Clock Oscillator Control Register	SOSCCR	8	8	3 ICLK
0008 0034h	SYSTEM	Low-Speed On-Chip Oscillator Control Register	LOCOCR	8	8	3 ICLK
0008 0035h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Control Register	ILOCOCR	8	8	3 ICLK
0008 0036h	SYSTEM	High-Speed On-Chip Oscillator Control Register	HOCOCR	8	8	3 ICLK
0008 003Ch	SYSTEM	Oscillation Stabilization Flag Register	OSCOVFSR	8	8	3 ICLK
0008 003Eh	SYSTEM	CLKOUT Output Control Register	CKOCR	16	16	3 ICLK
0008 0040h	SYSTEM	Oscillation Stop Detection Control Register	OSTDCR	8	8	3 ICLK
0008 0041h	SYSTEM	Oscillation Stop Detection Status Register	OSTDSR	8	8	3 ICLK
0008 00A0h	SYSTEM	Operating Power Control Register	OPCCR	8	8	3 ICLK
0008 00A1h	SYSTEM	Sleep Mode Return Clock Source Switching Register	RSTCKCR	8	8	3 ICLK
0008 00A2h	SYSTEM	Main Clock Oscillator Wait Control Register	MOSCWTCR	8	8	3 ICLK
0008 00A5h	SYSTEM	High-Speed On-Chip Oscillator Wait Control Register	HOCOWTCR	8	8	3 ICLK
0008 00AAh	SYSTEM	Sub Operating Power Control Register	SOPCCR	8	8	3 ICLK
0008 00C0h	SYSTEM	Reset Status Register 2	RSTSR2	8	8	3 ICLK
0008 00C2h	SYSTEM	Software Reset Register	SWRR	16	16	3 ICLK
0008 00E0h	SYSTEM	Voltage Monitoring 1 Circuit Control Register 1	LVD1CR1	8	8	3 ICLK
0008 00E1h	SYSTEM	Voltage Monitoring 1 Circuit Status Register	LVD1SR	8	8	3 ICLK
0008 00E2h	SYSTEM	Voltage Monitoring 2 Circuit Control Register 1	LVD2CR1	8	8	3 ICLK
0008 00E3h	SYSTEM	Voltage Monitoring 2 Circuit Status Register	LVD2SR	8	8	3 ICLK
0008 03FEh	SYSTEM	Protect Register	PRCR	16	16	3 ICLK
0008 1300h	BSC	Bus Error Status Clear Register	BERCLR	8	8	2 ICLK
0008 1304h	BSC	Bus Error Monitoring Enable Register	BEREN	8	8	2 ICLK
0008 1308h	BSC	Bus Error Status Register 1	BERSR1	8	8	2 ICLK
0008 130Ah	BSC	Bus Error Status Register 2	BERSR2	16	16	2 ICLK
0008 1310h	BSC	Bus Priority Control Register	BUSPRI	16	16	2 ICLK
0008 2400h	DTC	DTC Control Register	DTCCR	8	8	2 ICLK
0008 2404h	DTC	DTC Vector Base Register	DTCVBR	32	32	2 ICLK
0008 2408h	DTC	DTC Address Mode Register	DTCADMOD	8	8	2 ICLK
0008 240Ch	DTC	DTC Module Start Register	DTCST	8	8	2 ICLK
0008 240Eh	DTC	DTC Status Register	DTCSTS	16	16	2 ICLK
0008 7010h	ICU	Interrupt Request Register 016	IR016	8	8	2 ICLK
0008 701Bh	ICU	Interrupt Request Register 027	IR027	8	8	2 ICLK
0008 701Ch	ICU	Interrupt Request Register 028	IR028	8	8	2 ICLK
0008 701Dh	ICU	Interrupt Request Register 029	IR029	8	8	2 ICLK
0008 7020h	ICU	Interrupt Request Register 032	IR032	8	8	2 ICLK
0008 7021h	ICU	Interrupt Request Register 033	IR033	8	8	2 ICLK
0008 7022h	ICU	Interrupt Request Register 034	IR034	8	8	2 ICLK
0008 7024h	ICU	Interrupt Request Register 036	IR036	8	8	2 ICLK
0008 7025h	ICU	Interrupt Request Register 037	IR037	8	8	2 ICLK
0008 7026h	ICU	Interrupt Request Register 038	IR038	8	8	2 ICLK
0008 702Ch	ICU	Interrupt Request Register 044	IR044	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (2/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 702Dh	ICU	Interrupt Request Register 045	IR045	8	8	2 ICLK
0008 702Eh	ICU	Interrupt Request Register 046	IR046	8	8	2 ICLK
0008 702Fh	ICU	Interrupt Request Register 047	IR047	8	8	2 ICLK
0008 7039h	ICU	Interrupt Request Register 057	IR057	8	8	2 ICLK
0008 703Fh	ICU	Interrupt Request Register 063	IR063	8	8	2 ICLK
0008 7040h	ICU	Interrupt Request Register 064	IR064	8	8	2 ICLK
0008 7041h	ICU	Interrupt Request Register 065	IR065	8	8	2 ICLK
0008 7042h	ICU	Interrupt Request Register 066	IR066	8	8	2 ICLK
0008 7043h	ICU	Interrupt Request Register 067	IR067	8	8	2 ICLK
0008 7044h	ICU	Interrupt Request Register 068	IR068	8	8	2 ICLK
0008 7045h	ICU	Interrupt Request Register 069	IR069	8	8	2 ICLK
0008 7046h	ICU	Interrupt Request Register 070	IR070	8	8	2 ICLK
0008 7047h	ICU	Interrupt Request Register 071	IR071	8	8	2 ICLK
0008 7058h	ICU	Interrupt Request Register 088	IR088	8	8	2 ICLK
0008 7059h	ICU	Interrupt Request Register 089	IR089	8	8	2 ICLK
0008 705Ah	ICU	Interrupt Request Register 090	IR090	8	8	2 ICLK
0008 705Ch	ICU	Interrupt Request Register 092	IR092	8	8	2 ICLK
0008 705Dh	ICU	Interrupt Request Register 093	IR093	8	8	2 ICLK
0008 7066h	ICU	Interrupt Request Register 102	IR102	8	8	2 ICLK
0008 7067h	ICU	Interrupt Request Register 103	IR103	8	8	2 ICLK
0008 706Ah	ICU	Interrupt Request Register 106	IR106	8	8	2 ICLK
0008 7072h	ICU	Interrupt Request Register 114	IR114	8	8	2 ICLK
0008 7073h	ICU	Interrupt Request Register 115	IR115	8	8	2 ICLK
0008 7074h	ICU	Interrupt Request Register 116	IR116	8	8	2 ICLK
0008 7075h	ICU	Interrupt Request Register 117	IR117	8	8	2 ICLK
0008 7076h	ICU	Interrupt Request Register 118	IR118	8	8	2 ICLK
0008 7077h	ICU	Interrupt Request Register 119	IR119	8	8	2 ICLK
0008 7078h	ICU	Interrupt Request Register 120	IR120	8	8	2 ICLK
0008 7079h	ICU	Interrupt Request Register 121	IR121	8	8	2 ICLK
0008 707Ah	ICU	Interrupt Request Register 122	IR122	8	8	2 ICLK
0008 707Bh	ICU	Interrupt Request Register 123	IR123	8	8	2 ICLK
0008 707Ch	ICU	Interrupt Request Register 124	IR124	8	8	2 ICLK
0008 707Dh	ICU	Interrupt Request Register 125	IR125	8	8	2 ICLK
0008 707Eh	ICU	Interrupt Request Register 126	IR126	8	8	2 ICLK
0008 707Fh	ICU	Interrupt Request Register 127	IR127	8	8	2 ICLK
0008 7080h	ICU	Interrupt Request Register 128	IR128	8	8	2 ICLK
0008 7081h	ICU	Interrupt Request Register 129	IR129	8	8	2 ICLK
0008 7082h	ICU	Interrupt Request Register 130	IR130	8	8	2 ICLK
0008 7083h	ICU	Interrupt Request Register 131	IR131	8	8	2 ICLK
0008 7084h	ICU	Interrupt Request Register 132	IR132	8	8	2 ICLK
0008 7085h	ICU	Interrupt Request Register 133	IR133	8	8	2 ICLK
0008 7086h	ICU	Interrupt Request Register 134	IR134	8	8	2 ICLK
0008 7087h	ICU	Interrupt Request Register 135	IR135	8	8	2 ICLK
0008 7088h	ICU	Interrupt Request Register 136	IR136	8	8	2 ICLK
0008 7089h	ICU	Interrupt Request Register 137	IR137	8	8	2 ICLK
0008 708Ah	ICU	Interrupt Request Register 138	IR138	8	8	2 ICLK
0008 708Bh	ICU	Interrupt Request Register 139	IR139	8	8	2 ICLK
0008 708Ch	ICU	Interrupt Request Register 140	IR140	8	8	2 ICLK
0008 708Dh	ICU	Interrupt Request Register 141	IR141	8	8	2 ICLK
0008 70AAh	ICU	Interrupt Request Register 170	IR170	8	8	2 ICLK
0008 70ABh	ICU	Interrupt Request Register 171	IR171	8	8	2 ICLK
0008 70DAh	ICU	Interrupt Request Register 218	IR218	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (3/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 70DBh	ICU	Interrupt Request Register 219	IR219	8	8	2 ICLK
0008 70DCh	ICU	Interrupt Request Register 220	IR220	8	8	2 ICLK
0008 70DDh	ICU	Interrupt Request Register 221	IR221	8	8	2 ICLK
0008 70DEh	ICU	Interrupt Request Register 222	IR222	8	8	2 ICLK
0008 70DFh	ICU	Interrupt Request Register 223	IR223	8	8	2 ICLK
0008 70E0h	ICU	Interrupt Request Register 224	IR224	8	8	2 ICLK
0008 70E1h	ICU	Interrupt Request Register 225	IR225	8	8	2 ICLK
0008 70EEh	ICU	Interrupt Request Register 238	IR238	8	8	2 ICLK
0008 70EFh	ICU	Interrupt Request Register 239	IR239	8	8	2 ICLK
0008 70F0h	ICU	Interrupt Request Register 240	IR240	8	8	2 ICLK
0008 70F1h	ICU	Interrupt Request Register 241	IR241	8	8	2 ICLK
0008 70F2h	ICU	Interrupt Request Register 242	IR242	8	8	2 ICLK
0008 70F3h	ICU	Interrupt Request Register 243	IR243	8	8	2 ICLK
0008 70F4h	ICU	Interrupt Request Register 244	IR244	8	8	2 ICLK
0008 70F5h	ICU	Interrupt Request Register 245	IR245	8	8	2 ICLK
0008 70F6h	ICU	Interrupt Request Register 246	IR246	8	8	2 ICLK
0008 70F7h	ICU	Interrupt Request Register 247	IR247	8	8	2 ICLK
0008 70F8h	ICU	Interrupt Request Register 248	IR248	8	8	2 ICLK
0008 70F9h	ICU	Interrupt Request Register 249	IR249	8	8	2 ICLK
0008 711Bh	ICU	DTC Activation Enable Register 027	DTCER027	8	8	2 ICLK
0008 711Ch	ICU	DTC Activation Enable Register 028	DTCER028	8	8	2 ICLK
0008 711Dh	ICU	DTC Activation Enable Register 029	DTCER029	8	8	2 ICLK
0008 712Dh	ICU	DTC Activation Enable Register 045	DTCER045	8	8	2 ICLK
0008 712Eh	ICU	DTC Activation Enable Register 046	DTCER046	8	8	2 ICLK
0008 7140h	ICU	DTC Activation Enable Register 064	DTCER064	8	8	2 ICLK
0008 7141h	ICU	DTC Activation Enable Register 065	DTCER065	8	8	2 ICLK
0008 7142h	ICU	DTC Activation Enable Register 066	DTCER066	8	8	2 ICLK
0008 7143h	ICU	DTC Activation Enable Register 067	DTCER067	8	8	2 ICLK
0008 7144h	ICU	DTC Activation Enable Register 068	DTCER068	8	8	2 ICLK
0008 7145h	ICU	DTC Activation Enable Register 069	DTCER069	8	8	2 ICLK
0008 7146h	ICU	DTC Activation Enable Register 070	DTCER070	8	8	2 ICLK
0008 7147h	ICU	DTC Activation Enable Register 071	DTCER071	8	8	2 ICLK
0008 7166h	ICU	DTC Activation Enable Register 102	DTCER102	8	8	2 ICLK
0008 7167h	ICU	DTC Activation Enable Register 103	DTCER103	8	8	2 ICLK
0008 7172h	ICU	DTC Activation Enable Register 114	DTCER114	8	8	2 ICLK
0008 7173h	ICU	DTC Activation Enable Register 115	DTCER115	8	8	2 ICLK
0008 7174h	ICU	DTC Activation Enable Register 116	DTCER116	8	8	2 ICLK
0008 7175h	ICU	DTC Activation Enable Register 117	DTCER117	8	8	2 ICLK
0008 7179h	ICU	DTC Activation Enable Register 121	DTCER121	8	8	2 ICLK
0008 717Ah	ICU	DTC Activation Enable Register 122	DTCER122	8	8	2 ICLK
0008 717Dh	ICU	DTC Activation Enable Register 125	DTCER125	8	8	2 ICLK
0008 717Eh	ICU	DTC Activation Enable Register 126	DTCER126	8	8	2 ICLK
0008 718Bh	ICU	DTC Activation Enable Register 139	DTCER139	8	8	2 ICLK
0008 718Ch	ICU	DTC Activation Enable Register 140	DTCER140	8	8	2 ICLK
0008 718Dh	ICU	DTC Activation Enable Register 141	DTCER141	8	8	2 ICLK
0008 71DBh	ICU	DTC Activation Enable Register 219	DTCER219	8	8	2 ICLK
0008 71DCh	ICU	DTC Activation Enable Register 220	DTCER220	8	8	2 ICLK
0008 71DFh	ICU	DTC Activation Enable Register 223	DTCER223	8	8	2 ICLK
0008 71E0h	ICU	DTC Activation Enable Register 224	DTCER224	8	8	2 ICLK
0008 71EFh	ICU	DTC Activation Enable Register 239	DTCER239	8	8	2 ICLK
0008 71F0h	ICU	DTC Activation Enable Register 240	DTCER240	8	8	2 ICLK
0008 71F7h	ICU	DTC Activation Enable Register 247	DTCER247	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (4/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 71F8h	ICU	DTC Activation Enable Register 248	DTCER248	8	8	2 ICLK
0008 7202h	ICU	Interrupt Request Enable Register 02	IER02	8	8	2 ICLK
0008 7203h	ICU	Interrupt Request Enable Register 03	IER03	8	8	2 ICLK
0008 7204h	ICU	Interrupt Request Enable Register 04	IER04	8	8	2 ICLK
0008 7205h	ICU	Interrupt Request Enable Register 05	IER05	8	8	2 ICLK
0008 7207h	ICU	Interrupt Request Enable Register 07	IER07	8	8	2 ICLK
0008 7208h	ICU	Interrupt Request Enable Register 08	IER08	8	8	2 ICLK
0008 720Bh	ICU	Interrupt Request Enable Register 0B	IER0B	8	8	2 ICLK
0008 720Ch	ICU	Interrupt Request Enable Register 0C	IER0C	8	8	2 ICLK
0008 720Eh	ICU	Interrupt Request Enable Register 0E	IER0E	8	8	2 ICLK
0008 720Fh	ICU	Interrupt Request Enable Register 0F	IER0F	8	8	2 ICLK
0008 7210h	ICU	Interrupt Request Enable Register 10	IER10	8	8	2 ICLK
0008 7211h	ICU	Interrupt Request Enable Register 11	IER11	8	8	2 ICLK
0008 721Bh	ICU	Interrupt Request Enable Register 1B	IER1B	8	8	2 ICLK
0008 721Ch	ICU	Interrupt Request Enable Register 1C	IER1C	8	8	2 ICLK
0008 721Dh	ICU	Interrupt Request Enable Register 1D	IER1D	8	8	2 ICLK
0008 721Eh	ICU	Interrupt Request Enable Register 1E	IER1E	8	8	2 ICLK
0008 721Fh	ICU	Interrupt Request Enable Register 1F	IER1F	8	8	2 ICLK
0008 72E0h	ICU	Software Interrupt Activation Register	SWINTR	8	8	2 ICLK
0008 72F0h	ICU	Fast Interrupt Set Register	FIR	16	16	2 ICLK
0008 7300h	ICU	Interrupt Source Priority Register 000	IPR000	8	8	2 ICLK
0008 7303h	ICU	Interrupt Source Priority Register 003	IPR003	8	8	2 ICLK
0008 7304h	ICU	Interrupt Source Priority Register 004	IPR004	8	8	2 ICLK
0008 7305h	ICU	Interrupt Source Priority Register 005	IPR005	8	8	2 ICLK
0008 7320h	ICU	Interrupt Source Priority Register 032	IPR032	8	8	2 ICLK
0008 7321h	ICU	Interrupt Source Priority Register 033	IPR033	8	8	2 ICLK
0008 7322h	ICU	Interrupt Source Priority Register 034	IPR034	8	8	2 ICLK
0008 732Ch	ICU	Interrupt Source Priority Register 044	IPR044	8	8	2 ICLK
0008 7339h	ICU	Interrupt Source Priority Register 057	IPR057	8	8	2 ICLK
0008 733Fh	ICU	Interrupt Source Priority Register 063	IPR063	8	8	2 ICLK
0008 7340h	ICU	Interrupt Source Priority Register 064	IPR064	8	8	2 ICLK
0008 7341h	ICU	Interrupt Source Priority Register 065	IPR065	8	8	2 ICLK
0008 7342h	ICU	Interrupt Source Priority Register 066	IPR066	8	8	2 ICLK
0008 7343h	ICU	Interrupt Source Priority Register 067	IPR067	8	8	2 ICLK
0008 7344h	ICU	Interrupt Source Priority Register 068	IPR068	8	8	2 ICLK
0008 7345h	ICU	Interrupt Source Priority Register 069	IPR069	8	8	2 ICLK
0008 7346h	ICU	Interrupt Source Priority Register 070	IPR070	8	8	2 ICLK
0008 7347h	ICU	Interrupt Source Priority Register 071	IPR071	8	8	2 ICLK
0008 7358h	ICU	Interrupt Source Priority Register 088	IPR088	8	8	2 ICLK
0008 7359h	ICU	Interrupt Source Priority Register 089	IPR089	8	8	2 ICLK
0008 735Ch	ICU	Interrupt Source Priority Register 092	IPR092	8	8	2 ICLK
0008 735Dh	ICU	Interrupt Source Priority Register 093	IPR093	8	8	2 ICLK
0008 7366h	ICU	Interrupt Source Priority Register 102	IPR102	8	8	2 ICLK
0008 7367h	ICU	Interrupt Source Priority Register 103	IPR103	8	8	2 ICLK
0008 7372h	ICU	Interrupt Source Priority Register 114	IPR114	8	8	2 ICLK
0008 7376h	ICU	Interrupt Source Priority Register 118	IPR118	8	8	2 ICLK
0008 7379h	ICU	Interrupt Source Priority Register 121	IPR121	8	8	2 ICLK
0008 737Bh	ICU	Interrupt Source Priority Register 123	IPR123	8	8	2 ICLK
0008 737Dh	ICU	Interrupt Source Priority Register 125	IPR125	8	8	2 ICLK
0008 737Fh	ICU	Interrupt Source Priority Register 127	IPR127	8	8	2 ICLK
0008 738Bh	ICU	Interrupt Source Priority Register 139	IPR139	8	8	2 ICLK
0008 73DAh	ICU	Interrupt Source Priority Register 218	IPR218	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (5/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 73DEh	ICU	Interrupt Source Priority Register 222	IPR222	8	8	2 ICLK
0008 73EEh	ICU	Interrupt Source Priority Register 238	IPR238	8	8	2 ICLK
0008 73F2h	ICU	Interrupt Source Priority Register 242	IPR242	8	8	2 ICLK
0008 73F3h	ICU	Interrupt Source Priority Register 243	IPR243	8	8	2 ICLK
0008 73F4h	ICU	Interrupt Source Priority Register 244	IPR244	8	8	2 ICLK
0008 73F5h	ICU	Interrupt Source Priority Register 245	IPR245	8	8	2 ICLK
0008 73F6h	ICU	Interrupt Source Priority Register 246	IPR246	8	8	2 ICLK
0008 73F7h	ICU	Interrupt Source Priority Register 247	IPR247	8	8	2 ICLK
0008 73F8h	ICU	Interrupt Source Priority Register 248	IPR248	8	8	2 ICLK
0008 73F9h	ICU	Interrupt Source Priority Register 249	IPR249	8	8	2 ICLK
0008 7500h	ICU	IRQ Control Register 0	IRQCR0	8	8	2 ICLK
0008 7501h	ICU	IRQ Control Register 1	IRQCR1	8	8	2 ICLK
0008 7502h	ICU	IRQ Control Register 2	IRQCR2	8	8	2 ICLK
0008 7503h	ICU	IRQ Control Register 3	IRQCR3	8	8	2 ICLK
0008 7504h	ICU	IRQ Control Register 4	IRQCR4	8	8	2 ICLK
0008 7505h	ICU	IRQ Control Register 5	IRQCR5	8	8	2 ICLK
0008 7506h	ICU	IRQ Control Register 6	IRQCR6	8	8	2 ICLK
0008 7507h	ICU	IRQ Control Register 7	IRQCR7	8	8	2 ICLK
0008 7510h	ICU	IRQ Pin Digital Filter Enable Register 0	IRQFLTE0	8	8	2 ICLK
0008 7514h	ICU	IRQ Pin Digital Filter Setting Register 0	IRQFLTC0	16	16	2 ICLK
0008 7580h	ICU	Non-Maskable Interrupt Status Register	NMISR	8	8	2 ICLK
0008 7581h	ICU	Non-Maskable Interrupt Enable Register	NMIER	8	8	2 ICLK
0008 7582h	ICU	Non-Maskable Interrupt Status Clear Register	NMICLR	8	8	2 ICLK
0008 7583h	ICU	NMI Pin Interrupt Control Register	NMICR	8	8	2 ICLK
0008 7590h	ICU	NMI Pin Digital Filter Enable Register	NMIFLTE	8	8	2 ICLK
0008 7594h	ICU	NMI Pin Digital Filter Setting Register	NMIFLTC	8	8	2 ICLK
0008 8000h	CMT	Compare Match Timer Start Register 0	CMSTR0	16	16	2 or 3 PCLKB
0008 8002h	CMT0	Compare Match Timer Control Register	CMCR	16	16	2 or 3 PCLKB
0008 8004h	CMT0	Compare Match Timer Counter	CMCNT	16	16	2 or 3 PCLKB
0008 8006h	CMT0	Compare Match Timer Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8008h	CMT1	Compare Match Timer Control Register	CMCR	16	16	2 or 3 PCLKB
0008 800Ah	CMT1	Compare Match Timer Counter	CMCNT	16	16	2 or 3 PCLKB
0008 800Ch	CMT1	Compare Match Timer Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8030h	IWDT	IWDT Refresh Register	IWDTRR	8	8	2 or 3 PCLKB
0008 8032h	IWDT	IWDT Control Register	IWDTCR	16	16	2 or 3 PCLKB
0008 8034h	IWDT	IWDT Status Register	IWDTSR	16	16	2 or 3 PCLKB
0008 8036h	IWDT	IWDT Reset Control Register	IWDTRCR	8	8	2 or 3 PCLKB
0008 8038h	IWDT	IWDT Count Stop Control Register	IWDTCSTPR	8	8	2 or 3 PCLKB
0008 8280h	CRC	CRC Control Register	CRCCR	8	8	2 or 3 PCLKB
0008 8281h	CRC	CRC Data Input Register	CRCDIR	8	8	2 or 3 PCLKB
0008 8282h	CRC	CRC Data Output Register	CRCDOR	16	16	2 or 3 PCLKB
0008 8300h	RIIC0	I^2C Bus Control Register 1	ICCR1	8	8	2 or 3 PCLKB
0008 8301h	RIIC0	I^2C Bus Control Register 2	ICCR2	8	8	2 or 3 PCLKB
0008 8302h	RIIC0	I^2C Bus Mode Register 1	ICMR1	8	8	2 or 3 PCLKB
0008 8303h	RIIC0	I^2C Bus Mode Register 2	ICMR2	8	8	2 or 3 PCLKB
0008 8304h	RIIC0	I^2C Bus Mode Register 3	ICMR3	8	8	2 or 3 PCLKB
0008 8305h	RIIC0	I^2C Bus Function Enable Register	ICFER	8	8	2 or 3 PCLKB
0008 8306h	RIIC0	I^2C Bus Status Enable Register	ICSER	8	8	2 or 3 PCLKB
0008 8307h	RIIC0	I^2C Bus Interrupt Enable Register	ICIER	8	8	2 or 3 PCLKB
0008 8308h	RIIC0	I^2C Bus Status Register 1	ICSR1	8	8	2 or 3 PCLKB
0008 8309h	RIIC0	I^2C Bus Status Register 2	ICSR2	8	8	2 or 3 PCLKB
0008 830Ah	RIIC0	Slave Address Register L0	SARL0	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (6/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 830Ah	RIIC0	Timeout Internal Counter L	TMOCNTL	8	8	2 or 3 PCLKB
0008 830Bh	RIIC0	Slave Address Register U0	SARU0	8	8	2 or 3 PCLKB
0008 830Bh	RIIC0	Timeout Internal Counter U	TMOCNTU	8	8 *1	2 or 3 PCLKB
0008 830Ch	RIIC0	Slave Address Register L1	SARL1	8	8	2 or 3 PCLKB
0008 830Dh	RIIC0	Slave Address Register U1	SARU1	8	8	2 or 3 PCLKB
0008 830Eh	RIIC0	Slave Address Register L2	SARL2	8	8	2 or 3 PCLKB
0008 830Fh	RIIC0	Slave Address Register U2	SARU2	8	8	2 or 3 PCLKB
0008 8310h	RIIC0	I^2C Bus Bit Rate Low-Level Register	ICBRL	8	8	2 or 3 PCLKB
0008 8311h	RIIC0	I^2C Bus Bit Rate High-Level Register	ICBRH	8	8	2 or 3 PCLKB
0008 8312h	RIIC0	I^2C Bus Transmit Data Register	ICDRT	8	8	2 or 3 PCLKB
0008 8313h	RIIC0	I^2C Bus Receive Data Register	ICDRR	8	8	2 or 3 PCLKB
0008 8380h	RSPI0	RSPI Control Register	SPCR	8	8	2 or 3 PCLKB
0008 8381h	RSPI0	RSPI Slave Select Polarity Register	SSLP	8	8	2 or 3 PCLKB
0008 8382h	RSPI0	RSPI Pin Control Register	SPPCR	8	8	2 or 3 PCLKB
0008 8383h	RSPI0	RSPI Status Register	SPSR	8	8	2 or 3 PCLKB
0008 8384h	RSPI0	RSPI Data Register	SPDR	32	16, 32	2 or 3 PCLKB/2ICLK
0008 8388h	RSPI0	RSPI Sequence Control Register	SPSCR	8	8	2 or 3 PCLKB
0008 8389h	RSPI0	RSPI Sequence Status Register	SPSSR	8	8	2 or 3 PCLKB
0008 838Ah	RSPI0	RSPI Bit Rate Register	SPBR	8	8	2 or 3 PCLKB
0008 838Bh	RSPI0	RSPI Data Control Register	SPDCR	8	8	2 or 3 PCLKB
0008 838Ch	RSPI0	RSPI Clock Delay Register	SPCKD	8	8	2 or 3 PCLKB
0008 838Dh	RSPI0	RSPI Slave Select Negation Delay Register	SSLND	8	8	2 or 3 PCLKB
0008 838Eh	RSPI0	RSPI Next-Access Delay Register	SPND	8	8	2 or 3 PCLKB
0008 838Fh	RSPI0	RSPI Control Register 2	SPCR2	8	8	2 or 3 PCLKB
0008 8390h	RSPI0	RSPI Command Register 0	SPCMD0	16	16	2 or 3 PCLKB
0008 8392h	RSPI0	RSPI Command Register 1	SPCMD1	16	16	2 or 3 PCLKB
0008 8394h	RSPI0	RSPI Command Register 2	SPCMD2	16	16	2 or 3 PCLKB
0008 8396h	RSPI0	RSPI Command Register 3	SPCMD3	16	16	2 or 3 PCLKB
0008 8398h	RSPI0	RSPI Command Register 4	SPCMD4	16	16	2 or 3 PCLKB
0008 839Ah	RSPI0	RSPI Command Register 5	SPCMD5	16	16	2 or 3 PCLKB
0008 839Ch	RSPI0	RSPI Command Register 6	SPCMD6	16	16	2 or 3 PCLKB
0008 839Eh	RSPI0	RSPI Command Register 7	SPCMD7	16	16	2 or 3 PCLKB
0008 8680h	MTU	Timer Start Register	TSTR	8	8, 16	2 or 3 PCLKB
0008 8681h	MTU	Timer Synchronous Register	TSYR	8	8, 16	2 or 3 PCLKB
0008 8690h	MTU0	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8691h	MTU1	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8692h	MTU2	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8695h	MTU5	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8700h	MTU0	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8701h	MTU0	Timer Mode Register	TMDR	8	8	2 or 3 PCLKB
0008 8702h	MTU0	Timer I/O Control Register H	TIORH	8	8	2 or 3 PCLKB
0008 8703h	MTU0	Timer I/O Control Register L	TIORL	8	8	2 or 3 PCLKB
0008 8704h	MTU0	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 8705h	MTU0	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8706h	MTU0	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8708h	MTU0	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 870Ah	MTU0	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 870Ch	MTU0	Timer General Register C	TGRC	16	16	2 or 3 PCLKB
0008 870Eh	MTU0	Timer General Register D	TGRD	16	16	2 or 3 PCLKB
0008 8720h	MTU0	Timer General Register E	TGRE	16	16	2 or 3 PCLKB
0008 8722h	MTU0	Timer General Register F	TGRF	16	16	2 or 3 PCLKB
0008 8724h	MTU0	Timer Interrupt Enable Register 2	TIER2	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (7/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 8726h	MTU0	Timer Buffer Operation Transfer Mode Register	TBTM	8	8	2 or 3 PCLKB
0008 8780h	MTU1	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8781h	MTU1	Timer Mode Register	TMDR	8	8	2 or 3 PCLKB
0008 8782h	MTU1	Timer I/O Control Register	TIOR	8	8	2 or 3 PCLKB
0008 8784h	MTU1	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 8785h	MTU1	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8786h	MTU1	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8788h	MTU1	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 878Ah	MTU1	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 8790h	MTU1	Timer Input Capture Control Register	TICCR	8	8	2 or 3 PCLKB
0008 8800h	MTU2	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8801h	MTU2	Timer Mode Register	TMDR	8	8	2 or 3 PCLKB
0008 8802h	MTU2	Timer I/O Control Register	TIOR	8	8	2 or 3 PCLKB
0008 8804h	MTU2	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 8805h	MTU2	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8806h	MTU2	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8808h	MTU2	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 880Ah	MTU2	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 8880h	MTU5	Timer Counter U	TCNTU	16	16	2 or 3 PCLKB
0008 8882h	MTU5	Timer General Register U	TGRU	16	16	2 or 3 PCLKB
0008 8884h	MTU5	Timer Control Register U	TCRU	8	8	2 or 3 PCLKB
0008 8886h	MTU5	Timer I/O Control Register U	TIORU	8	8	2 or 3 PCLKB
0008 8890h	MTU5	Timer Counter V	TCNTV	16	16	2 or 3 PCLKB
0008 8892h	MTU5	Timer General Register V	TGRV	16	16	2 or 3 PCLKB
0008 8894h	MTU5	Timer Control Register V	TCRV	8	8	2 or 3 PCLKB
0008 8896h	MTU5	Timer I/O Control Register V	TIORV	8	8	2 or 3 PCLKB
0008 88A0h	MTU5	Timer Counter W	TCNTW	16	16	2 or 3 PCLKB
0008 88A2h	MTU5	Timer General Register W	TGRW	16	16	2 or 3 PCLKB
0008 88A4h	MTU5	Timer Control Register W	TCRW	8	8	2 or 3 PCLKB
0008 88A6h	MTU5	Timer I/O Control Register W	TIORW	8	8	2 or 3 PCLKB
0008 88B2h	MTU5	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 88B4h	MTU5	Timer Start Register	TSTR	8	8	2 or 3 PCLKB
0008 88B6h	MTU5	Timer Compare Match Clear Register	TCNTCMPCLR	8	8	2 or 3 PCLKB
0008 9000h	S12AD	A/D Control Register	ADCSR	16	16	2 or 3 PCLKB
0008 9004h	S12AD	A/D Channel Select Register A	ADANSA	16	16	2 or 3 PCLKB
0008 9008h	S12AD	A/D-Converted Value Addition Mode Select Register	ADADS	16	16	2 or 3 PCLKB
0008 900Ch	S12AD	A/D-Converted Value Addition Count Select Register	ADADC	8	8	2 or 3 PCLKB
0008 900Eh	S12AD	A/D Control Extended Register	ADCER	16	16	2 or 3 PCLKB
0008 9010h	S12AD	A/D Start Trigger Select Register	ADSTRGR	16	16	2 or 3 PCLKB
0008 9012h	S12AD	A/D Converted Extended Input Control Register	ADEXICR	16	16	2 or 3 PCLKB
0008 9014h	S12AD	A/D Channel Select Register B	ADANSB	16	16	2 or 3 PCLKB
0008 9018h	S12AD	A/D Data Duplication Register	ADDBLDR	16	16	2 or 3 PCLKB
0008 901Ah	S12AD	A/D Temperature Sensor Data Register	ADTSDR	16	16	2 or 3 PCLKB
0008 901Ch	S12AD	A/D Internal Reference Voltage Data Register	ADOCDR	16	16	2 or 3 PCLKB
0008 9020h	S12AD	A/D Data Register 0	ADDR0	16	16	2 or 3 PCLKB
0008 9022h	S12AD	A/D Data Register 1	ADDR1	16	16	2 or 3 PCLKB
0008 9024h	S12AD	A/D Data Register 2	ADDR2	16	16	2 or 3 PCLKB
0008 9026h	S12AD	A/D Data Register 3	ADDR3	16	16	2 or 3 PCLKB
0008 9028h	S12AD	A/D Data Register 4	ADDR4	16	16	2 or 3 PCLKB
0008 902Ch	S12AD	A/D Data Register 6	ADDR6	16	16	2 or 3 PCLKB
0008 9030h	S12AD	A/D Data Register 8	ADDR8	16	16	2 or 3 PCLKB
0008 9032h	S12AD	A/D Data Register 9	ADDR9	16	16	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (8/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 9034h	S12AD	A/D Data Register 10	ADDR10	16	16	2 or 3 PCLKB
0008 9036h	S12AD	A/D Data Register 11	ADDR11	16	16	2 or 3 PCLKB
0008 9038h	S12AD	A/D Data Register 12	ADDR12	16	16	2 or 3 PCLKB
0008 903Ah	S12AD	A/D Data Register 13	ADDR13	16	16	2 or 3 PCLKB
0008 903Ch	S12AD	A/D Data Register 14	ADDR14	16	16	2 or 3 PCLKB
0008 903Eh	S12AD	A/D Data Register 15	ADDR15	16	16	2 or 3 PCLKB
0008 9060h	S12AD	A/D Sampling State Register 0	ADSSTR0	8	8	2 or 3 PCLKB
0008 9061h	S12AD	A/D Sampling State Register L	ADSSTRL	8	8	2 or 3 PCLKB
0008 9070h	S12AD	A/D Sampling State Register T	ADSSTRT	8	8	2 or 3 PCLKB
0008 9071h	S12AD	A/D Sampling State Register O	ADSSTRO	8	8	2 or 3 PCLKB
0008 9073h	S12AD	A/D Sampling State Register 1	ADSSTR1	8	8	2 or 3 PCLKB
0008 9074h	S12AD	A/D Sampling State Register 2	ADSSTR2	8	8	2 or 3 PCLKB
0008 9075h	S12AD	A/D Sampling State Register 3	ADSSTR3	8	8	2 or 3 PCLKB
0008 9076h	S12AD	A/D Sampling State Register 4	ADSSTR4	8	8	2 or 3 PCLKB
0008 9078h	S12AD	A/D Sampling State Register 6	ADSSTR6	8	8	2 or 3 PCLKB
0008 A020h	SCI1	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 A021h	SCI1	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 A022h	SCI1	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 A023h	SCI1	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 A024h	SCI1	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 A025h	SCI1	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 A026h	SCI1	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A027h	SCI1	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A028h	SCI1	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A029h	SCI1	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A02Ah	SCI1	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A02Bh	SCI1	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A02Ch	SCI1	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A02Dh	SCI1	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 A0A0h	SCI5	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 A0A1h	SCI5	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 A0A2h	SCI5	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 A0A3h	SCI5	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 A0A4h	SCI5	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 A0A5h	SCI5	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 A0A6h	SCI5	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A0A7h	SCI5	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A0A8h	SCI5	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A0A9h	SCI5	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A0AAh	SCI5	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A0ABh	SCI5	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A0ACh	SCI5	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A0ADh	SCI5	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 B000h	CAC	CAC Control Register 0	CACR0	8	8	2 or 3 PCLKB
0008 B001h	CAC	CAC Control Register 1	CACR1	8	8	2 or 3 PCLKB
0008 B002h	CAC	CAC Control Register 2	CACR2	8	8	2 or 3 PCLKB
0008 B003h	CAC	CAC Interrupt Request Enable Register	CAICR	8	8	2 or 3 PCLKB
0008 B004h	CAC	CAC Status Register	CASTR	8	8	2 or 3 PCLKB
0008 B006h	CAC	CAC Upper-Limit Value Setting Register	CAULVR	16	16	2 or 3 PCLKB
0008 B008h	CAC	CAC Lower-Limit Value Setting Register	CALLVR	16	16	2 or 3 PCLKB
0008 B00Ah	CAC	CAC Counter Buffer Register	CACNTBR	16	16	2 or 3 PCLKB
0008 B080h	DOC	DOC Control Register	DOCR	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (9/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 B082h	DOC	DOC Data Input Register	DODIR	16	16	2 or 3 PCLKB
0008 B084h	DOC	DOC Data Setting Register	DODSR	16	16	2 or 3 PCLKB
0008 B300h	SCI12	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 B301h	SCI12	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 B302h	SCI12	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 B303h	SCI12	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 B304h	SCI12	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 B305h	SCI12	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 B306h	SCI12	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 B307h	SCI12	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 B308h	SCI12	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 B309h	SCI12	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 B30Ah	SCI12	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 B30Bh	SCI12	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 B30Ch	SCI12	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 B30Dh	SCI12	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 B320h	SCI12	Extended Serial Mode Enable Register	ESMER	8	8	2 or 3 PCLKB
0008 B321h	SCI12	Control Register 0	CR0	8	8	2 or 3 PCLKB
0008 B322h	SCI12	Control Register 1	CR1	8	8	2 or 3 PCLKB
0008 B323h	SCI12	Control Register 2	CR2	8	8	2 or 3 PCLKB
0008 B324h	SCI12	Control Register 3	CR3	8	8	2 or 3 PCLKB
0008 B325h	SCI12	Port Control Register	PCR	8	8	2 or 3 PCLKB
0008 B326h	SCI12	Interrupt Control Register	ICR	8	8	2 or 3 PCLKB
0008 B327h	SCI12	Status Register	STR	8	8	2 or 3 PCLKB
0008 B328h	SCI12	Status Clear Register	STCR	8	8	2 or 3 PCLKB
0008 B329h	SCI12	Control Field 0 Data Register	CF0DR	8	8	2 or 3 PCLKB
0008 B32Ah	SCI12	Control Field 0 Compare Enable Register	CF0CR	8	8	2 or 3 PCLKB
0008 B32Bh	SCI12	Control Field 0 Receive Data Register	CF0RR	8	8	2 or 3 PCLKB
0008 B32Ch	SCI12	Primary Control Field 1 Data Register	PCF1DR	8	8	2 or 3 PCLKB
0008 B32Dh	SCI12	Secondary Control Field 1 Data Register	SCF1DR	8	8	2 or 3 PCLKB
0008 B32Eh	SCI12	Control Field 1 Compare Enable Register	CF1CR	8	8	2 or 3 PCLKB
0008 B32Fh	SCI12	Control Field 1 Receive Data Register	CF1RR	8	8	2 or 3 PCLKB
0008 B330h	SCI12	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 B331h	SCI12	Timer Mode Register	TMR	8	8	2 or 3 PCLKB
0008 B332h	SCI12	Timer Prescaler Register	TPRE	8	8	2 or 3 PCLKB
0008 B333h	SCI12	Timer Count Register	TCNT	8	8	2 or 3 PCLKB
0008 C000h	PORT0	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C001h	PORT1	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C002h	PORT2	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C003h	PORT3	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C004h	PORT4	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C005h	PORT5	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ah	PORTA	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Bh	PORTB	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ch	PORTC	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Eh	PORTE	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C011h	PORTH	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C012h	PORTJ	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C020h	PORT0	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C021h	PORT1	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C022h	PORT2	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C023h	PORT3	Port Output Data Register	PODR	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (10/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 C024h	PORT4	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C025h	PORT5	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Ah	PORTA	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Bh	PORTB	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Ch	PORTC	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Eh	PORTE	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C031h	PORTH	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C032h	PORTJ	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C040h	PORT0	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C041h	PORT1	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C042h	PORT2	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C043h	PORT3	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C044h	PORT4	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C045h	PORT5	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C04Ah	PORTA	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C04Bh	PORTB	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C04Ch	PORTC	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C04Eh	PORTE	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C051h	PORTH	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C052h	PORTJ	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C060h	PORT0	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C061h	PORT1	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C062h	PORT2	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C063h	PORT3	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C064h	PORT4	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C065h	PORT5	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Ah	PORTA	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Bh	PORTB	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Ch	PORTC	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Eh	PORTE	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C071h	PORTH	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C072h	PORTJ	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C083h	PORT1	Open Drain Control Register 1	ODR1	8	8, 16	2 or 3 PCLKB
0008 C085h	PORT2	Open Drain Control Register 1	ODR1	8	8, 16	2 or 3 PCLKB
0008 C086h	PORT3	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB
0008 C094h	PORTA	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB
0008 C095h	PORTA	Open Drain Control Register 1	ODR1	8	8, 16	2 or 3 PCLKB
0008 C096h	PORTB	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB
0008 C097h	PORTB	Open Drain Control Register 1	ODR1	8	8, 16	2 or 3 PCLKB
0008 C098h	PORTC	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB
0008 C099h	PORTC	Open Drain Control Register 1	ODR1	8	8, 16	2 or 3 PCLKB
0008 C09Ch	PORTE	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB
0008 C09Dh	PORTE	Open Drain Control Register 1	ODR1	8	8, 16	2 or 3 PCLKB
0008 C0C0h	PORT0	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C1h	PORT1	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C2h	PORT2	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (11/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 C0C3h	PORT3	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C5h	PORT5	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CAh	PORTA	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CBh	PORTB	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CCh	PORTC	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CEh	PORTE	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0D1h	PORTH	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C11Fh	MPC	Write-Protect Register	PWPR	8	8	2 or 3 PCLKB
0008 C120h	PORT	Port Switching Register B	PSRB	8	8	2 or 3 PCLKB
0008 C121h	PORT	Port Switching Register A	PSRA	8	8	2 or 3 PCLKB
0008 C14Ch	MPC	P14 Pin Function Control Register	P14PFS	8	8	2 or 3 PCLKB
0008 C14Dh	MPC	P15 Pin Function Control Register	P15PFS	8	8	2 or 3 PCLKB
0008 C14Eh	MPC	P16 Pin Function Control Register	P16PFS	8	8	2 or 3 PCLKB
0008 C14Fh	MPC	P17 Pin Function Control Register	P17PFS	8	8	2 or 3 PCLKB
0008 C156h	MPC	P26 Pin Function Control Register	P26PFS	8	8	2 or 3 PCLKB
0008 C157h	MPC	P27 Pin Function Control Register	P27PFS	8	8	2 or 3 PCLKB
0008 C158h	MPC	P30 Pin Function Control Register	P30PFS	8	8	2 or 3 PCLKB
0008 C159h	MPC	P31 Pin Function Control Register	P31PFS	8	8	2 or 3 PCLKB
0008 C15Ah	MPC	P32 Pin Function Control Register	P32PFS	8	8	2 or 3 PCLKB
0008 C160h	MPC	P40 Pin Function Control Register	P40PFS	8	8	2 or 3 PCLKB
0008 C161h	MPC	P41 Pin Function Control Register	P41PFS	8	8	2 or 3 PCLKB
0008 C162h	MPC	P42 Pin Function Control Register	P42PFS	8	8	2 or 3 PCLKB
0008 C163h	MPC	P43 Pin Function Control Register	P43PFS	8	8	2 or 3 PCLKB
0008 C164h	MPC	P44 Pin Function Control Register	P44PFS	8	8	2 or 3 PCLKB
0008 C166h	MPC	P46 Pin Function Control Register	P46PFS	8	8	2 or 3 PCLKB
0008 C190h	MPC	PA0 Pin Function Control Register	PA0PFS	8	8	2 or 3 PCLKB
0008 C191h	MPC	PA1 Pin Function Control Register	PA1PFS	8	8	2 or 3 PCLKB
0008 C193h	MPC	PA3 Pin Function Control Register	PA3PFS	8	8	2 or 3 PCLKB
0008 C194h	MPC	PA4 Pin Function Control Register	PA4PFS	8	8	2 or 3 PCLKB
0008 C196h	MPC	PA6 Pin Function Control Register	PA6PFS	8	8	2 or 3 PCLKB
0008 C198h	MPC	PB0 Pin Function Control Register	PB0PFS	8	8	2 or 3 PCLKB
0008 C199h	MPC	PB1 Pin Function Control Register	PB1PFS	8	8	2 or 3 PCLKB
0008 C19Bh	MPC	PB3 Pin Function Control Register	PB3PFS	8	8	2 or 3 PCLKB
0008 C19Dh	MPC	PB5 Pin Function Control Register	PB5PFS	8	8	2 or 3 PCLKB
0008 C19Eh	MPC	PB6 Pin Function Control Register	PB6PFS	8	8	2 or 3 PCLKB
0008 C19Fh	MPC	PB7 Pin Function Control Register	PB7PFS	8	8	2 or 3 PCLKB
0008 C1A2h	MPC	PC2 Pin Function Control Register	PC2PFS	8	8	2 or 3 PCLKB
0008 C1A3h	MPC	PC3 Pin Function Control Register	PC3PFS	8	8	2 or 3 PCLKB
0008 C1A4h	MPC	PC4 Pin Function Control Register	PC4PFS	8	8	2 or 3 PCLKB
0008 C1A5h	MPC	PC5 Pin Function Control Register	PC5PFS	8	8	2 or 3 PCLKB
0008 C1A6h	MPC	PC6 Pin Function Control Register	PC6PFS	8	8	2 or 3 PCLKB
0008 C1A7h	MPC	PC7 Pin Function Control Register	PC7PFS	8	8	2 or 3 PCLKB
0008 C1B0h	MPC	PE0 Pin Function Control Register	PE0PFS	8	8	2 or 3 PCLKB
0008 C1B1h	MPC	PE1 Pin Function Control Register	PE1PFS	8	8	2 or 3 PCLKB
0008 C1B2h	MPC	PE2 Pin Function Control Register	PE2PFS	8	8	2 or 3 PCLKB
0008 C1B3h	MPC	PE3 Pin Function Control Register	PE3PFS	8	8	2 or 3 PCLKB
0008 C1B4h	MPC	PE4 Pin Function Control Register	PE4PFS	8	8	2 or 3 PCLKB
0008 C1B5h	MPC	PE5 Pin Function Control Register	PE5PFS	8	8	2 or 3 PCLKB
0008 C1B6h	MPC	PE6 Pin Function Control Register	PE6PFS	8	8	2 or 3 PCLKB
0008 C1B7h	MPC	PE7 Pin Function Control Register	PE7PFS	8	8	2 or 3 PCLKB
0008 C1C8h	MPC	PH0 Pin Function Control Register	PH0PFS	8	8	2 or 3 PCLKB
0008 C1C9h	MPC	PH1 Pin Function Control Register	PH1PFS	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (12/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 C1CAh	MPC	PH2 Pin Function Control Register	PH2PFS	8	8	2 or 3 PCLKB
0008 C1CBh	MPC	PH3 Pin Function Control Register	PH3PFS	8	8	2 or 3 PCLKB
0008 C1D6h	MPC	PJ6 Pin Function Control Register	PJ6PFS	8	8	2 or 3 PCLKB
0008 C1D7h	MPC	PJ7 Pin Function Control Register	PJ7PFS	8	8	2 or 3 PCLKB
0008 C290h	SYSTEM	Reset Status Register 0	RSTSR0	8	8	4 or 5 PCLKB
0008 C291h	SYSTEM	Reset Status Register 1	RSTSR1	8	8	4 or 5 PCLKB
0008 C293h	SYSTEM	Main Clock Oscillator Forced Oscillation Control Register	MOFCR	8	8	4 or 5 PCLKB
0008 C297h	SYSTEM	Voltage Monitoring Circuit Control Register	LVCMPCR	8	8	4 or 5 PCLKB
0008 C298h	SYSTEM	Voltage Detection Level Select Register	LVDLVLR	8	8	4 or 5 PCLKB
0008 C29Ah	SYSTEM	Voltage Monitoring 1 Circuit Control Register 0	LVD1CR0	8	8	4 or 5 PCLKB
0008 C29Bh	SYSTEM	Voltage Monitoring 2 Circuit Control Register 0	LVD2CR0	8	8	4 or 5 PCLKB
0008 C400h	RTC	64-Hz Counter	R64CNT	8	8	2 or 3 PCLKB
0008 C402h	RTC	Second Counter	RSECCNT	8	8	2 or 3 PCLKB
0008 C402h	RTC	Binary Counter 0	BCNT0	8	8	2 or 3 PCLKB
0008 C404h	RTC	Minute Counter	RMINCNT	8	8	2 or 3 PCLKB
0008 C404h	RTC	Binary Counter 1	BCNT1	8	8	2 or 3 PCLKB
0008 C406h	RTC	Hour Counter	RHRCNT	8	8	2 or 3 PCLKB
0008 C406h	RTC	Binary Counter 2	BCNT2	8	8	2 or 3 PCLKB
0008 C408h	RTC	Day-Of-Week Counter	RWKCNT	8	8	2 or 3 PCLKB
0008 C408h	RTC	Binary Counter 3	BCNT3	8	8	2 or 3 PCLKB
0008 C40Ah	RTC	Date Counter	RDAYCNT	8	8	2 or 3 PCLKB
0008 C40Ch	RTC	Month Counter	RMONCNT	8	8	2 or 3 PCLKB
0008 C40Eh	RTC	Year Counter	RYRCNT	16	16	2 or 3 PCLKB
0008 C410h	RTC	Second Alarm Register	RSECAR	8	8	2 or 3 PCLKB
0008 C410h	RTC	Binary Counter 0 Alarm Register	BCNT0AR	8	8	2 or 3 PCLKB
0008 C412h	RTC	Minute Alarm Register	RMINAR	8	8	2 or 3 PCLKB
0008 C412h	RTC	Binary Counter 1 Alarm Register	BCNT1AR	8	8	2 or 3 PCLKB
0008 C414h	RTC	Hour Alarm Register	RHRAR	8	8	2 or 3 PCLKB
0008 C414h	RTC	Binary Counter 2 Alarm Register	BCNT2AR	8	8	2 or 3 PCLKB
0008 C416h	RTC	Day-of-Week Alarm Register	RWKAR	8	8	2 or 3 PCLKB
0008 C416h	RTC	Binary Counter 3 Alarm Register	BCNT3AR	8	8	2 or 3 PCLKB
0008 C418h	RTC	Date Alarm Register	RDAYAR	8	8	2 or 3 PCLKB
0008 C418h	RTC	Binary Counter 0 Alarm Enable Register	BCNT0AER	8	8	2 or 3 PCLKB
0008 C41Ah	RTC	Month Alarm Register	RMONAR	8	8	2 or 3 PCLKB
0008 C41Ah	RTC	Binary Counter 1 Alarm Enable Register	BCNT1AER	8	8	2 or 3 PCLKB
0008 C41Ch	RTC	Year Alarm Register	RYRAR	16	16	2 or 3 PCLKB
0008 C41Ch	RTC	Binary Counter 2 Alarm Enable Register	BCNT2AER	16	16	2 or 3 PCLKB
0008 C41Eh	RTC	Year Alarm Enable Register	RYRAREN	8	8	2 or 3 PCLKB
0008 C41Eh	RTC	Binary Counter 3 Alarm Enable Register	BCNT3AER	8	8	2 or 3 PCLKB
0008 C422h	RTC	RTC Control Register 1	RCR1	8	8	2 or 3 PCLKB
0008 C424h	RTC	RTC Control Register 2	RCR2	8	8	2 or 3 PCLKB
0008 C426h	RTC	RTC Control Register 3	RCR3	8	8	2 or 3 PCLKB
0008 C42Eh	RTC	Time Error Adjustment Register	RADJ	8	8	2 or 3 PCLKB
007F C0ACh	TEMPS	Temperature Sensor Calibration Data Register	TSCDRL	8	8	1 or 2 PCLKB
007F C0ADh	TEMPS	Temperature Sensor Calibration Data Register	TSCDRH	8	8	1 or 2 PCLKB
007F C0B0h	FLASH	Flash Start-Up Setting Monitor Register	FSCMR	16	16	2 or 3 FCLK
007F C0B2h	FLASH	Flash Access Window Start Address Monitor	FAWSMR	16	16	2 or 3 FCLK
007F C0B4h	FLASH	Flash Access Window End Address Monitor Register	FAWEMR	16	16	2 or 3 FCLK
007F C0B6h	FLASH	Flash Initial Setting Register	FISR	8	8	2 or 3 FCLK
007F C0B7h	FLASH	Flash Extra Area Control Register	FEXCR	8	8	2 or 3 FCLK
007F C0B8h	FLASH	Flash Error Address Monitor Register L	FEAML	16	16	2 or 3 FCLK
007F C0BAh	FLASH	Flash Error Address Monitor Register H	FEAMH	8	8	2 or 3 FCLK

Table 4.1 List of I/O Registers (Address Order) (13/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
007F C0C0h	FLASH	Protection Unlock Register	FPR	8	8	2 or 3 FCLK
007F C0C1h	FLASH	Protection Unlock Status Register	FPSR	8	8	2 or 3 FCLK
007F C0C2h	FLASH	Flash Read Buffer Register L	FRBL	16	16	2 or 3 FCLK
007F C0C4h	FLASH	Flash Read Buffer Register H	FRBH	16	16	2 or 3 FCLK
007F FF80h	FLASH	Flash P/E Mode Control Register	FPMCR	8	8	2 or 3 FCLK
007F FF81h	FLASH	Flash Area Select Register	FASR	8	8	2 or 3 FCLK
007F FF82h	FLASH	Flash Processing Start Address Register L	FSARL	16	16	2 or 3 FCLK
007F FF84h	FLASH	Flash Processing Start Address Register H	FSARH	8	8	2 or 3 FCLK
007F FF85h	FLASH	Flash Control Register	FCR	8	8	2 or 3 FCLK
007F FF86h	FLASH	Flash Processing End Address Register L	FEARL	16	16	2 or 3 FCLK
007F FF88h	FLASH	Flash Processing End Address Register H	FEARH	8	8	2 or 3 FCLK
007F FF89h	FLASH	Flash Reset Register	FRESETR	8	8	2 or 3 FCLK
007F FF8Ah	FLASH	Flash Status Register 0	FSTATR0	8	8	2 or 3 FCLK
007F FF8Bh	FLASH	Flash Status Register 1	FSTATR1	8	8	2 or 3 FCLK
007F FF8Ch	FLASH	Flash Write Buffer Register L	FWBL	16	16	2 or 3 FCLK
007F FF8Eh	FLASH	Flash Write Buffer Register H	FWBH	16	16	2 or 3 FCLK
007F FFB2h	FLASH	Flash P/E Mode Entry Register	FENTRYR	16	16	2 or 3 FCLK

Note 1. Odd addresses cannot be accessed in 16-bit units. When accessing a register in 16-bit units, access the address of the TMOCNTL register. Table 24.6 lists register allocation for 16-bit access in the User's Manual: Hardware.

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Conditions: VSS = AVSS0 = VREFL0 = 0 V

Item		Symbol	Value	Unit
Power supply voltage		VCC	–0.3 to +4.6	V
Input voltage	Ports for 5 V tolerant*1	V_{in}	–0.3 to +6.5	V
	Ports P40 to P44, P46, ports PJ6, PJ7	V_{in}	–0.3 to AVCC0 +0.3	V
	Ports other than above	V_{in}	–0.3 to VCC +0.3	V
Reference power supply voltage		VREFH0	–0.3 to AVCC0 +0.3	V
Analog power supply voltage		AVCC0	–0.3 to +4.6	V
Analog input voltage		V_{AN}	–0.3 to AVCC0 + 0.3 (when AN000 to AN004 and AN006 used) –0.3 to VCC + 0.3 (when AN008 to AN015 used)	V
Operating temperature*2		T_{opr}	–40 to +85 –40 to +105	°C
Storage temperature		T_{stg}	–55 to +125	°C

Caution: Permanent damage to the MCU may result if absolute maximum ratings are exceeded.
To preclude any malfunctions due to noise interference, insert capacitors of high frequency characteristics between the VCC and VSS pins, between the AVCC0 and AVSS0 pins, and between the VREFH0 and VREFL0 pins. Place capacitors of about 0.1 µF as close as possible to every power supply pin and use the shortest and heaviest possible traces. Also, connect capacitors as stabilization capacitance.

Connect the VCL pin to a VSS pin via a 4.7 µF capacitor. The capacitor must be placed close to the pin, refer to section 5.9.1, Connecting VCL Capacitor and Bypass Capacitors.

Do not input signals or an I/O pull-up power supply to ports other than 5-V tolerant ports while the device is not powered. The current injection that results from input of such a signal or I/O pull-up may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements.
If input voltage (within the specified range from -0.3 to + 6.5V) is applied to 5-V tolerant ports, it will not cause problems such as damage to the MCU.

Note 1. Ports P16, P17, PA6, and PB0 are 5 V tolerant.
Note 2. The upper limit of operating temperature is 85°C or 105°C, depending on the product. For details, refer to 1.2 List of Products.

Table 5.2 Recommended Operating Conditions

Item	Symbol	Min.	Typ.	Max.	Unit
Power supply voltages	VCC*1	1.8	—	3.6	V
	VSS	—	0	—	V
Analog power supply voltages	AVCC0*1, *2	1.8	—	3.6	V
	AVSS0	—	0	—	V
	VREFH0	1.8	—	AVCC0	V
	VREFL0	—	0	—	V

Note 1. Supply AVCC0 simultaneously with or after supplying VCC.
Note 2. Refer to section 27.6.10, Voltage Range of Analog Power Supply Pins in the User's Manual: Hardware to determine the AVCC0 voltage.

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)	V_{IH}	VCC × 0.7	—	5.8	V	
	Ports P16, P17, port PA6, port PB0 (5 V tolerant)		VCC × 0.8	—	5.8		
	Ports P03, P05, ports P14, P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC0 to PC7, ports PE0 to PE7, ports PH0 to PH3, PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	RIIC input pin (except for SMBus)	V_{IL}	–0.3	—	VCC × 0.3		
	Other than RIIC input pin		–0.3	—	VCC × 0.2		
	RIIC input pin (except for SMBus)	ΔV_T	VCC × 0.05	—	—		
	Other than RIIC input pin		VCC × 0.1	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	RIIC input pin (SMBus)		2.1	—	VCC + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		
	RIIC input pin (SMBus)		–0.3	—	0.8		

Table 5.4 DC Characteristics (2)

Conditions: 1.8 V ≤ VCC < 2.7 V, 1.8 V ≤ AVCC0 < 2.7 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	Ports P16, P17, port PA6, port PB0 (5 V tolerant)	V_{IH}	VCC × 0.8	—	5.8	V	
	Ports P03, P05, ports P14, P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC0 to PC7, ports PE0 to PE7, ports PH0 to PH3, PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	All pins		–0.3	—	VCC × 0.2		
	All pins	ΔV_T	VCC × 0.01	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		

Table 5.5 DC Characteristics (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input leakage current	RES#, MD, port P35, port PH7	$\lvert I_{in} \rvert$	—	—	1.0	µA	V_{in} = 0 V, VCC
Three-state leakage current (off-state)	Ports for 5 V tolerant	$\lvert I_{TSI} \rvert$	—	—	1.0	µA	V_{in} = 0 V, 5.8 V
	Pins other than above		—	—	1.0		V_{in} = 0 V, VCC
Input capacitance	All input pins (except for port P16, port P35)	C_{in}	—	—	15	pF	V_{in} = 0 mV, Frequency: 1 MHz, T_a = 25°C
	Port P16, port P35		—	—	30		

Table 5.6 DC Characteristics (4)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input pull-up resistor	All ports (except for port P35, port PH7)	R_U	10	20	100	kΩ	V_{in} = 0 V

Table 5.7 DC Characteristics (5) (1/2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

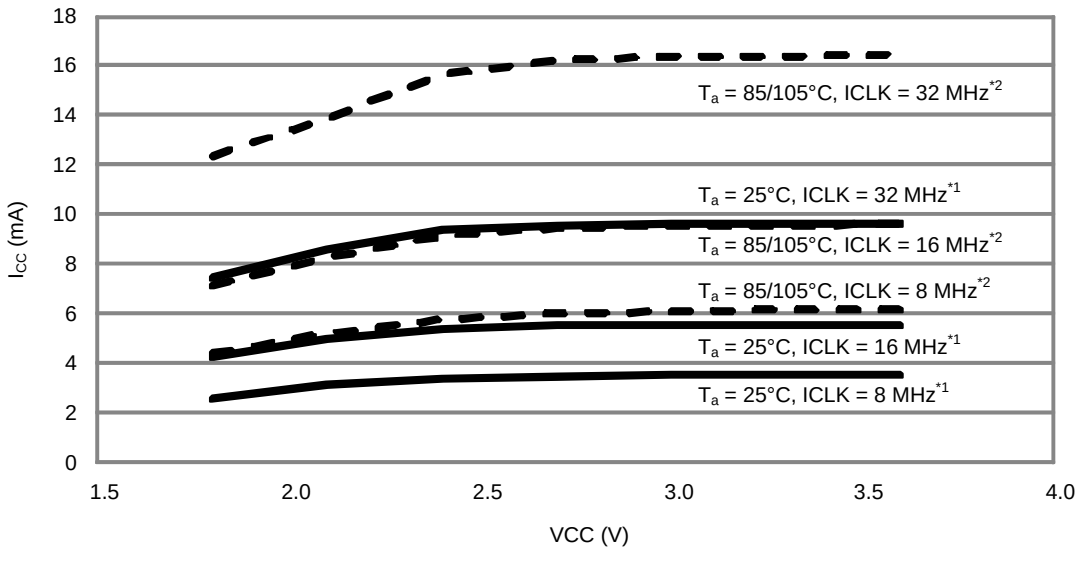
Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	High-speed operating mode	Normal operating mode	No peripheral operation*2	ICLK = 32 MHz	I_{CC}	3.2	—	mA	
				ICLK = 16 MHz		2.1	—		
				ICLK = 8 MHz		1.5	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		9.6	—		
				ICLK = 16 MHz		5.6	—		
				ICLK = 8 MHz		3.5	—		
			All peripheral operation: Max.*3	ICLK = 32 MHz		—	21.6		
		Sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.5	—		
				ICLK = 16 MHz		1.2	—		
				ICLK = 8 MHz		1.0	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		5.1	—		
				ICLK = 16 MHz		3.1	—		
				ICLK = 8 MHz		2.0	—		
		Deep sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.0	—		
				ICLK = 16 MHz		0.80	—		
				ICLK = 8 MHz		0.70	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		3.4	—		
				ICLK = 16 MHz		2.2	—		
				ICLK = 8 MHz		1.5	—		
	Middle-speed operating modes	Normal operating mode	No peripheral operation*5	ICLK = 12 MHz	I_{CC}	1.7	—	mA	
				ICLK = 8 MHz		1.3	—		
				ICLK = 1 MHz		0.72	—		
			All peripheral operation: Normal*6	ICLK = 12 MHz		4.2	—		
				ICLK = 8 MHz		3.3	—		
				ICLK = 1 MHz		1.2	—		
			All peripheral operation: Max.*6	ICLK = 12 MHz		—	10		
		Sleep mode	No peripheral operation*5	ICLK = 12 MHz		1.0	—		
				ICLK = 8 MHz		0.82	—		
				ICLK = 1 MHz		0.65	—		
			All peripheral operation: Normal*6	ICLK = 12 MHz		2.3	—		
				ICLK = 8 MHz		1.9	—		
				ICLK = 1 MHz		1.0	—		
		Deep sleep mode	No peripheral operation*5	ICLK = 12 MHz		0.8	—		
				ICLK = 8 MHz		0.66	—		
				ICLK = 1 MHz		0.58	—		
			All peripheral operation: Normal*6	ICLK = 12 MHz		1.6	—		
				ICLK = 8 MHz		1.5	—		
				ICLK = 1 MHz		0.87	—		

Table 5.7 DC Characteristics (5) (2/2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

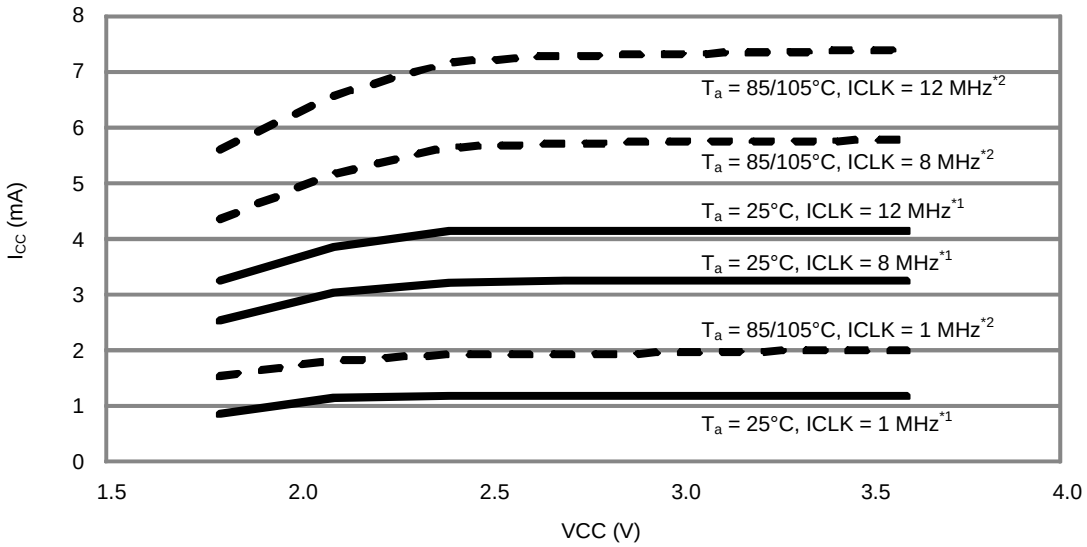
Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	Low-speed operating mode	Normal operating mode	No peripheral operation*7	ICLK = 32.768 kHz	I_{CC}	3.9	—	µA	
			All peripheral operation: Normal*8, *9	ICLK = 32.768 kHz		10.4	—		
			All peripheral operation: Max.*8, *9	ICLK = 32.768 kHz		—	36		
		Sleep mode	No peripheral operation*7	ICLK = 32.768 kHz		2.1	—		
			All peripheral operation: Normal*8	ICLK = 32.768 kHz		5.6	—		
		Deep sleep mode	No peripheral operation*7	ICLK = 32.768 kHz		1.7	—		
			All peripheral operation: Normal*8	ICLK = 32.768 kHz		3.9	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. Clock supply to the peripheral functions is stopped. The clock source is HOCO. FCLK and PCLK are set to divided by 64.
Note 3. Clocks are supplied to the peripheral functions. The clock source is HOCO. FCLK and PCLK are set to the same frequency as ICLK.
Note 4. Values when VCC = 3.3 V.
Note 5. Clock supply to the peripheral functions is stopped. The clock source is the main oscillation circuit when ICLK = 12 MHz and HOCO when ICLK = 8 or 1 MHz. FCLK and PCLK are set to divided by 64.
Note 6. Clocks are supplied to the peripheral functions. The clock source is the main oscillation circuit when ICLK = 12 MHz and HOCO when ICLK = 8 or 1 MHz. FCLK and PCLK are set to the same frequency as ICLK.
Note 7. Clock supply to the peripheral functions is stopped. The clock source is the sub-clock oscillator. FCLK and PCLK are set to divided by 64.
Note 8. Clocks are supplied to the peripheral functions. The clock source is the sub-clock oscillator. FCLK and PCLK are set to the same frequency as ICLK.
Note 9. Values when the MSTPCRA.MSTPA17 bit (12-bit A/D converter module stop bit) is set to “transition to the module stop state is made”.



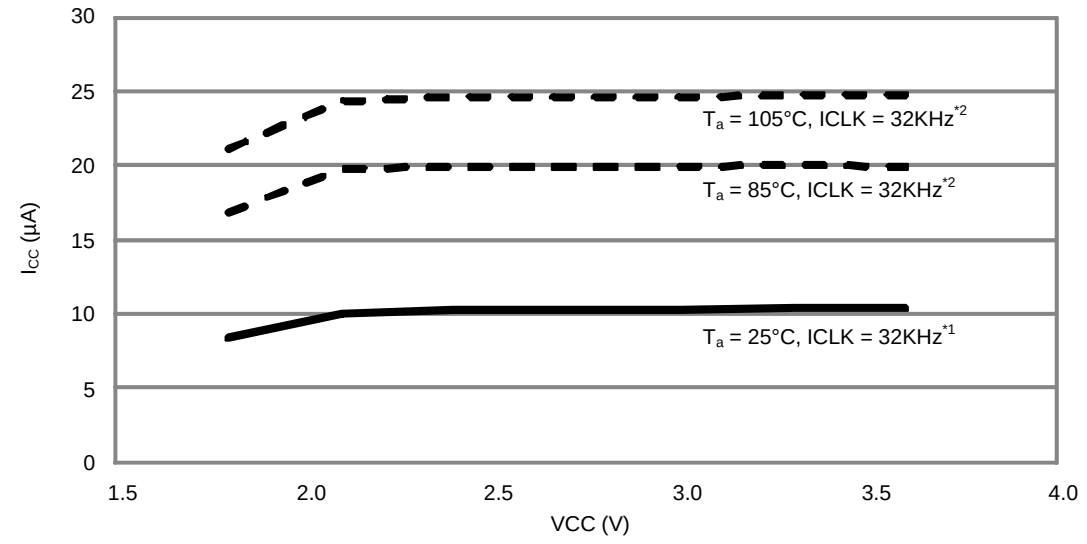
Note 1. All peripheral operation is normal. Average value of the tested middle samples during product evaluation
Note 2. All peripheral operation is maximum. Average value of the tested upper-limit samples during product evaluation.

Figure 5.1 Voltage Dependency in High-Speed Operating Mode (Reference Data)



Note 1. All peripheral operation is normal. Average value of the tested middle samples during product evaluation
Note 2. All peripheral operation is maximum. Average value of the tested upper-limit samples during product evaluation.

Figure 5.2 Voltage Dependency in Middle-Speed Operating Mode (Reference Data)



Note 1. All peripheral operation is normal. Average value of the tested middle samples during product evaluation
Note 2. All peripheral operation is maximum. Average value of the tested upper-limit samples during product evaluation.

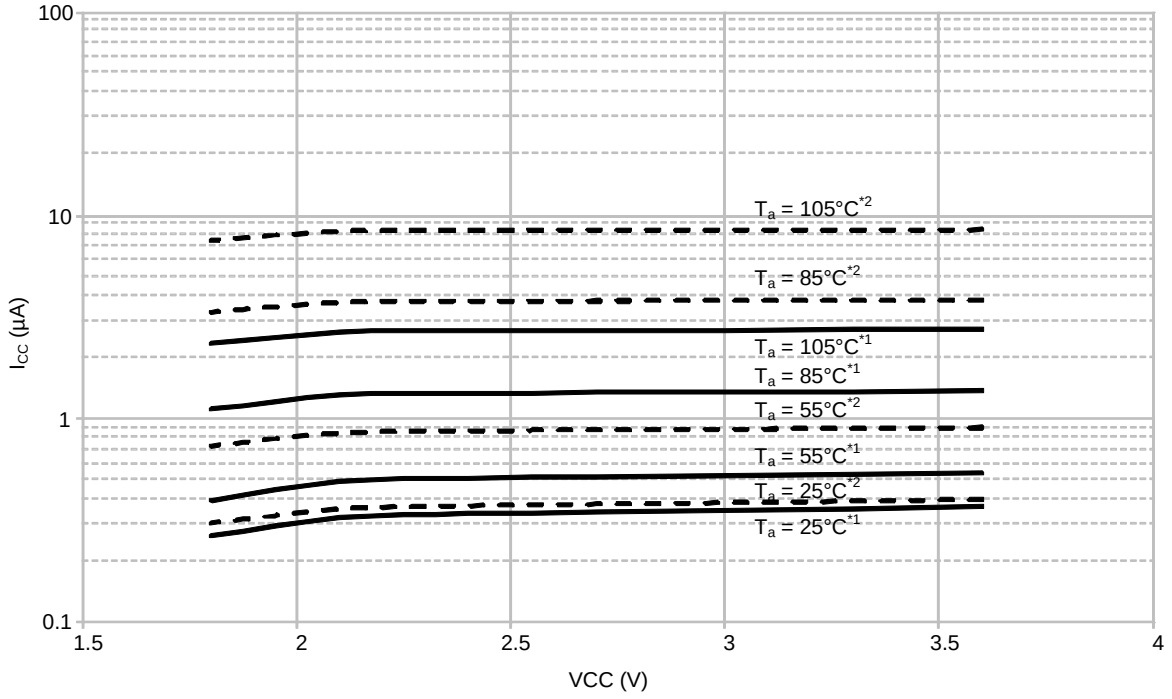
Figure 5.3 Voltage Dependency in Low-Speed Operating Mode (Reference Data)

Table 5.8 DC Characteristics (6)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

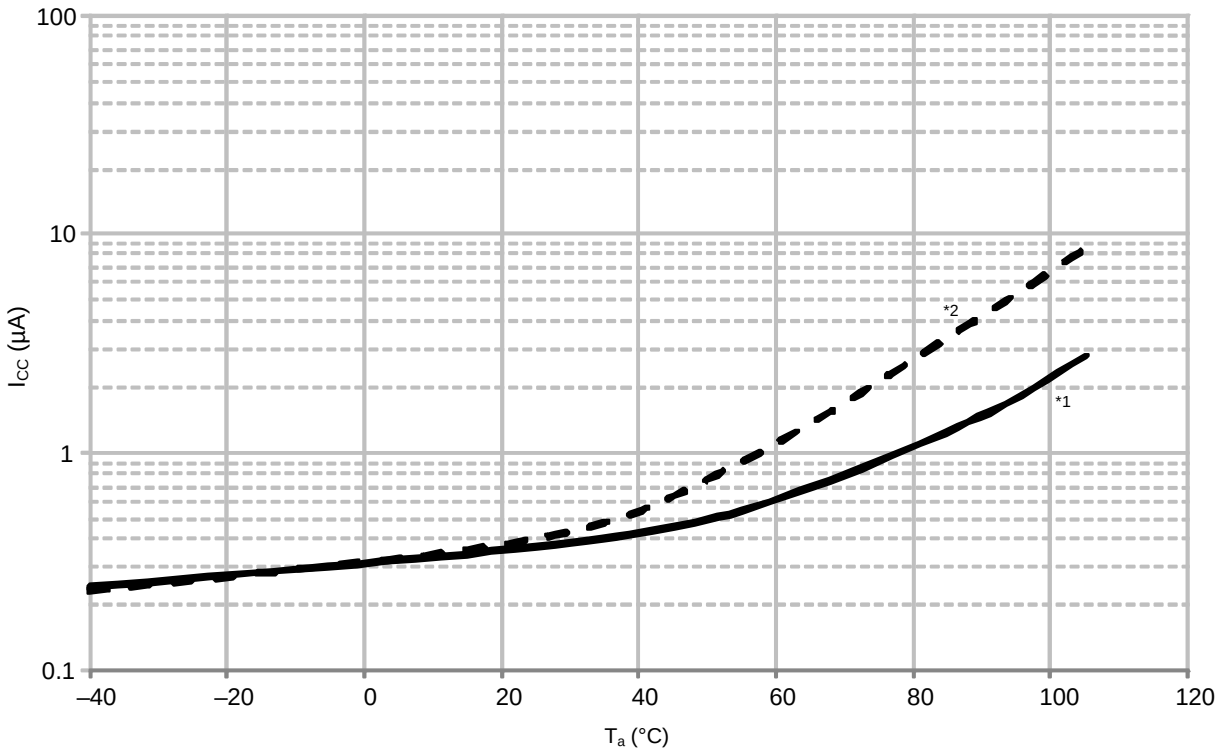
Item			Symbol	Typ.*3	Max.	Unit	Test Conditions
Supply current*1	Software standby mode*2	T_a = 25°C	I_{CC}	0.35	0.53	µA	
		T_a = 55°C		0.54	1.17		
		T_a = 85°C		1.38	5.2		
		T_a = 105°C		2.8	11.4		
	Increment for RTC operation*4			0.31	—		RCR3.RTCDV[2:0] = 010b
				1.09	—		RCR3.RTCDV[2:0] = 100b
	Increment for IWDT operation			0.37	—		

Note 1. Supply current values are with all output pins unloaded and all input pull-up MOSs in the off state.
Note 2. The IWDT and LVD are stopped.
Note 3. VCC = 3.3 V.
Note 4. Includes the oscillation circuit.



Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.4 Voltage Dependency in Software Standby Mode (Reference Data)



Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.5 Temperature Dependency in Software Standby Mode (Reference Data)

Table 5.9 DC Characteristics (7)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V

Item	Symbol	Typ.	Max.	Unit	Test Conditions
Permissible total consumption power*1	Pd	—	300	mW	D version (T_a = -40 to 85°C)
		—	105		G version (T_a = -40 to 105°C)*2

Note 1. Total power dissipated by the entire chip (including output currents).
Note 2. Please contact Renesas Electronics sales office for derating under T_a = +85°C to 105°C. Derating is the systematic reduction of load for the sake of improved reliability.

Table 5.10 DC Characteristics (8)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.*2	Max.	Unit	Test Conditions
Analog power supply current	During A/D conversion (at high-speed conversion)	I_{AVCC}	—	0.7	1.2	mA	
	Waiting for A/D conversion (all units)		—	—	0.3	μA	
Reference power supply current	During A/D conversion (at high-speed conversion)	I_{REFH0}	—	25	52	μA	
	Waiting for A/D conversion (all units)		—	—	60	nA	
Temperature sensor*1		I_{TEMP}	—	75	—	μA	
LDV1, 2	Per channel	I_{LVD}	—	0.15	—	μA	

Note 1. Current consumed by the power supply (VCC).
Note 2. When VCC = AVCC0 = 3.3 V.

Table 5.11 DC Characteristics (9)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RAM standby voltage	V_{RAM}	1.8	—	—	V	

Table 5.12 DC Characteristics (10)

Conditions: 0 V ≤ VCC ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Power-on VCC rising gradient	At normal startup*1	SrVCC	0.02	—	20	ms/V	
	During fast startup time*2		0.02	—	2		
	Voltage monitoring 1 reset enabled at startup*3, *4		0.02	—	—		

Note: When powering on AVCC0 and VCC, power them on at the same time or VCC first.
Note 1. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.
Note 2. When OFS1.(STUPLVD1REN, FASTSTUP) = 10b.
Note 3. When OFS1.STUPLVD1REN = 0.
Note 4. Turn on the power supply voltage according to the normal startup rising gradient because the register settings set by OFS1 are not read in boot mode.

Table 5.13 DC Characteristics (11)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C
The ripple voltage must meet the allowable ripple frequency $f_{r(VCC)}$ within the range between the VCC upper limit (3.6 V) and lower limit (1.8 V).
When VCC change exceeds VCC ±10%, the allowable voltage change rising/falling gradient dt/dVCC must be met.

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Allowable ripple frequency	$f_{r\ (VCC)}$	—	—	10	kHz	Figure 5.6 $V_{r\ (VCC)}$ ≤ VCC × 0.2
		—	—	1	MHz	Figure 5.6 $V_{r\ (VCC)}$ ≤ VCC × 0.08
		—	—	10	MHz	Figure 5.6 $V_{r\ (VCC)}$ ≤ VCC × 0.06
Allowable voltage change rising/ falling gradient	dt/dVCC	1.0	—	—	ms/V	When VCC change exceeds VCC ±10%

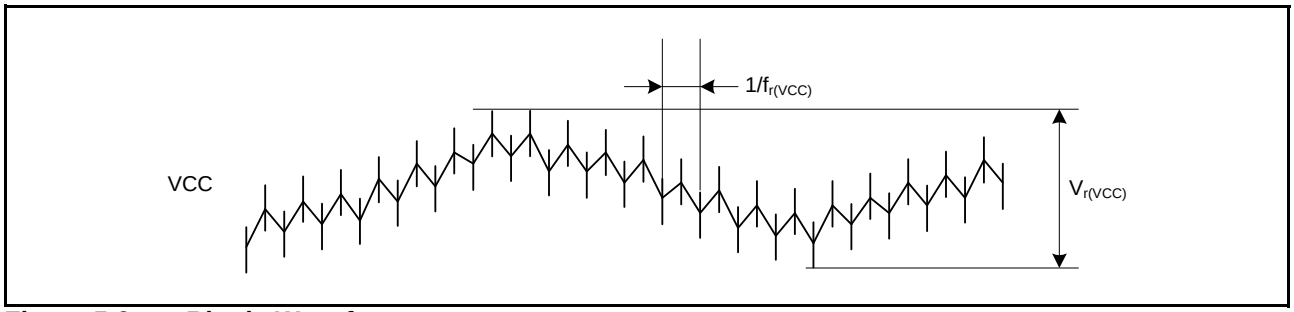


Figure 5.6 Ripple Waveform

Table 5.14 DC Characteristics (12)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Permissible error of VCL pin external capacitance	C_{VCL}	1.4	4.7	7.0	µF	

Note: The recommended capacitance is 4.7 µF. Variations in connected capacitors should be within the above range.

Table 5.15 Permissible Output Currents (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V,
T_a = –40 to +85°C (D version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	2.4	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		30	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		30	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		30	
	Total of all output pins		60	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		–10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		–15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

Table 5.16 Permissible Output Currents (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V,
T_a = –40 to +105°C (G version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	1.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		20	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		20	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		20	
	Total of all output pins		40	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		–10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		–15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

Table 5.17 Output Voltage (1)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +10°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for RIIC, ports P40 to P44, P46, ports PJ6, PJ7)		V_{OL}	—	0.6	V	I_{OL} = 3.0 mA
				—	0.4		I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports PJ6, PJ7			—	0.4		I_{OL} = 0.4 mA
	RIIC pins	Standard mode		—	0.4		I_{OL} = 3.0 mA
		Fast mode		—	0.6		I_{OL} = 6.0 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)		V_{OH}	VCC – 0.5	—	V	I_{OH} = –2.0 mA
	Ports P40 to P44, P46, ports PJ6, PJ7			AVCC0 – 0.5	—		I_{OH} = –0.1 mA

Table 5.18 Output Voltage (2)

Conditions: 1.8 V ≤ VCC ≤ 2.7 V, 1.8 V ≤ AVCC0 ≤ 2.7 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)	V_{OL}	—	0.6	V	I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports PJ6, PJ7		—	0.4		I_{OL} = 0.4 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)	V_{OH}	VCC – 0.5	—	V	I_{OH} = –1.0 mA
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 – 0.5	—		I_{OH} = –0.1 mA

5.2.1 Standard I/O Pin Output Characteristics (1)

Figure 5.7 to Figure 5.10 show the characteristics of general ports (except for the RIIC output pin, ports P40 to P44, P46, ports PJ6, PJ7).

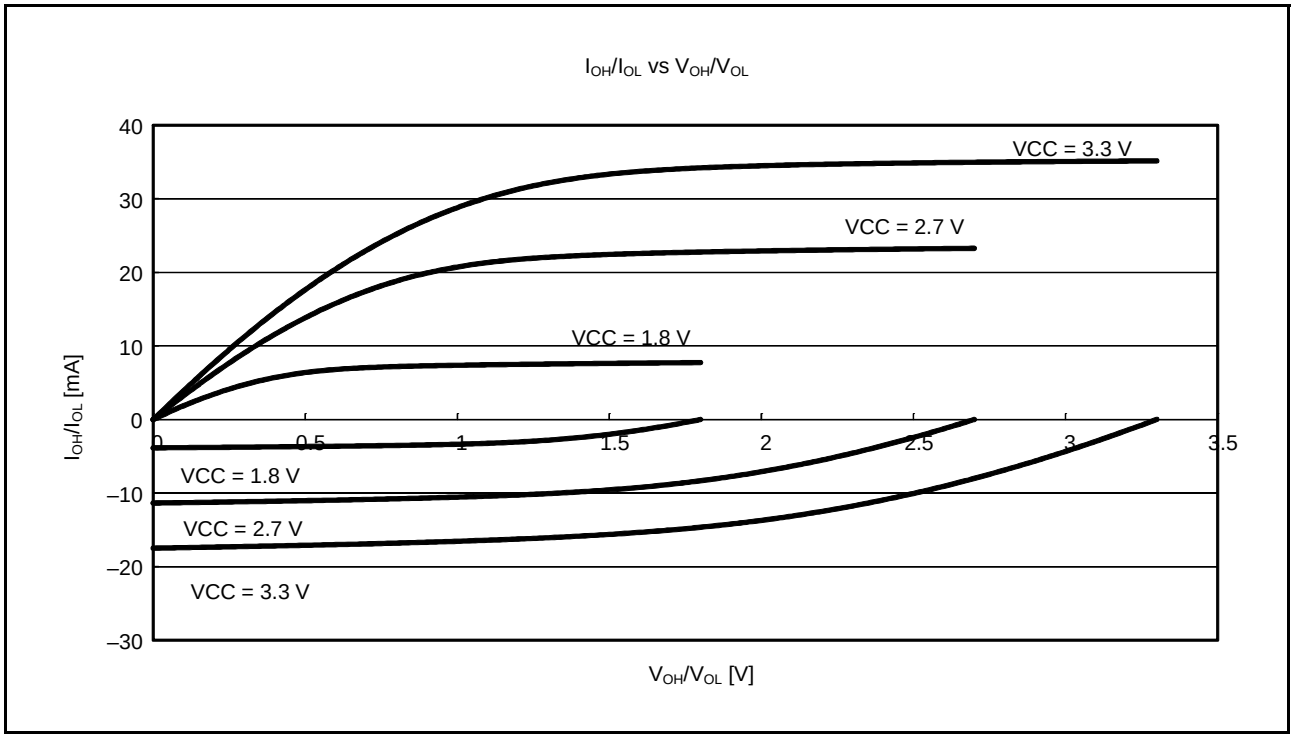


Figure 5.7 V_{OH}/V_{OL} and I_{OH}/I_{OL} Voltage Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at T_a = 25°C (Reference Data)

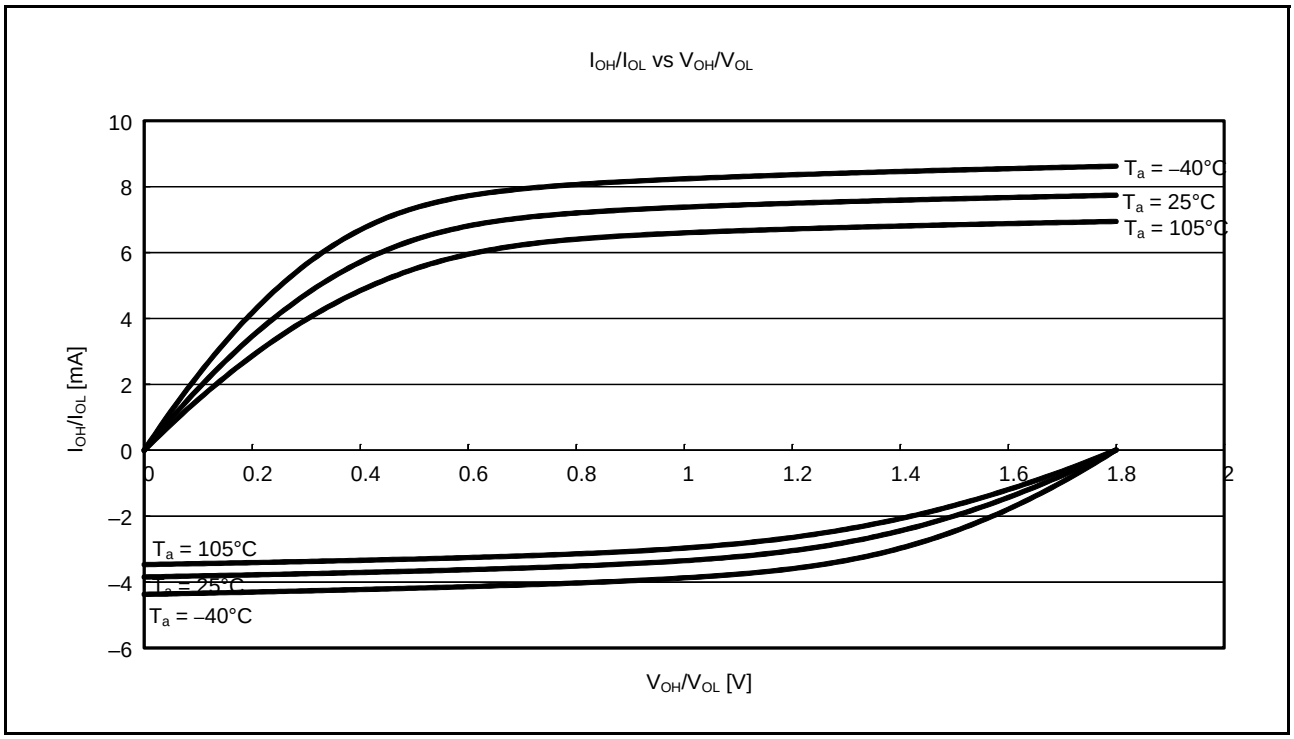


Figure 5.8 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 1.8 V (Reference Data)

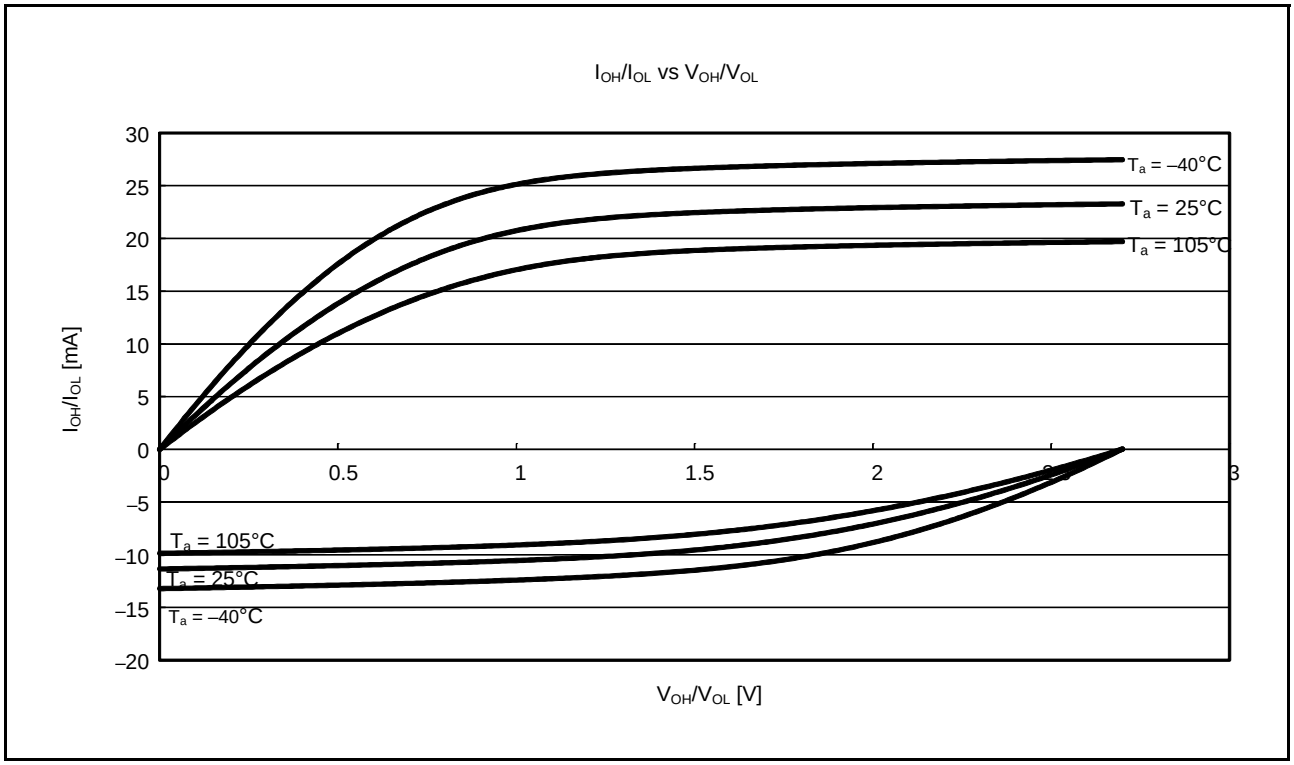


Figure 5.9 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 2.7 V (Reference Data)

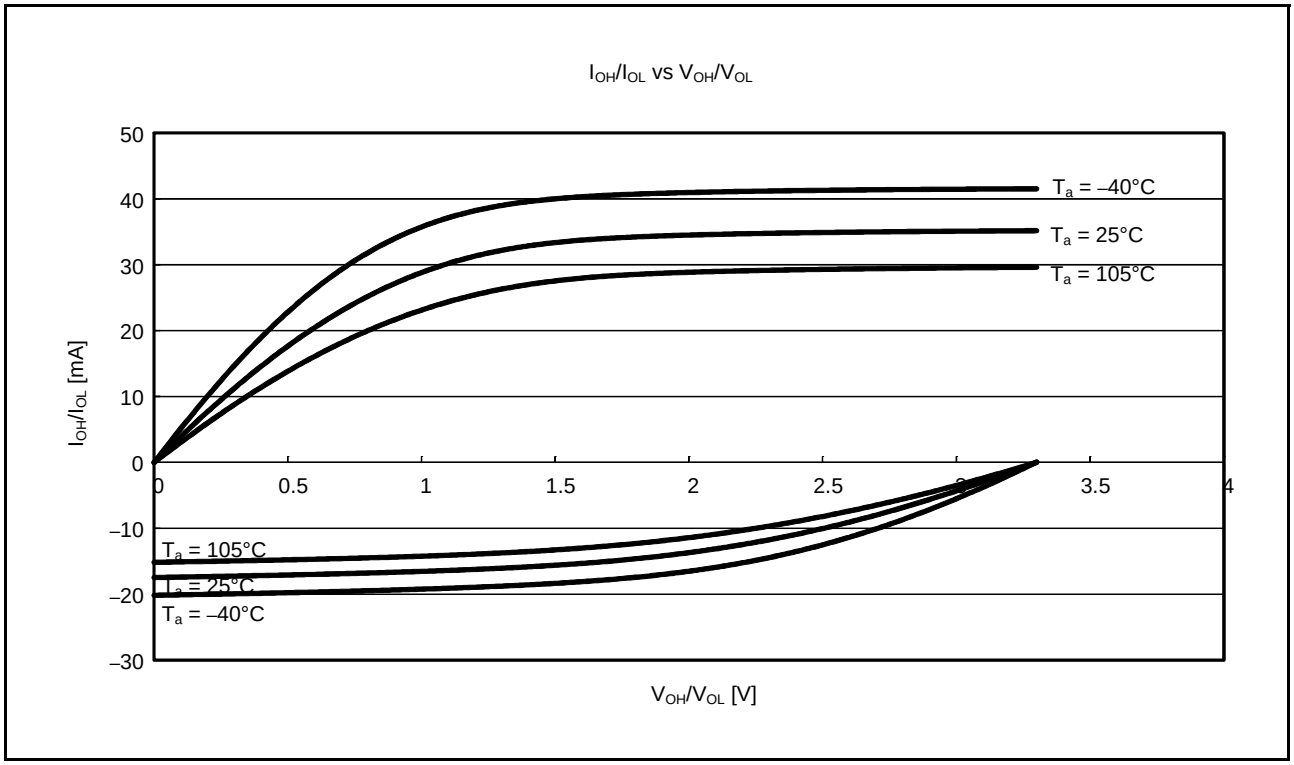


Figure 5.10 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 3.3 V (Reference Data)

5.2.2 Standard I/O Pin Output Characteristics (2)

Figure 5.11 to Figure 5.13 show the characteristics of the RIIC output pin.

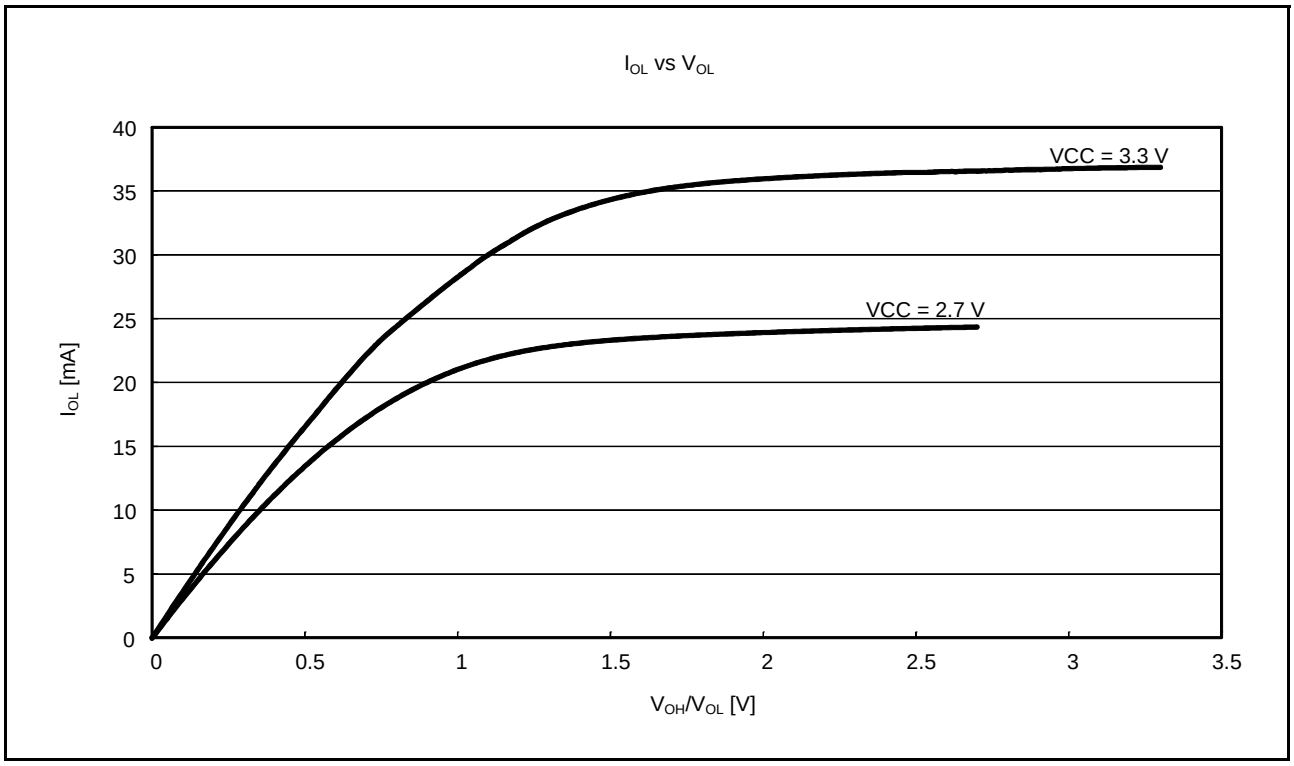


Figure 5.11 V_{OL} and I_{OL} Voltage Characteristics of RIIC Output Pin at T_a = 25°C (Reference Data)

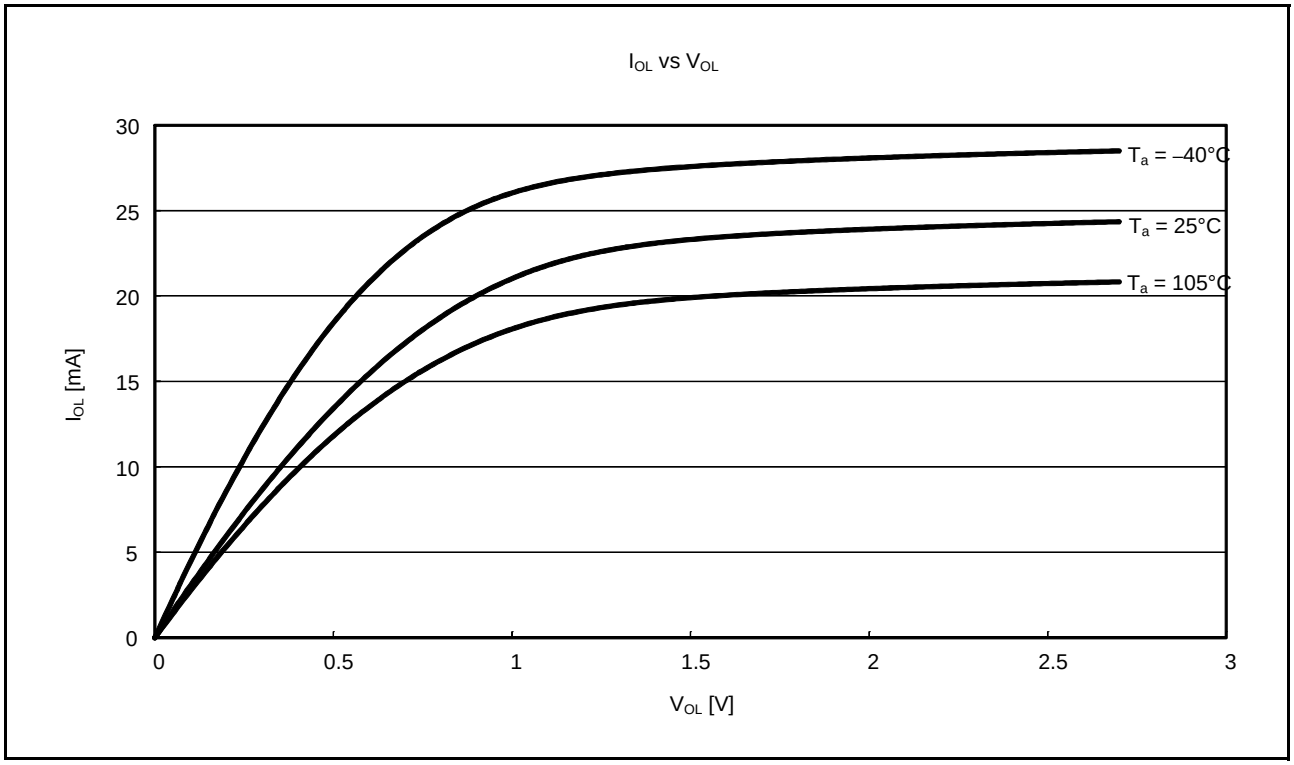


Figure 5.12 V_{OL} and I_{OL} Temperature Characteristics of RIIC Output Pin at VCC = 2.7 V (Reference Data)

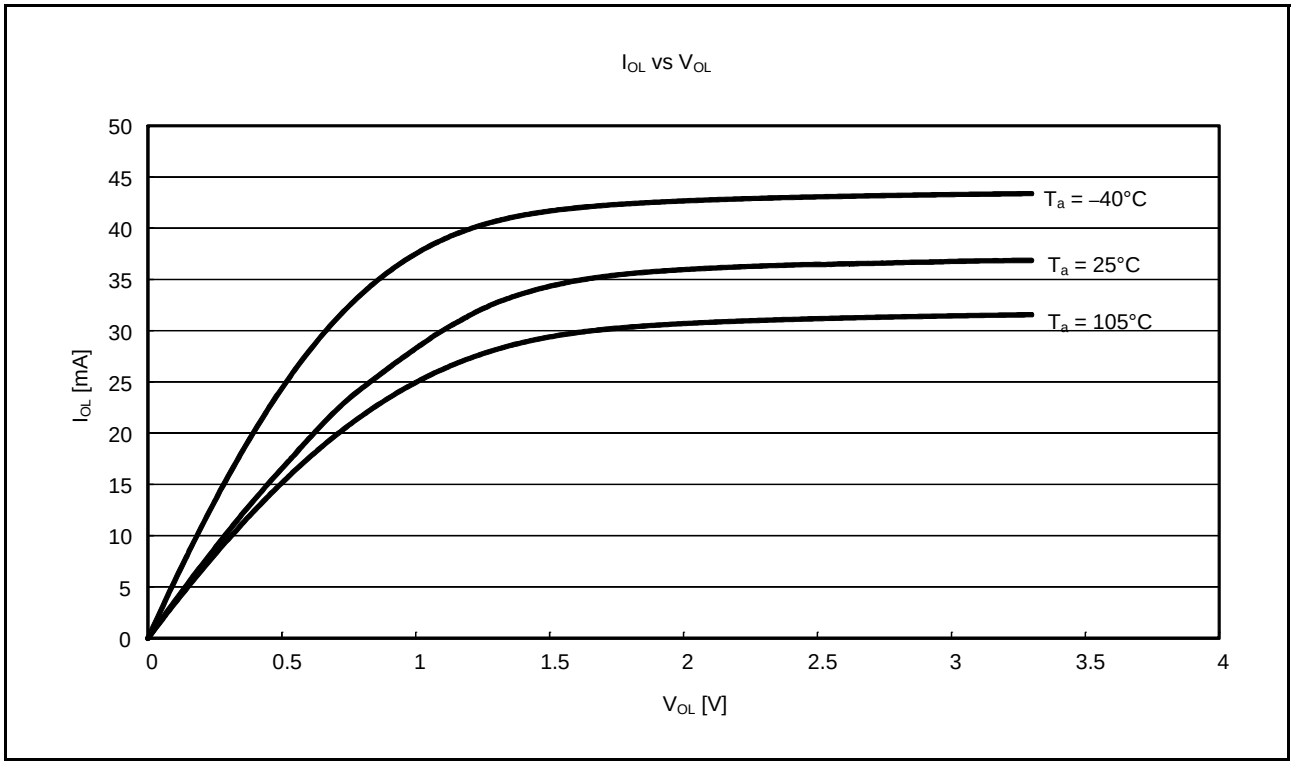


Figure 5.13 V_{OL} and I_{OL} Temperature Characteristics of RIIC Output Pin at VCC = 3.3 V (Reference Data)

5.2.3 Standard I/O Pin Output Characteristics (3)

Figure 5.14 to Figure 5.17 show the characteristics ports P40 to P44, P46, ports PJ6, PJ7.

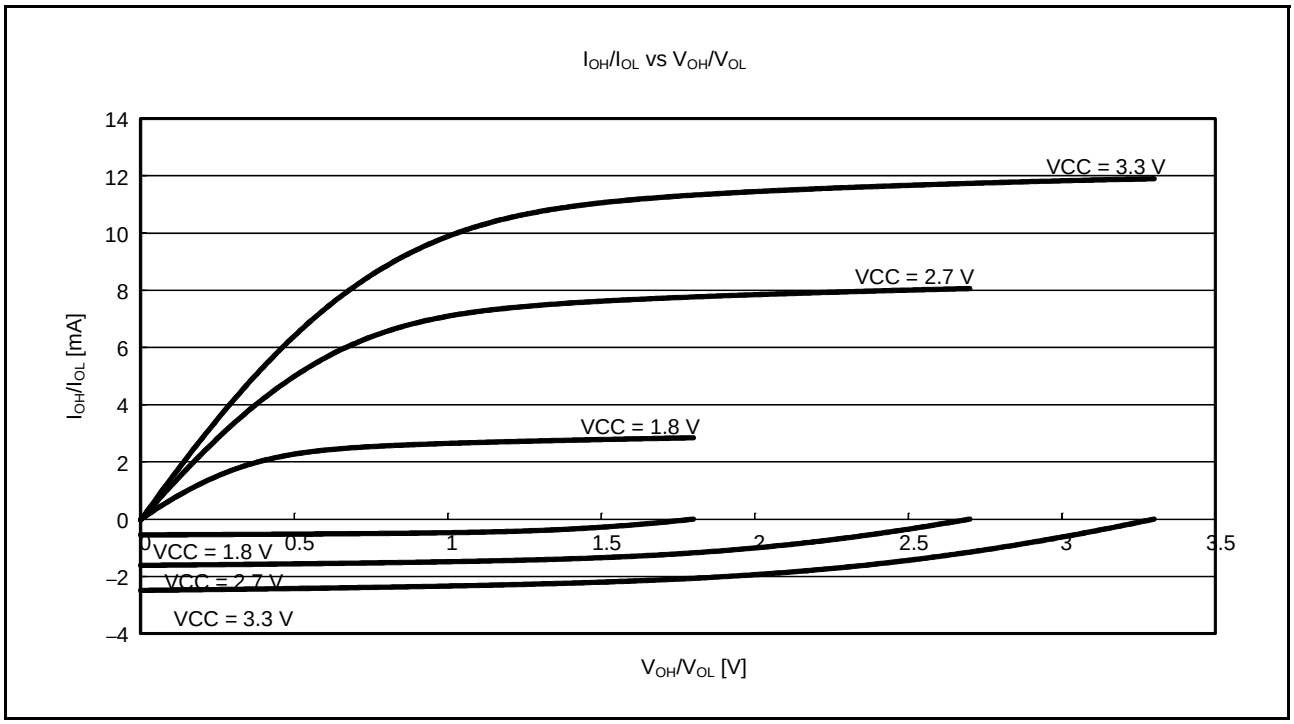


Figure 5.14 V_{OH}/V_{OL} and I_{OH}/I_{OL} Voltage Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at T_a = 25°C (Reference Data)

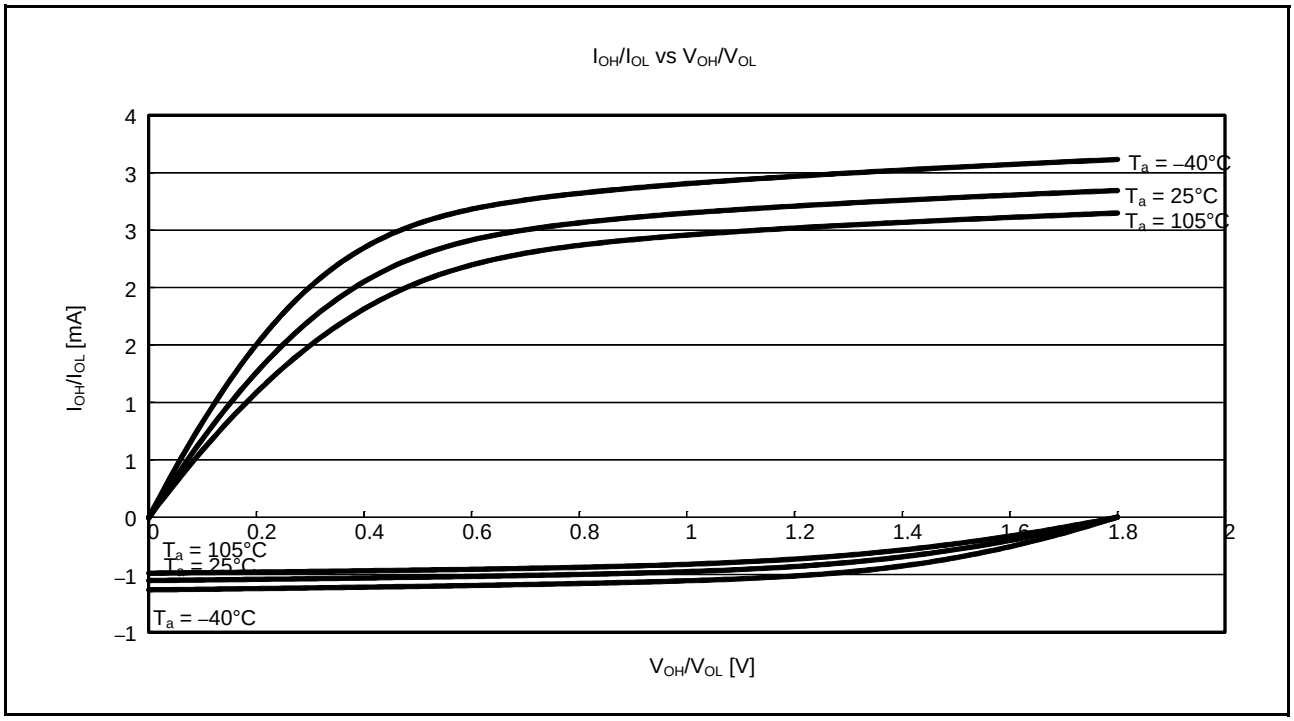


Figure 5.15 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 1.8 V (Reference Data)

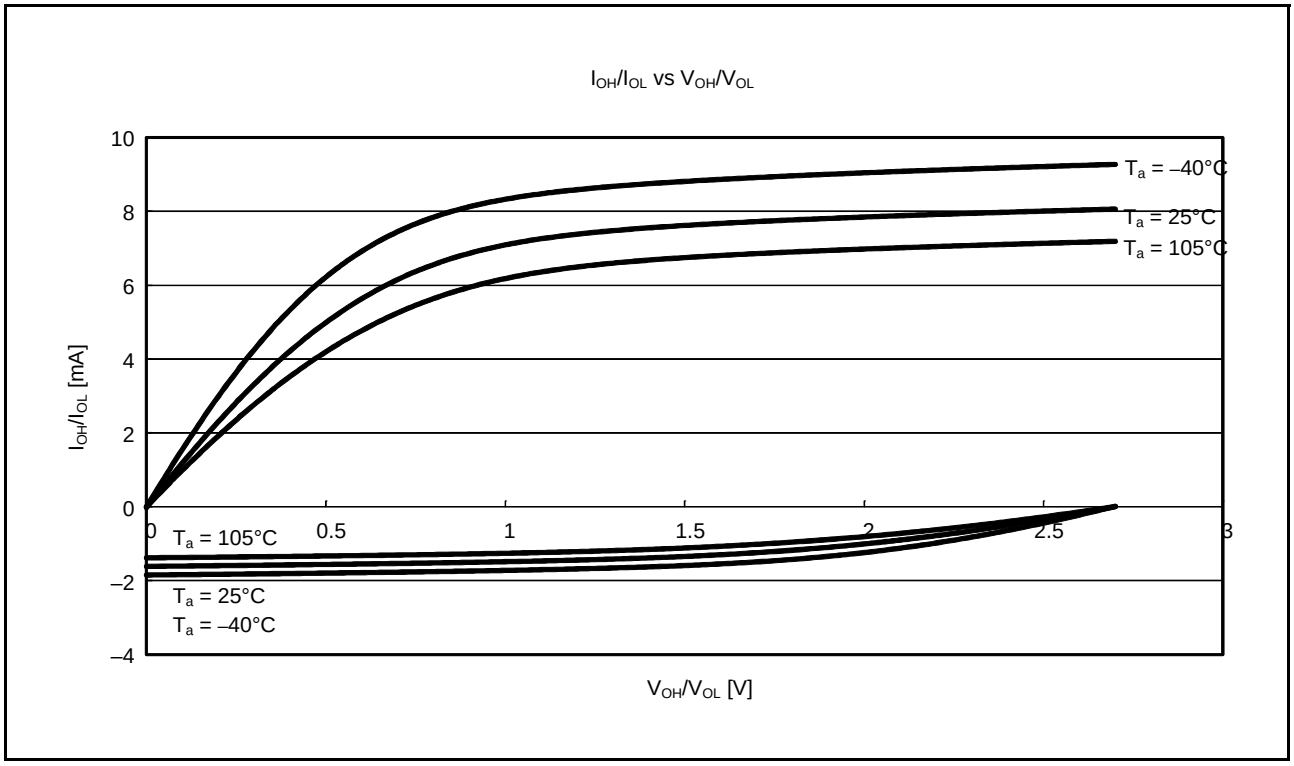


Figure 5.16 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 2.7 V (Reference Data)

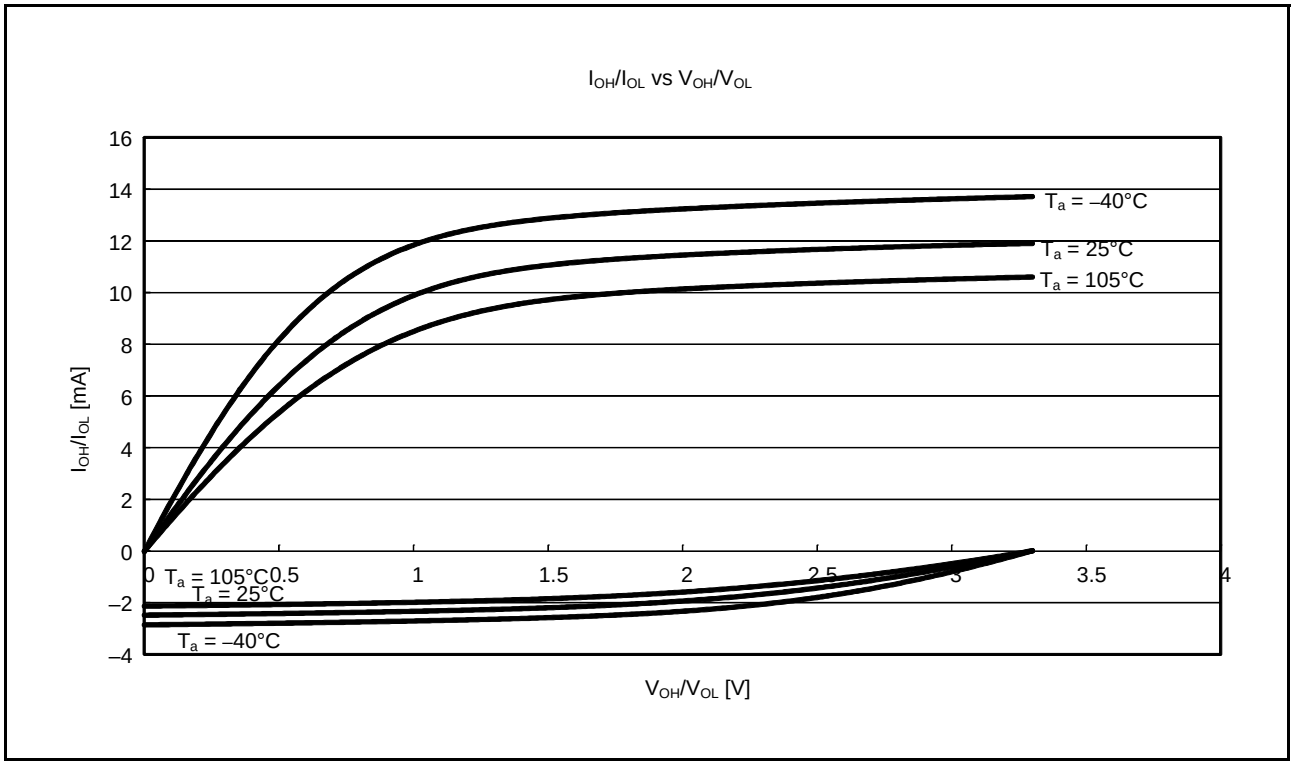


Figure 5.17 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 3.3 V (Reference Data)

5.3 AC Characteristics

5.3.1 Clock Timing

Table 5.19 Operation Frequency Value (High-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	16	32	MHz
	FlashIF clock (FCLK)*1, *2		8	16	32	
	Peripheral module clock (PCLKB)		8	16	32	
	Peripheral module clock (PCLKD)*3		8	16	32	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.

Table 5.20 Operation Frequency Value (Middle-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	12	12	MHz
	FlashIF clock (FCLK)*1, *2		8	12	12	
	Peripheral module clock (PCLKB)		8	12	12	
	Peripheral module clock (PCLKD)*3		8	12	12	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.

Table 5.21 Operation Frequency Value (Low-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	32.768			kHz
	FlashIF clock (FCLK)*1		32.768			
	Peripheral module clock (PCLKB)		32.768			
	Peripheral module clock (PCLKD)*2		32.768			

Note 1. Programming and erasing the flash memory is impossible.
Note 2. The A/D converter cannot be used.

Table 5.22 Clock Timing

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
XTAL external clock input cycle time		t_{Xcyc}	50	—	—	ns	Figure 5.18
XTAL external clock input high pulse width		t_{XH}	20	—	—	ns	
XTAL external clock input low pulse width		t_{XL}	20	—	—	ns	
XTAL external clock rising time		t_{Xr}	—	—	5	ns	
XTAL external clock falling time		t_{Xf}	—	—	5	ns	
XTAL external clock input wait time*1		t_{EXWT}	0.5	—	—	μs	
Main clock oscillator oscillation frequency	2.4 ≤ VCC ≤ 3.6	f_{MAIN}	1	—	20	MHz	
	1.8 ≤ VCC < 2.4		1	—	8		
Main clock oscillation stabilization time (crystal)*2		$t_{MAINOSC}$	—	3	—	ms	Figure 5.20
Main clock oscillation stabilization time (ceramic resonator)*2		$t_{MAINOSC}$	—	50		μs	
LOCO clock oscillation frequency		f_{LOCO}	3.44	4.0	4.56	MHz	
LOCO clock oscillation stabilization time		t_{LOCO}	—	—	0.5	μs	Figure 5.21
IWDT-dedicated clock oscillation frequency		f_{ILOCO}	12.75	15	17.25	kHz	
IWDT-dedicated clock oscillation stabilization time		t_{ILOCO}	—	—	50	μs	Figure 5.19
HOCO clock oscillation frequency		f_{HOCO}	31.52	32	32.48	MHz	T_a = –40 to 85°C
			31.68	32	32.32		T_a = –20 to 85°C
			31.36	32	32.64		T_a = –40 to 105°C
HOCO clock oscillation stabilization time		t_{HOCO2}	—	—	56	μs	Figure 5.23
Sub-clock oscillator oscillation frequency*4		f_{SUB}	—	32.768	—	kHz	
Sub-clock oscillation stabilization time*3		t_{SUBOSC}	—	0.5	—	s	Figure 5.24

Note 1. Time until the clock can be used after the main clock oscillator stop bit (MOSCCR.MOSTP) is set to 0 (operating) when the external clock is stable.

Note 2. Reference values when an 8-MHz oscillator is used.
When specifying the main clock oscillator stabilization time, set the MOSCWTCR register with a stabilization time value that is equal to or greater than the oscillator-manufacturer-recommended value.
After changing the setting of the MOSCCR.MOSTP bit so that the main clock oscillator operates, read the OSCOVFSR.MOOVF flag to confirm that is has become 1, and then start using the main clock.

Note 3. After changing the setting of the SOSCCR.SOSTP bit or RCR3.RTCEN bit so that the sub-clock oscillator operates, only start using the sub-clock after the sub-clock oscillation stabilization wait time that is equal to or greater than the oscillator-manufacturer-recommended value has elapsed.
Reference value when a 32.768-kHz resonator is used.

Note 4. Only 32.768 kHz can be used.

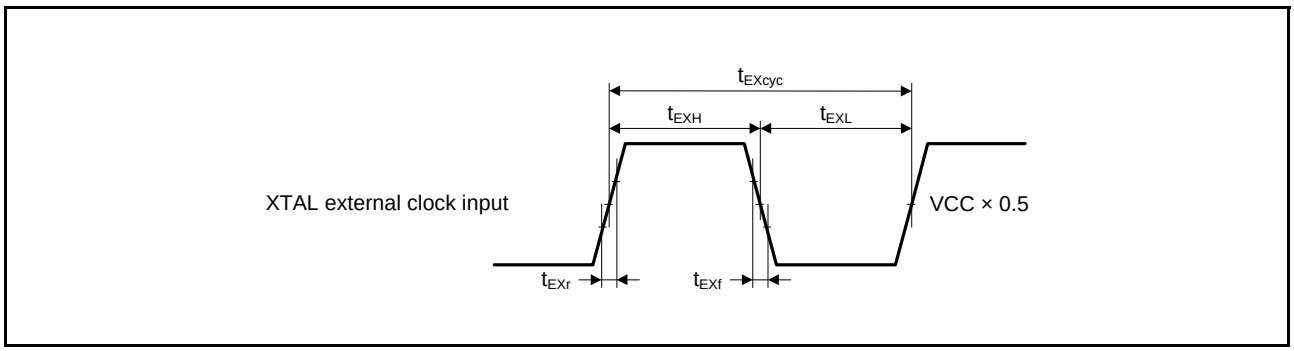


Figure 5.18 XTAL External Clock Input Timing

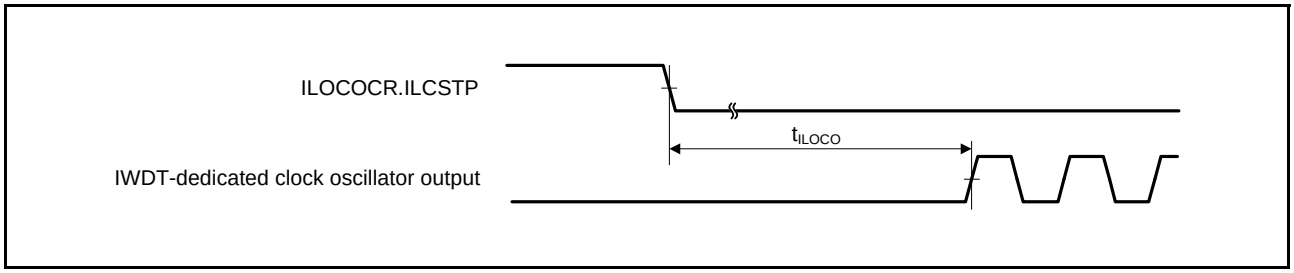


Figure 5.19 IWDT-Dedicated Clock Oscillation Start Timing

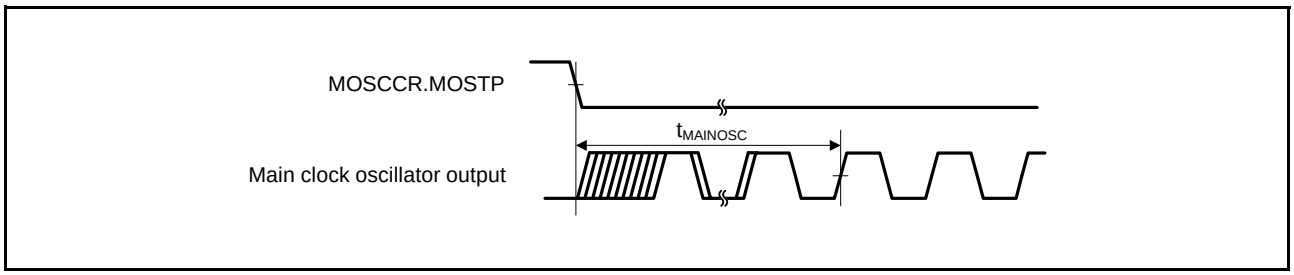


Figure 5.20 Main Clock Oscillation Start Timing

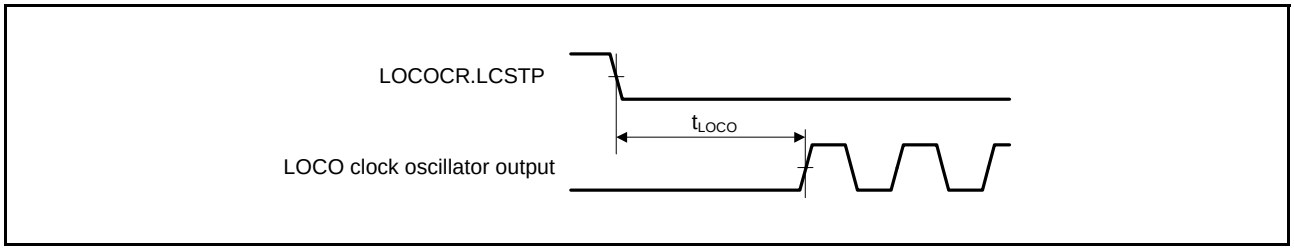


Figure 5.21 LOCO Clock Oscillation Start Timing

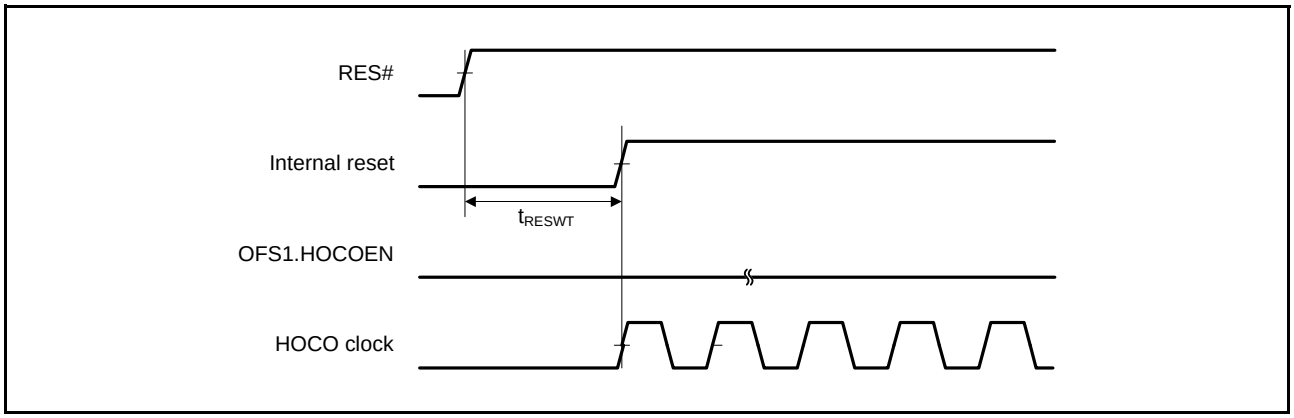


Figure 5.22 HOCO Clock Oscillation Start Timing (After Reset is Canceled by Setting OFS1.HOCOEN Bit to 0)

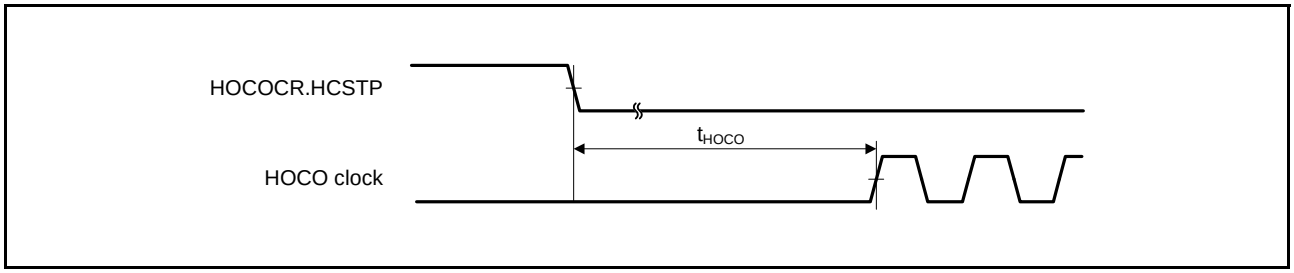


Figure 5.23 HOCO Clock Oscillation Start Timing (Oscillation is Started by Setting HOCOCR.HCSTP Bit)

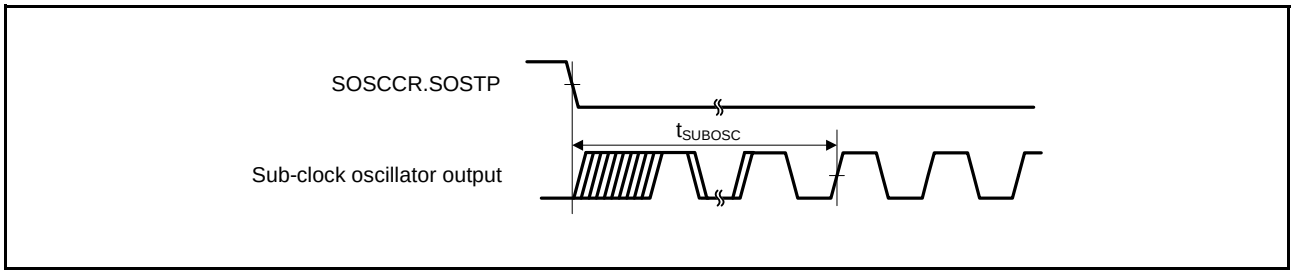


Figure 5.24 Sub-Clock Oscillation Start Timing

5.3.2 Reset Timing

Table 5.23 Reset Timing

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RES# pulse width	At power-on	t_{RESWP}	3	—	—	ms	Figure 5.25
	Other than above	t_{RESW}	30	—	—	μs	Figure 5.26
Wait time after RES# cancellation (at power-on)	At normal startup*1	t_{RESWT}	—	8.5	—	ms	Figure 5.25
	During fast startup time*2	t_{RESWT}	—	560	—	μs	
Wait time after RES# cancellation (during powered-on state)		t_{RESWT}	—	114	—	μs	Figure 5.26
Independent watchdog timer reset period		t_{RESWIW}	—	1	—	IWDT clock cycle	Figure 5.27
Software reset period		t_{RESWSW}	—	1	—	ICLK cycle	
Wait time after independent watchdog timer reset cancellation*3		t_{RESW2}	—	300	—	μs	
Wait time after software reset cancellation		t_{RESW2}	—	168	—	μs	

Note 1. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.
Note 2. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.
Note 3. When IWDTCR.CKS[3:0] = 0000b.

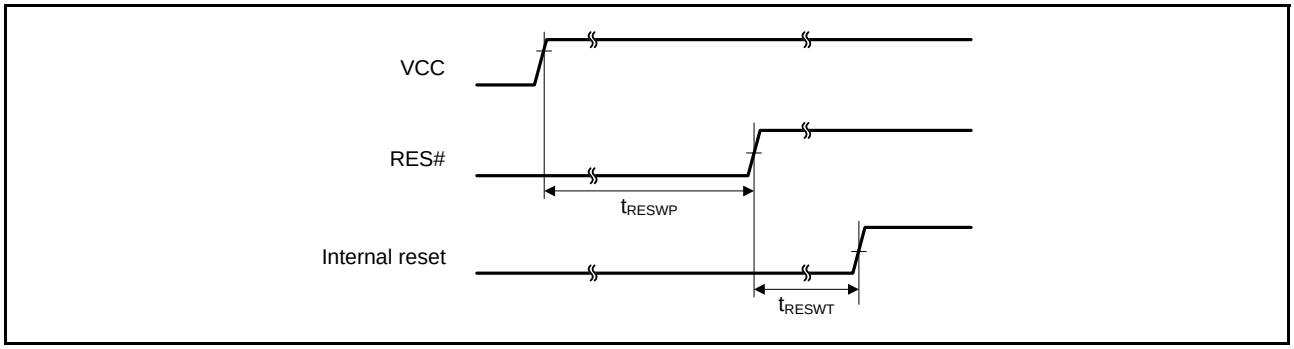


Figure 5.25 Reset Input Timing at Power-On

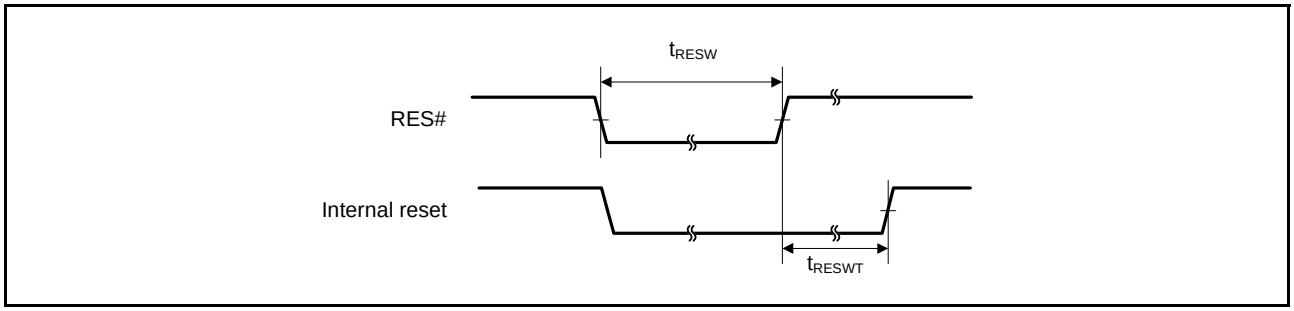


Figure 5.26 Reset Input Timing (1)

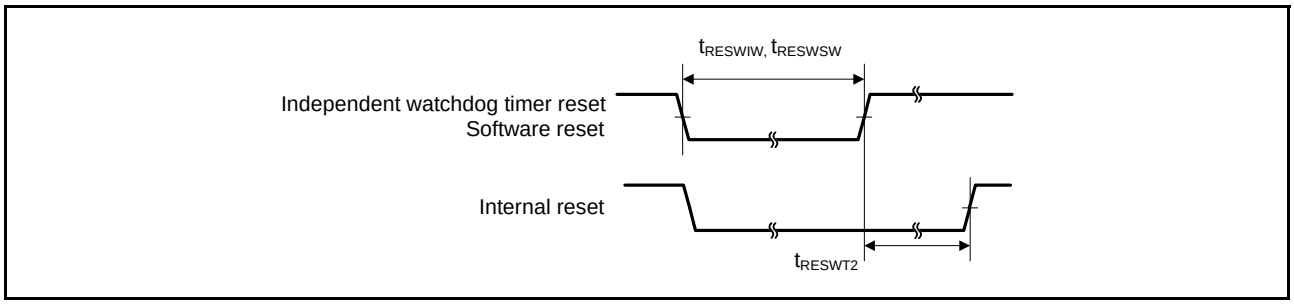


Figure 5.27 Reset Input Timing (2)

5.3.3 Timing of Recovery from Low Power Consumption Modes

Table 5.24 Timing of Recovery from Low Power Consumption Modes (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	High-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.28
		External clock input to main clock oscillator	Main clock oscillator operating*3	t_{SBYEX}	—	35	50	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	650	800	µs	
		HOCO clock oscillator operating*4		t_{SBYHO}	—	40	55	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	40	55	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.
Note 2. When the frequency of the crystal is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 3. When the frequency of the external clock is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 4. When the frequency of HOCO is 32 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.25 Timing of Recovery from Low Power Consumption Modes (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Middle-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.28
		External clock input to main clock oscillator	Main clock oscillator operating*3	t_{SBYEX}	—	3	4	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	600	750	µs	
		HOCO clock oscillator operating*4		t_{SBYHO}	—	40	50	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	4.8	7	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.
Note 2. When the frequency of the crystal is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 3. When the frequency of the external clock is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 4. When the frequency of HOCO is 8 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.26 Timing of Recovery from Low Power Consumption Modes (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Low-speed mode	Sub-clock oscillator operating	t_{SBYSC}	—	600	750	µs	Figure 5.28

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The sub-clock continues oscillating in software standby mode during low-speed mode.

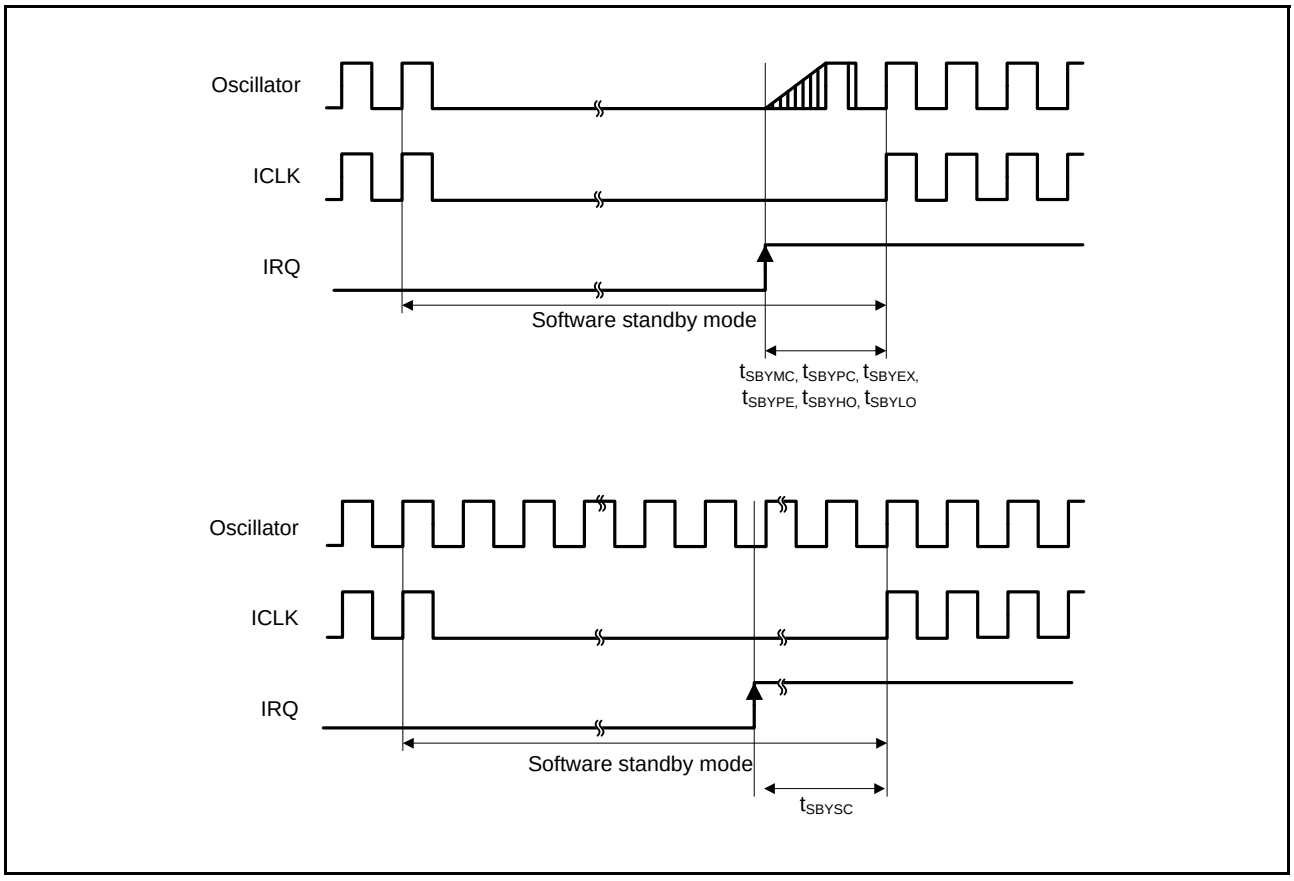


Figure 5.28 Software Standby Mode Cancellation Timing

Table 5.27 Timing of Recovery from Low Power Consumption Modes (4)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from deep sleep mode*1	High-speed mode*2	t_{DSLP}	—	2	3.5	µs	
	Middle-speed mode*3	t_{DSLP}	—	3	4	µs	
	Low-speed mode*4	t_{DSLP}	—	400	500	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. Oscillators continue oscillating in deep sleep mode.
Note 2. When the frequency of the system clock is 32 MHz.
Note 3. When the frequency of the system clock is 12 MHz.
Note 4. When the frequency of the system clock is 32.768 kHz.

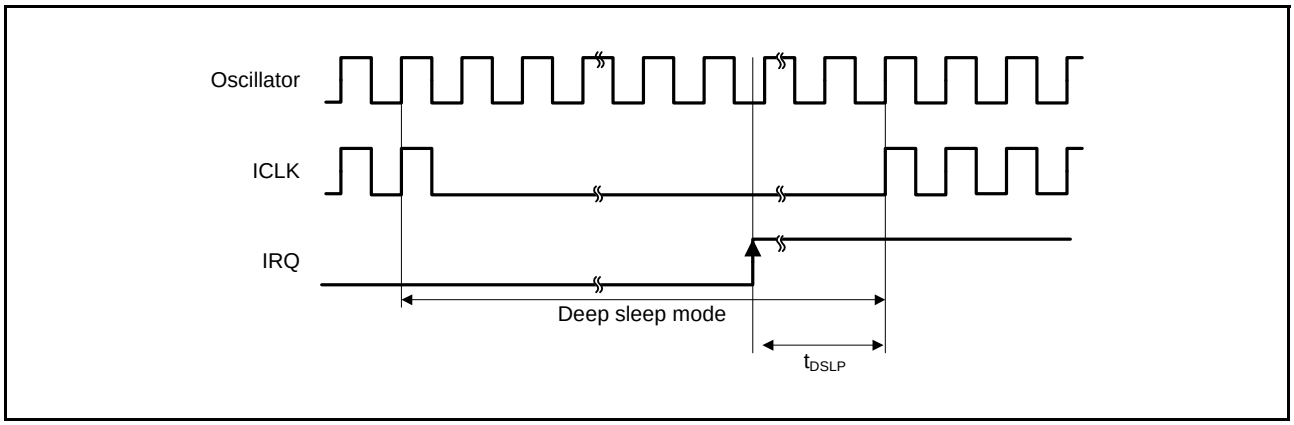


Figure 5.29 Deep Sleep Mode Cancellation Timing

Table 5.28 Timing of Recovery from Low Power Consumption Modes (5) Operating Mode Transition Time

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = -40 to +105°C

Mode before Transition	Mode after Transition	ICLK Frequency	Transition Time			Unit
			Min.	Typ.	Max.	
High-speed operating mode	Middle-speed operating mode	8 MHz	—	10	—	µs
Middle-speed operating mode	High-speed operating mode	8 MHz	—	37.5	—	µs
Low-speed operating mode	Middle-speed operating mode, high-speed operating mode	32.768 kHz	—	213.62	—	µs
Middle-speed operating mode, high-speed operating mode	Low-speed operating mode	32.768 kHz	—	183.11	—	µs

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.

5.3.4 Control Signal Timing

Table 5.29 Control Signal Timing

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
NMI pulse width	t_{NMIW}	200	—	—	ns	NMI digital filter disabled (NMIFLTE.NFLTEN = 0)	t_{Pcyc} × 2 ≤ 200 ns
		t_{Pcyc} × 2*1	—	—			t_{Pcyc} × 2 > 200 ns
		200	—	—		NMI digital filter enabled (NMIFLTE.NFLTEN = 1)	t_{NMICK} × 3 ≤ 200 ns
		t_{NMICK} × 3.5*2	—	—			t_{NMICK} × 3 > 200 ns
IRQ pulse width	t_{IRQW}	200	—	—	ns	IRQ digital filter disabled (IRQFLTE0.FLTENi = 0)	t_{Pcyc} × 2 ≤ 200 ns
		t_{Pcyc} × 2*1	—	—			t_{Pcyc} × 2 > 200 ns
		200	—	—		IRQ digital filter enabled (IRQFLTE0.FLTENi = 1)	t_{IRQCK} × 3 ≤ 200 ns
		t_{IRQCK} × 3.5*3	—	—			t_{IRQCK} × 3 > 200 ns

Note: 200 ns minimum in software standby mode.
Note 1. t_{Pcyc} indicates the cycle of PCLKB.
Note 2. t_{NMICK} indicates the cycle of the NMI digital filter sampling clock.
Note 3. t_{IRQCK} indicates the cycle of the IRQi digital filter sampling clock (i = 0 to 7).

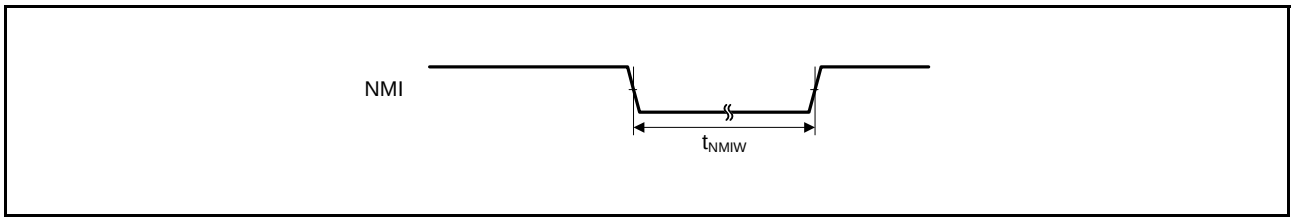


Figure 5.30 NMI Interrupt Input Timing

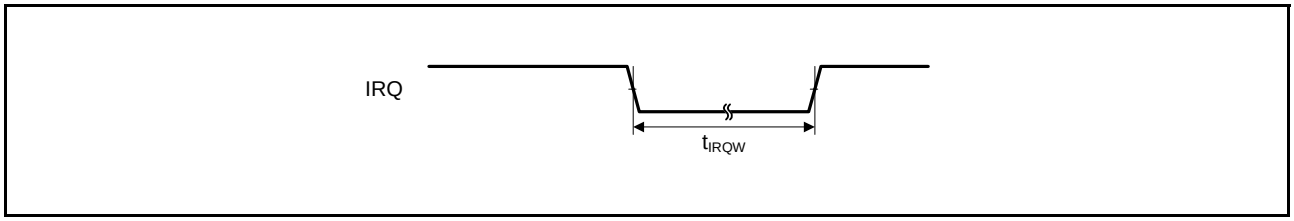


Figure 5.31 IRQ Interrupt Input Timing

5.3.5 Timing of On-Chip Peripheral Modules

Table 5.30 Timing of On-Chip Peripheral Modules (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Max.	Unit*1	Test Conditions
I/O ports	Input data pulse width			t_{PRW}	1.5	—	t_{Pcyc}	Figure 5.32
MTU2	Input capture input pulse width		Single-edge setting	t_{TICW}	1.5	—	t_{Pcyc}	Figure 5.33
			Both-edge setting		2.5	—		
	Timer clock pulse width		Single-edge setting	t_{TCKWH}, t_{TCKWL}	1.5	—	t_{Pcyc}	Figure 5.34
			Both-edge setting		2.5	—		
			Phase counting mode		2.5	—		
SCI	Input clock cycle		Asynchronous	t_{Scyc}	4	—	t_{Pcyc}	Figure 5.35
			Clock synchronous		6	—		
	Input clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time			t_{SCKr}	—	20	ns	
	Input clock fall time			t_{SCKf}	—	20	ns	
	Output clock cycle		Asynchronous	t_{Scyc}	16	—	t_{Pcyc}	Figure 5.36 C = 30 pF
			Clock synchronous		4	—		
	Output clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time			t_{SCKr}	—	20	ns	
	Output clock fall time			t_{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous		t_{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous	2.7 V or above		—	65	ns	
			1.8 V or above		—	100	ns	
	Receive data setup time (master)	Clock synchronous	2.7 V or above	t_{RXS}	65	—	ns	
			1.8 V or above		90	—	ns	
	Receive data setup time (slave)	Clock synchronous			40	—	ns	
	Receive data hold time	Clock synchronous		t_{RXH}	40	—	ns	
A/D converter	Trigger input pulse width			t_{TRGW}	1.5	—	t_{Pcyc}	Figure 5.37
CAC	CACREF input pulse width		$t_{Pcyc} \le t_{cac}$*2	t_{CACREF}	4.5 t_{cac} + 3 t_{Pcyc}	—	ns	
			$t_{Pcyc} > t_{cac}$*2		5 t_{cac} + 6.5 t_{Pcyc}			
CLKOUT	CLKOUT pin output cycle*4		VCC = 2.7 V or above	t_{Ccyc}	125	—	ns	
			VCC = 1.8 V or above		250			
	CLKOUT pin high pulse width*3		VCC = 2.7 V or above	t_{CH}	35	—	ns	
			VCC = 1.8 V or above		70			
	CLKOUT pin low pulse width*3		VCC = 2.7 V or above	t_{CL}	35	—	ns	
			VCC = 1.8 V or above		70			
	CLKOUT pin output rise time		VCC = 2.7 V or above	t_{Cr}	—	15	ns	
			VCC = 1.8 V or above			30		
	CLKOUT pin output fall time		VCC = 2.7 V or above	t_{Cf}	—	15	ns	
			VCC = 1.8 V or above			30		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle
Note 3. When the LOCO is selected as the clock output source (CKOCR.CKOSEL[2:0] bits = 000b), set the clock output division ratio selection to divided by 2 (CKOCR.CKODIV[2:0] bits = 001b).
Note 4. When the XTAL external clock input or an oscillator is used with divided by 1 (CKOCR.CKOSEL[2:0] bits = 010b and CKOCR.CKODIV[2:0] bits = 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Table 5.31 Timing of On-Chip Peripheral Modules (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item				Symbol	Min.	Max.	Unit	Test Conditions
RSPI	RSPCK clock cycle	Master		t_{SPcyc}	2	4096	t_{Pcyc} *1	Figure 5.39
		Slave			8	4096		
	RSPCK clock high pulse width	Master		t_{SPCKWH}	$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2 - 3$	—	ns	
		Slave			$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2$	—		
	RSPCK clock low pulse width	Master		t_{SPCKWL}	$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2 - 3$	—	ns	
		Slave			$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2$	—		
	RSPCK clock rise/fall time	Output	2.7 V or above	t_{SPCKr}, t_{SPCKf}	—	10	ns	
			1.8 V or above		—	15		
		Input			—	1	µs	
	Data input setup time	Master	2.7 V or above	t_{SU}	10	—	ns	Figure 5.40 to Figure 5.45
			1.8 V or above		30	—		
		Slave			$25 - t_{Pcyc}$	—		
	Data input hold time	Master	RSPCK set to a division ratio other than PCLKB divided by 2	t_H	t_{Pcyc}	—	ns	
			RSPCK set to PCLKB divided by 2	t_{HF}	0	—		
		Slave		t_H	$20 + 2 \times t_{Pcyc}$	—		
	SSL setup time	Master		t_{LEAD}	$–30 + N^{*2} \times t_{SPcyc}$	—	ns	
		Slave			2	—	t_{Pcyc}	
	SSL hold time	Master		t_{LAG}	$–30 + N^{*3} \times t_{SPcyc}$	—	ns	
		Slave			2	—	t_{Pcyc}	
	Data output delay time	Master	2.7 V or above	t_{OD}	—	14	ns	
			1.8 V or above		—	30		
		Slave	2.7 V or above		—	$3 \times t_{Pcyc} + 65$		
			1.8 V or above		—	$3 \times t_{Pcyc} + 105$		
	Data output hold time	Master	2.7 V or above	t_{OH}	0	—	ns	
			1.8 V or above		–20	—		
		Slave			0	—		
	Successive transmission delay time	Master		t_{TD}	$t_{SPcyc} + 2 \times t_{Pcyc}$	$8 \times t_{SPcyc} + 2 \times t_{Pcyc}$	ns	
		Slave			$4 \times t_{Pcyc}$	—		
	MOSI and MISO rise/fall time	Output	2.7 V or above	t_{Dr}, t_{Df}	—	10	ns	
			1.8 V or above		—	20		
		Input			—	1	µs	
	SSL rise/fall time	Output		t_{SSLr}, t_{SSLf}	—	20	ns	
		Input			—	1	µs	
	Slave access time		2.7 V or above	t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
			1.8 V or above		—	7		
	Slave output release time		2.7 V or above	t_{REL}	—	5	t_{Pcyc}	
			1.8 V or above		—	6		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. N: An integer from 1 to 8 that can be set by the RSPI clock delay register (SPCKD)
Note 3. N: An integer from 1 to 8 that can be set by the RSPI slave select negation delay register (SSLND)

Table 5.32 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.39
	SCK clock cycle input (slave)			6	65536		
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.40, Figure 5.42
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SS input setup time		t_{LEAD}	3	—	t_{Pcyc}	
	SS input hold time		t_{LAG}	3	—	t_{Pcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	85		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SS input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

Table 5.33 Timing of On-Chip Peripheral Modules (4)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

Item		Symbol	Min.*1	Max.	Unit	Test Conditions
RIIC (Standard mode, SMBus)	SCL0 input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	—	ns	Figure 5.46
	SCL0 input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0 input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0, SDA0 input rise time	t_{Sr}	—	1000	ns	
	SCL0, SDA0 input fall time	t_{Sf}	—	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA0 input bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition input hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition input setup time	t_{STAS}	1000	—	ns	
	STOP condition input setup time	t_{STOS}	1000	—	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	
RIIC (Fast mode)	SCL0 input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 600	—	ns	Figure 5.46
	SCL0 input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0 input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0, SDA0 input rise time	t_{Sr}	—*2	300	ns	
	SCL0, SDA0 input fall time	t_{Sf}	—*2	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA0 input bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition input hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition input setup time	t_{STAS}	300	—	ns	
	STOP condition input setup time	t_{STOS}	300	—	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	

Note: t_{IICcyc}: RIIC internal reference count clock (IICφ) cycle

Note 1. The value in parentheses is used when the ICMR3.NF[1:0] bits are set to 11b while a digital filter is enabled with the ICFER.NFE bit = 1.

Note 2. The minimum tsr and tsf specifications for fast mode are not set.

Table 5.34 Timing of On-Chip Peripheral Modules (5)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Simple I²C (Standard mode)	SDA0 input rise time	t_{Sr}	—	1000	ns	Figure 5.46
	SDA0 input fall time	t_{Sf}	—	300	ns	
	SDA0 input spike pulse removal time	t_{SP}	0	4 × t_{pcyc}*1	ns	
	Data input setup time	t_{SDAS}	250	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	
Simple I²C (Fast mode)	SCL0, SDA0 input rise time	t_{Sr}	—	300	ns	Figure 5.46
	SCL0, SDA0 input fall time	t_{Sf}	—	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	4 × t_{pcyc}*1	ns	
	Data input setup time	t_{SDAS}	100	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	

Note: t_{Pcyc}: PCLK cycle

Note 1. This applies when the SMR.CKS[1:0] bits = 00b and the SNFR.NFCS[2:0] bits = 010b while the SNFR.NFE bit = 1 and the digital filter is enabled.

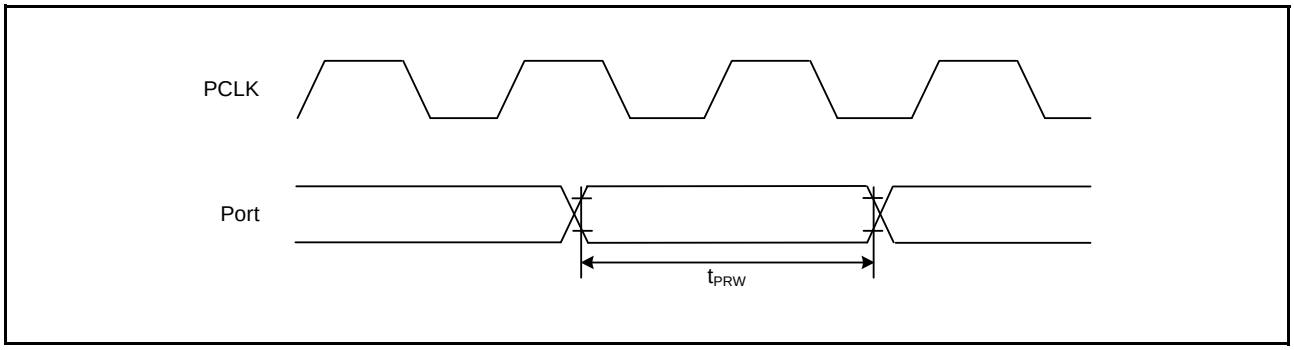


Figure 5.32 I/O Port Input Timing

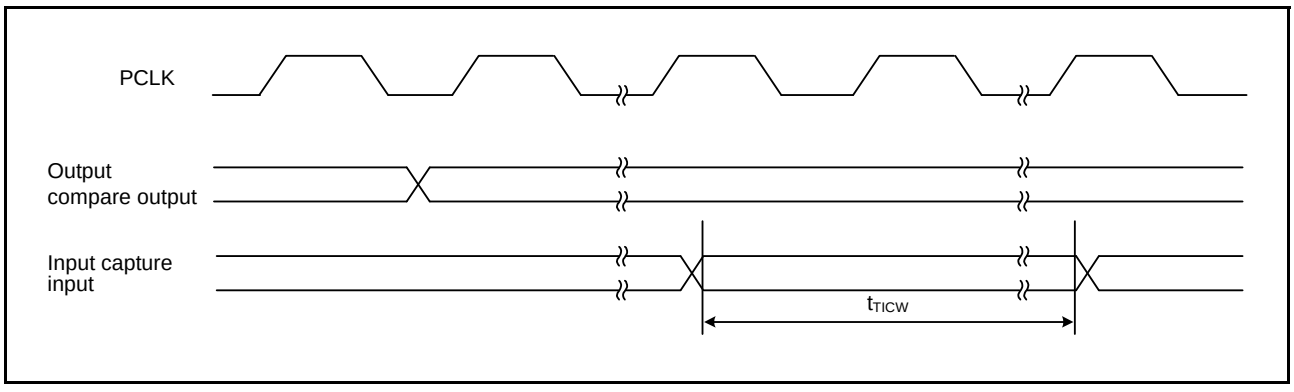


Figure 5.33 MTU2 Input/Output Timing

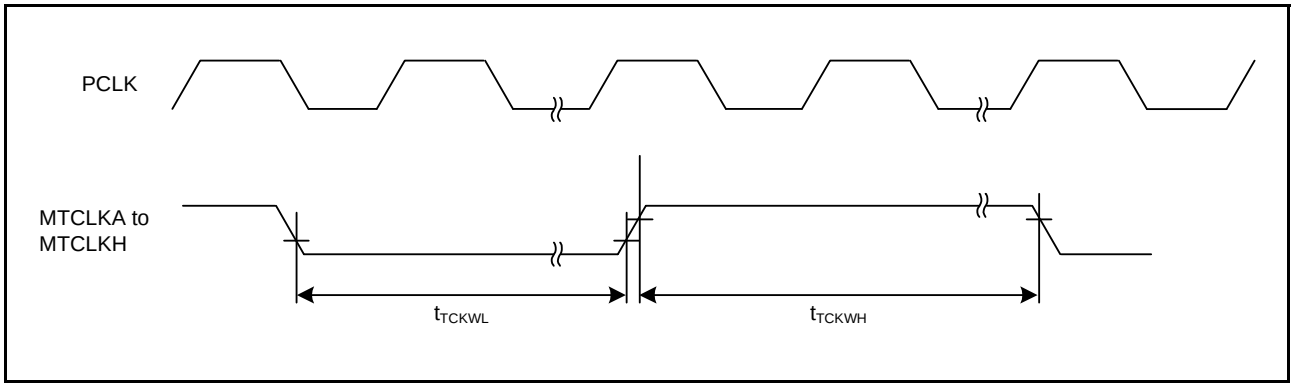


Figure 5.34 MTU2 Clock Input Timing

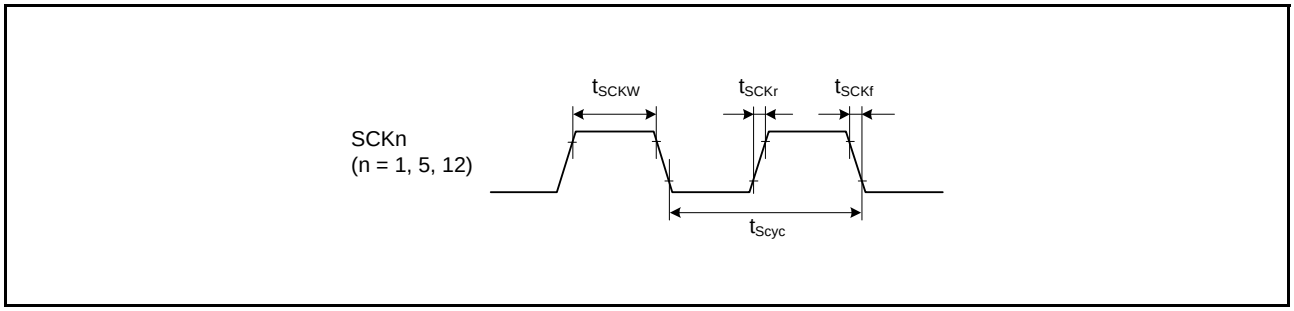


Figure 5.35 SCK Clock Input Timing

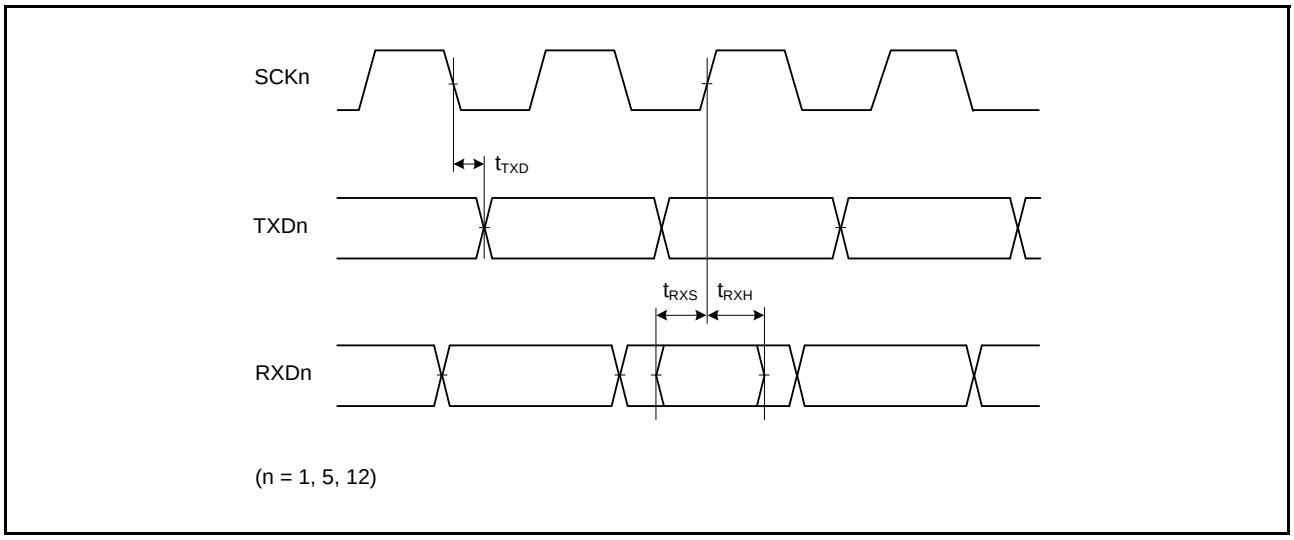


Figure 5.36 SCI Input/Output Timing: Clock Synchronous Mode

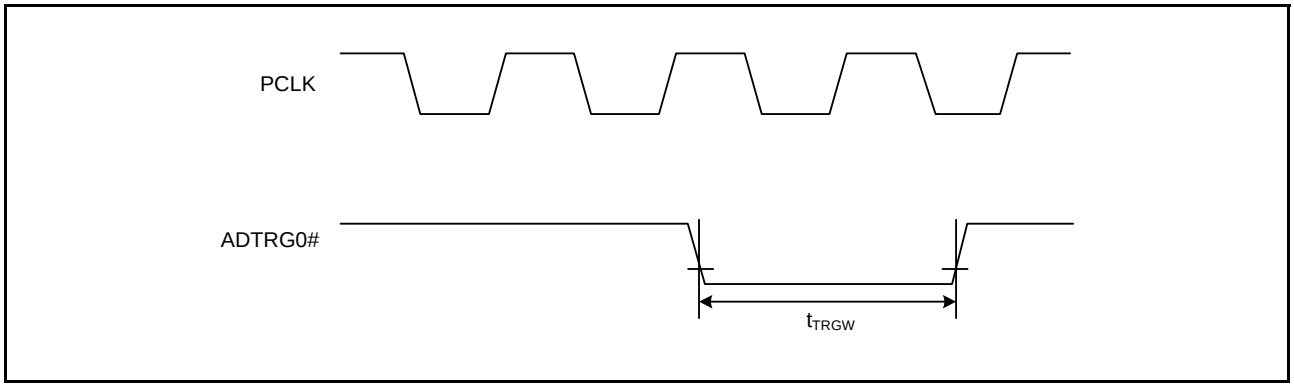


Figure 5.37 A/D Converter External Trigger Input Timing

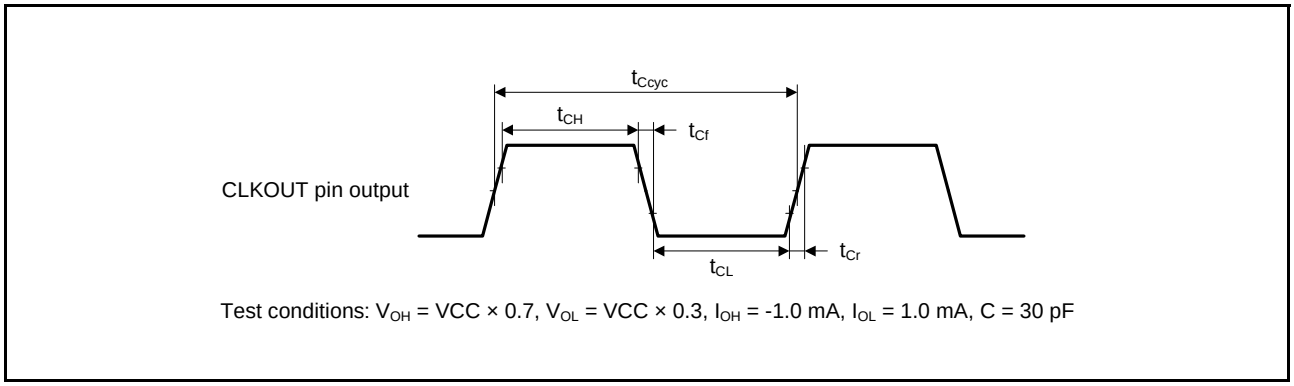


Figure 5.38 CLKOUT Output Timing

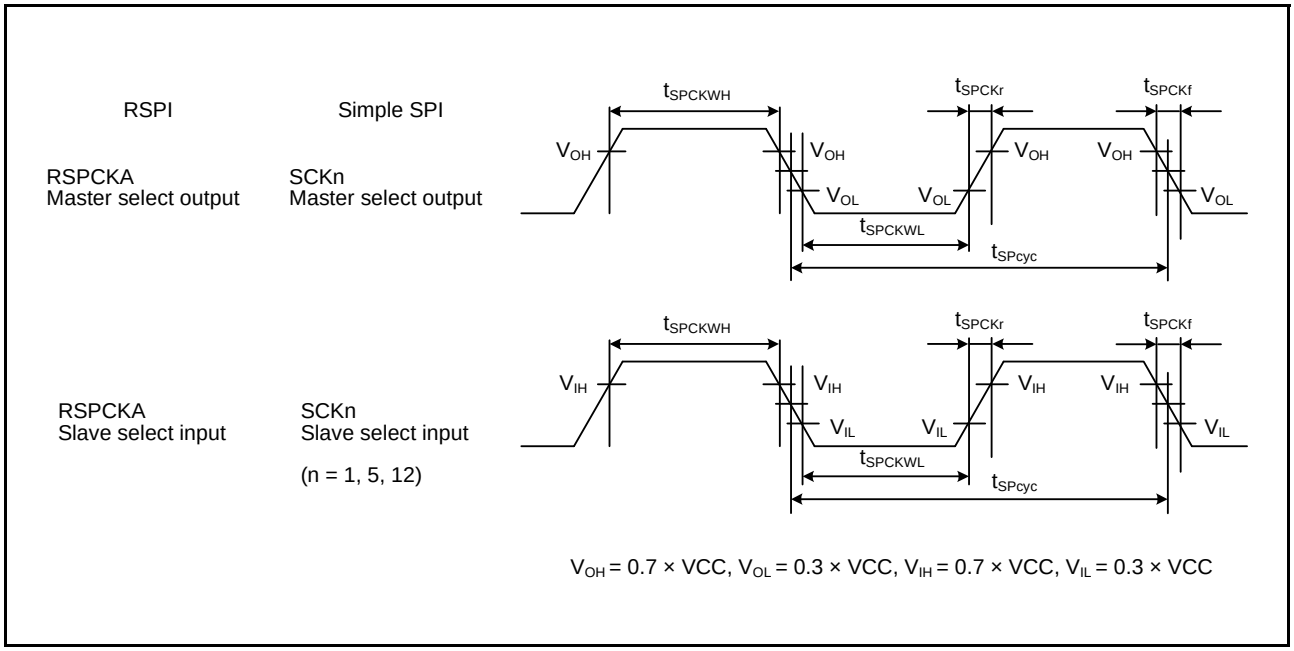


Figure 5.39 RSPI Clock Timing and Simple SPI Clock Timing

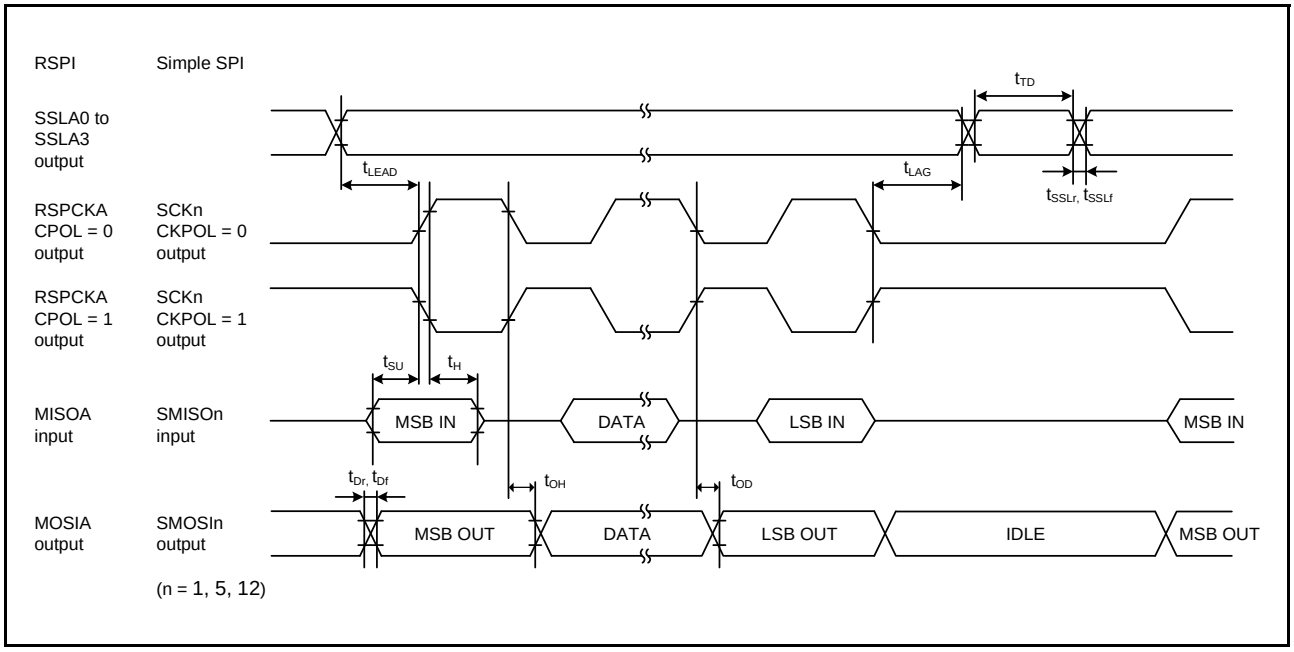


Figure 5.40 RSPI Timing (Master, CPHA = 0) (Bit Rate: PCLKB Set to Division Ratio Other Than Divided by 2) and Simple SPI Timing (Master, CKPH = 1)

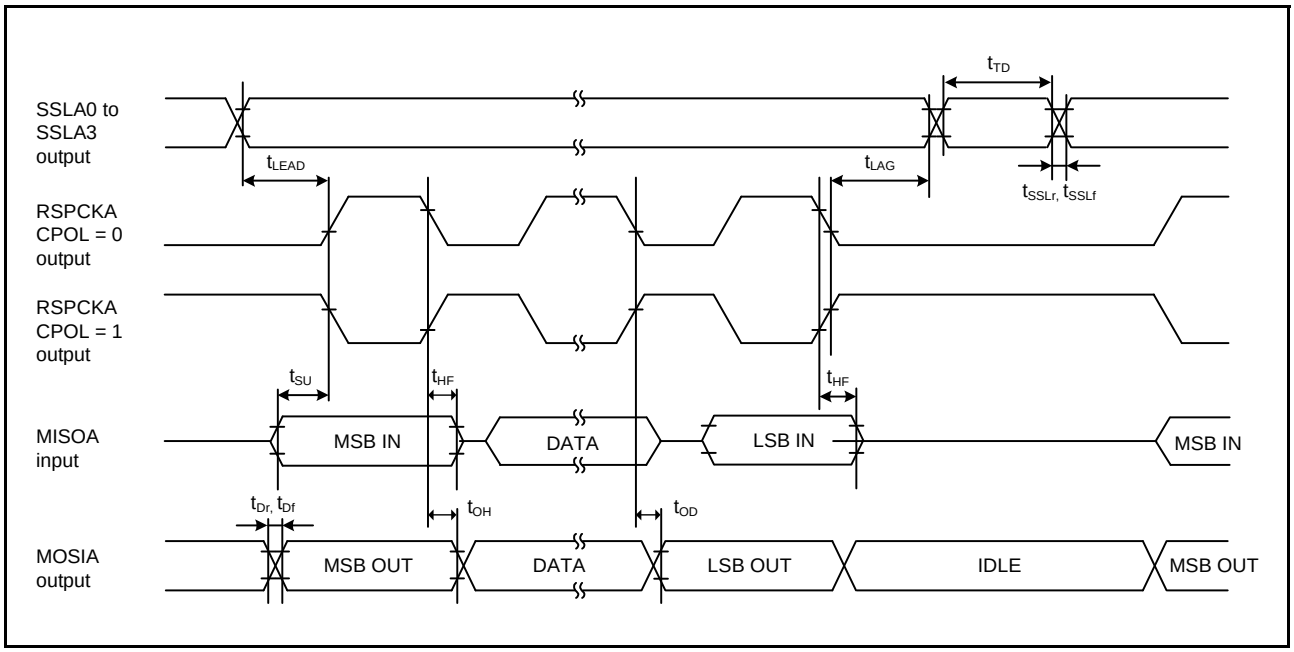


Figure 5.41 RSPI Timing (Master, CPHA = 0) (Bit Rate: PCLKB Set to Divided by 2)

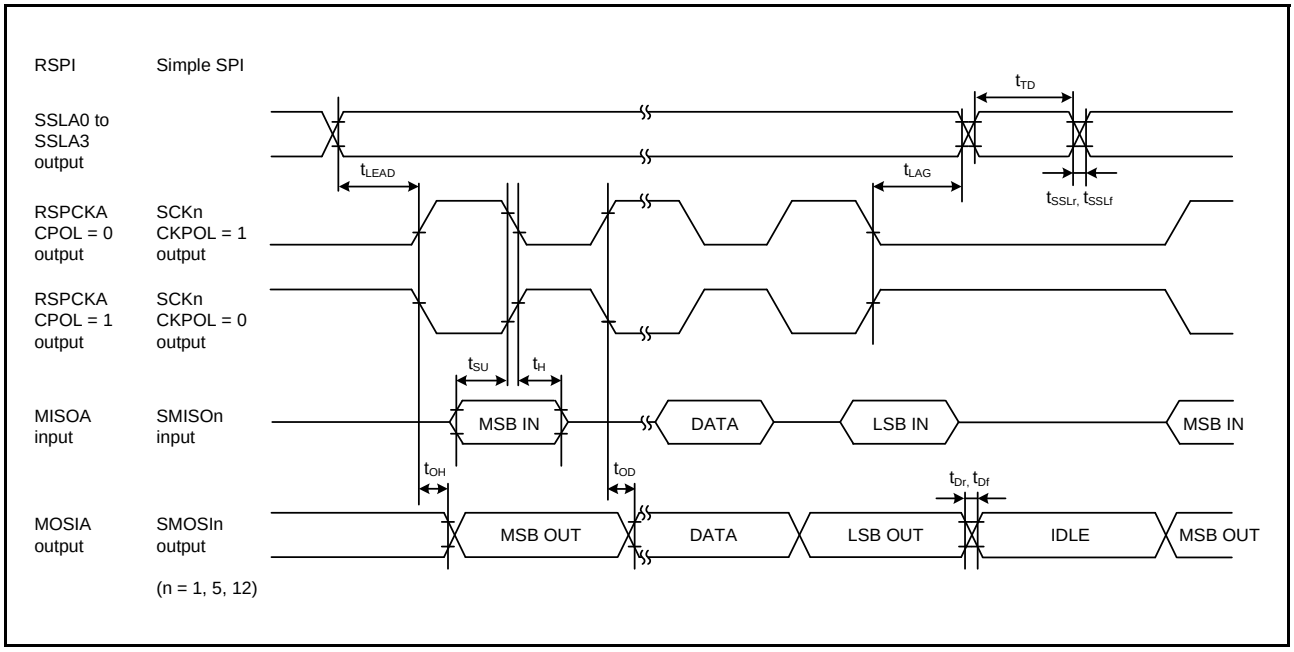


Figure 5.42 RSPI Timing (Master, CPHA = 1) (Bit Rate: PCLKB Set to Division Ratio Other Than Divided by 2) and Simple SPI Timing (Master, CKPH = 0)

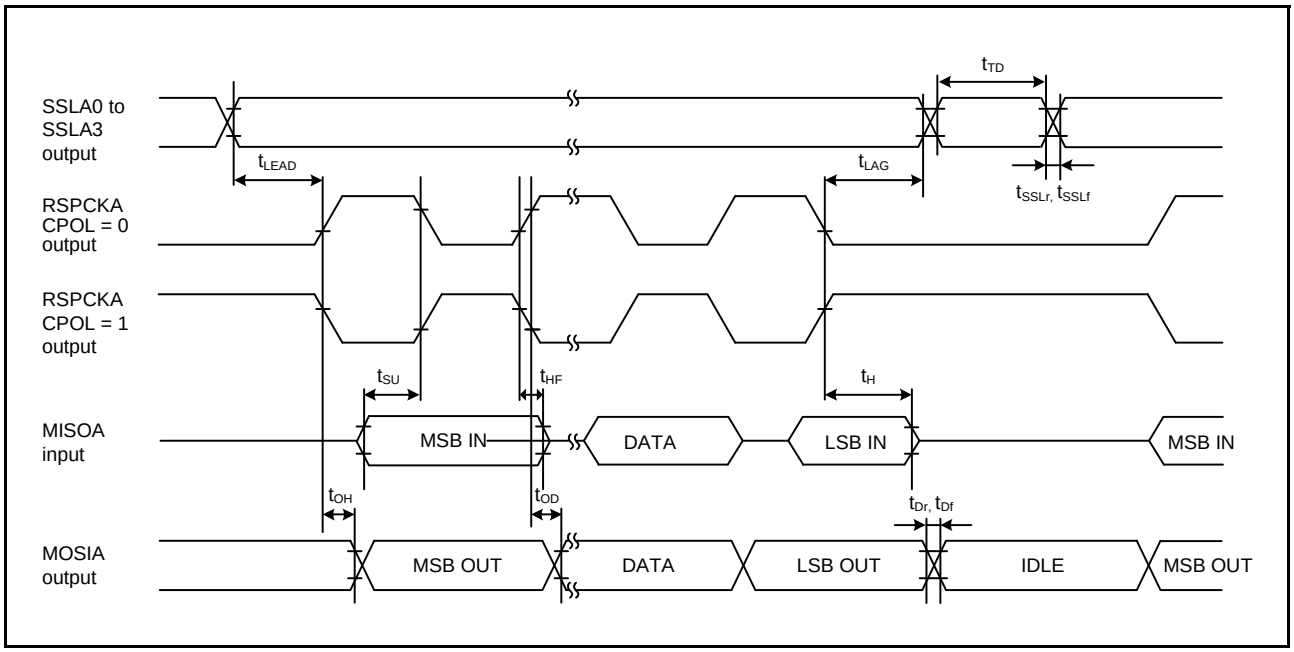


Figure 5.43 RSPI Timing (Master, CPHA = 1) (Bit Rate: PCLKB Set to Divided by 2)

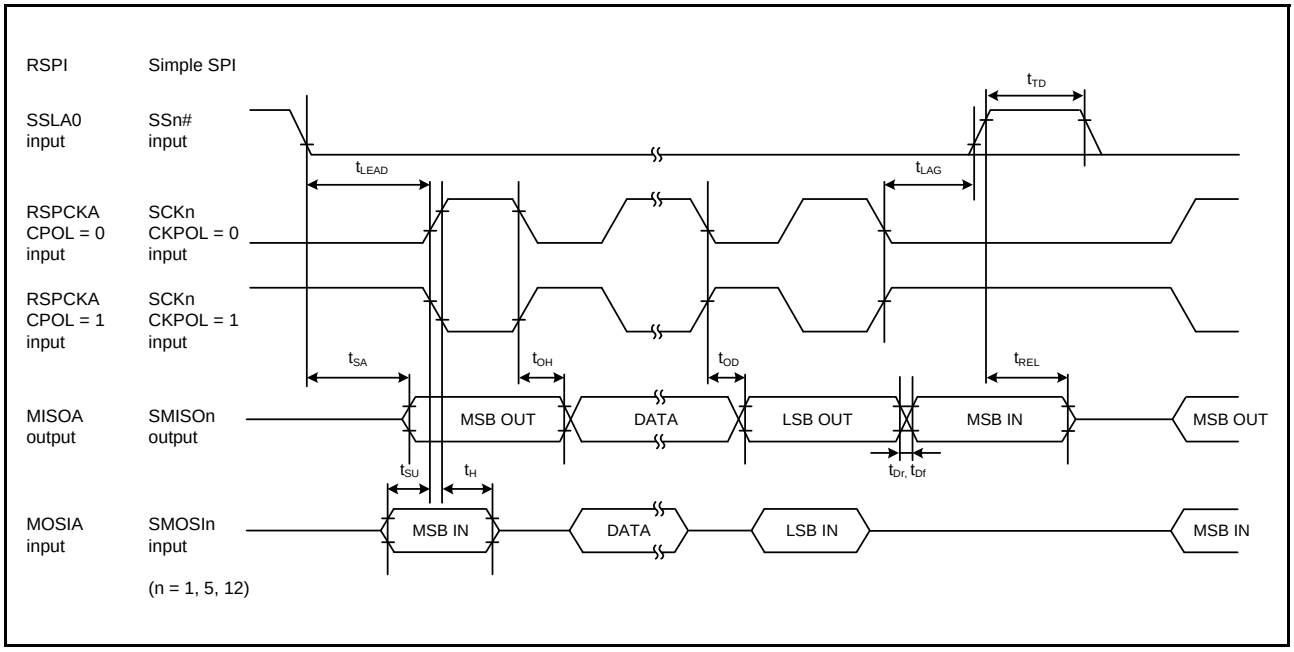


Figure 5.44 RSPI Timing (Slave, CPHA = 0) and Simple SPI Timing (Slave, CKPH = 1)

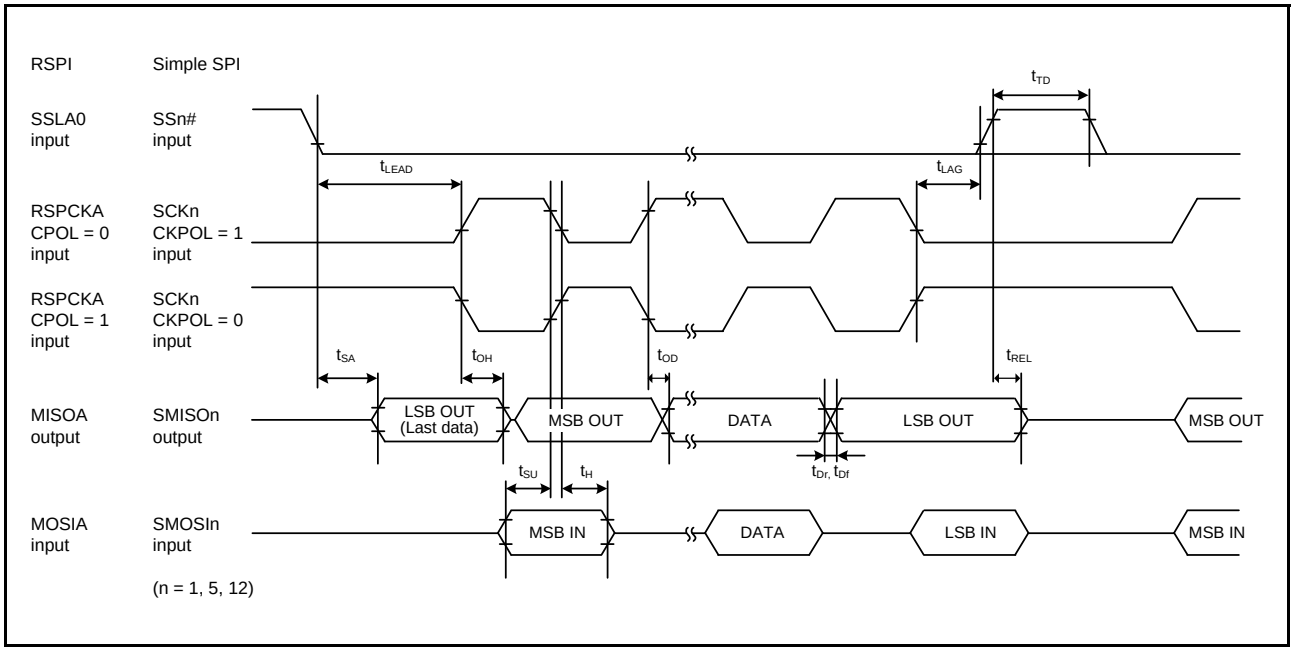
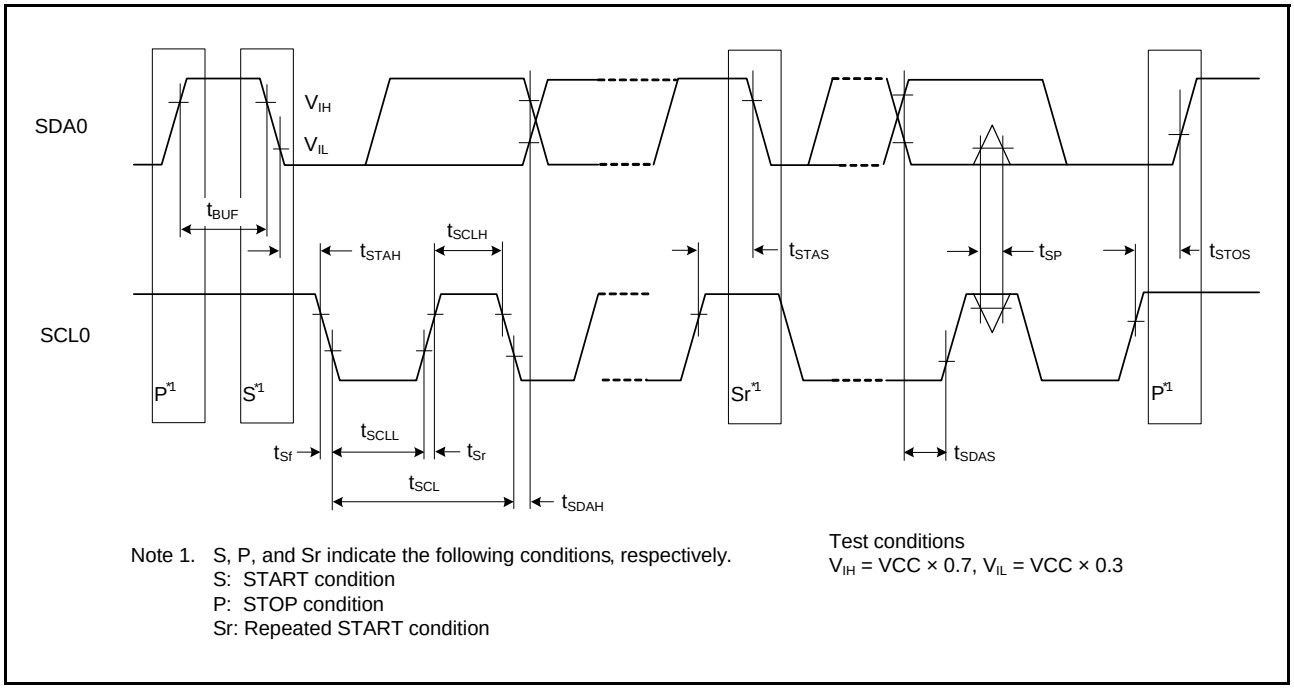


Figure 5.45 RSPI Timing (Slave, CPHA = 1) and Simple SPI Timing (Slave, CKPH = 0)



Note 1. S, P, and Sr indicate the following conditions, respectively.
S: START condition
P: STOP condition
Sr: Repeated START condition

Figure 5.46 RIIC Bus Interface Input/Output Timing and Simple I²C Bus Interface Input/Output Timing

5.4 A/D Conversion Characteristics

Table 5.35 A/D Conversion Characteristics (1)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, 2.7 V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VREFL0 = 0 V,
T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		4	—	32	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 32 MHz)	Permissible signal source impedance (Max.) = 0.3 kΩ	1.031 (0.313)*2	—	—	µs	High-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 09h
		1.375 (0.641)*2	—	—		Normal-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±4.5	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±6.0	LSB	Other than above
Full-scale error		—	±0.75	±4.5	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±6.0	LSB	Other than above
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±8.0	LSB	Other than above
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.0	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

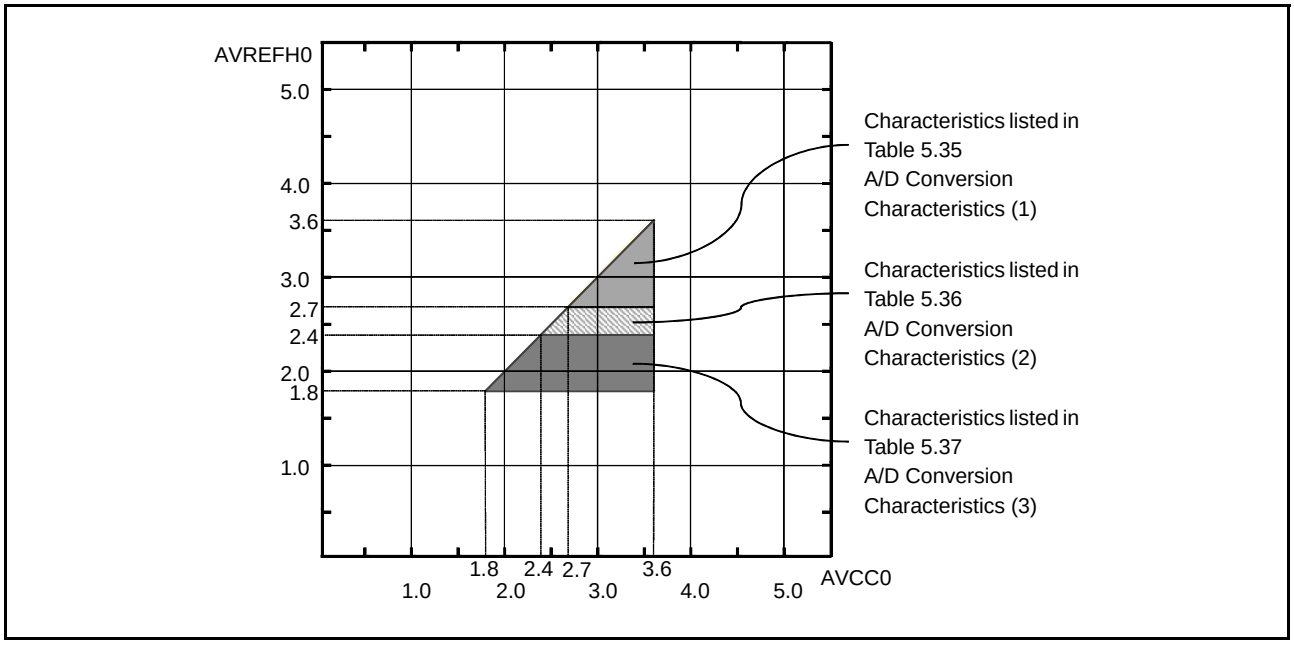


Figure 5.47 AVCC0 to AVREFH Voltage Range

Table 5.36 A/D Conversion Characteristics (2)

Conditions: 2.4 V ≤ VCC ≤ 3.6 V, 2.4 V ≤ AVCC0 ≤ 3.6 V, 2.4 V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VREFL0 = 0 V,
T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		4	—	16	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance (Max.) = 1.0 kΩ	2.062 (0.625)*2	—	—	µs	High-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 09h
		2.750 (1.313)*2	—	—	µs	Normal-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±6.0	LSB	
Full-scale error		—	±1.25	±6.0	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±3.0	±8.0	LSB	
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.5	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

Table 5.37 A/D Conversion Characteristics (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, 1.8 V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VREFL0 = 0 V,
T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	8	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 8 MHz)	Permissible signal source impedance (Max.) = 5.0 kΩ	4.875 (1.250)*2	—	—	µs	High-precision channel ADCSR.ADHSC bit = 0 ADSSTRn.SST[7:0] bits = 09h
		6.250 (2.625)*2	—	—		Normal-precision channel ADCSR.ADHSC bit = 0 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±24.0	LSB	
Full-scale error		—	±1.25	±24.0	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±2.75	±32.0	LSB	
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.25	±12.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

Table 5.38 A/D Converter Channel Classification

Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN004, AN006	AVCC0 = 1.8 to 3.6 V	Pins AN000 to AN004 and AN006 cannot be used as digital outputs when the A/D converter is in use.
Normal-precision channel	AN008 to AN015		
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 3.6 V	
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 3.6 V	

Table 5.39 A/D Internal Reference Voltage Characteristics

Conditions: 2.0 V ≤ VCC ≤ 3.6 V, 2.0 V ≤ AVCC0 ≤ 3.6 V*1, VSS = AVSS0 = VREFL0 = 0 V, T_a = –40 to +105°C

Item	Min.	Typ.	Max.	Unit	Test Conditions
Internal reference voltage input channel*2	1.36	1.43	1.50	V	

Note 1. The internal reference voltage cannot be selected for input channels when AVCC0 < 2.0 V.
Note 2. The A/D internal reference voltage indicates the voltage when the internal reference voltage is input to the A/D converter.

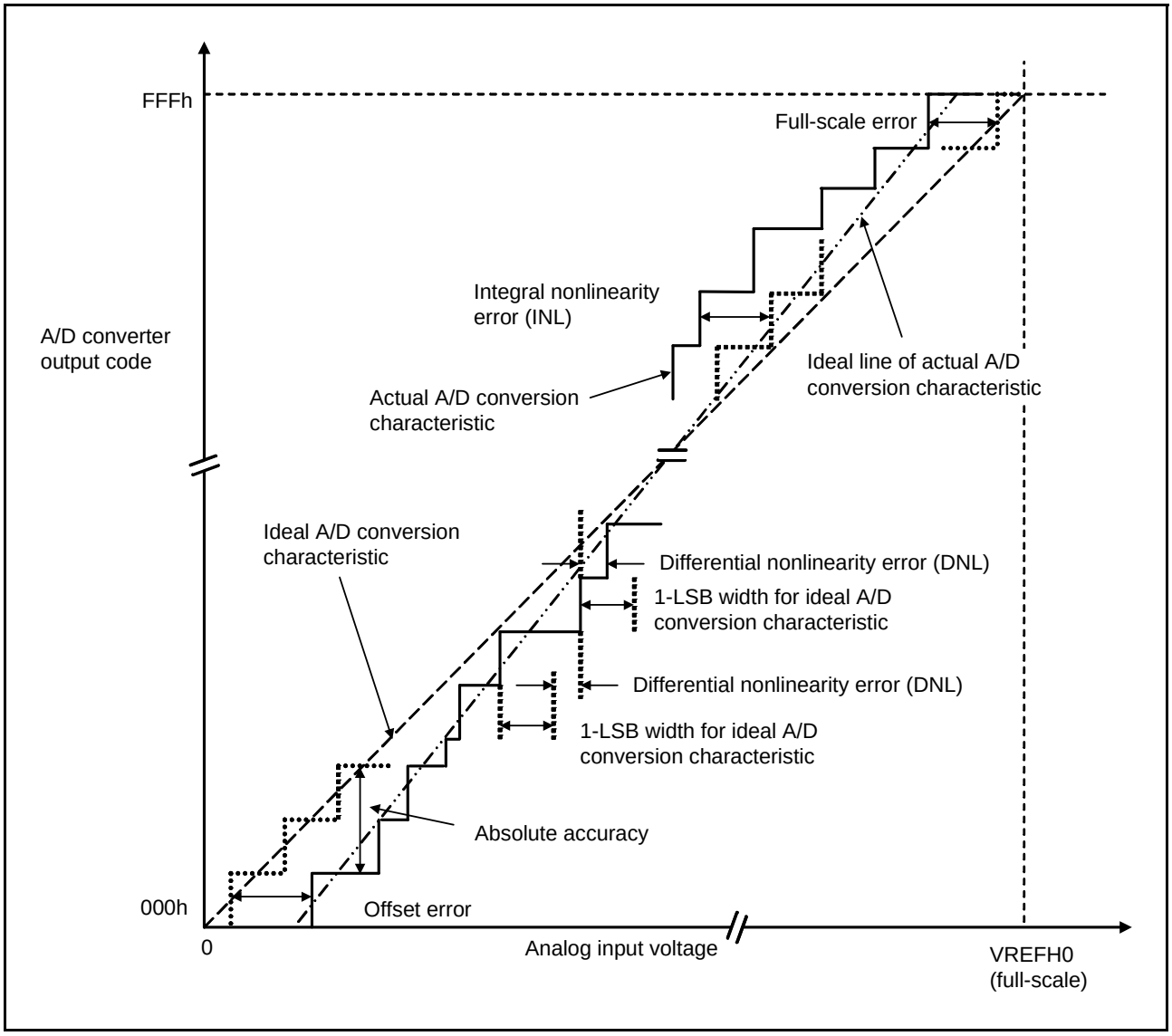


Figure 5.48 Illustration of A/D Converter Characteristic Terms

Absolute accuracy

Absolute accuracy is the difference between output code based on the theoretical A/D conversion characteristics, and the actual A/D conversion result. When measuring absolute accuracy, the voltage at the midpoint of the width of analog input voltage (1-LSB width), that can meet the expectation of outputting an equal code based on the theoretical A/D conversion characteristics, is used as an analog input voltage. For example, if 12-bit resolution is used and if reference voltage (VREFH0 = 3.072 V), then 1-LSB width becomes 0.75 mV, and 0 mV, 0.75 mV, 1.5 mV, ... are used as analog input voltages.

If analog input voltage is 6 mV, absolute accuracy = ±5 LSB means that the actual A/D conversion result is in the range of 003h to 00Dh though an output code, 008h, can be expected from the theoretical A/D conversion characteristics.

Integral nonlinearity error (INL)

Integral nonlinearity error is the maximum deviation between the ideal line when the measured offset and full-scale errors are zeroed, and the actual output code.

Differential nonlinearity error (DNL)

Differential nonlinearity error is the difference between 1-LSB width based on the ideal A/D conversion characteristics and the width of the actually output code.

Offset error

Offset error is the difference between a transition point of the ideal first output code and the actual first output code.

Full-scale error

Full-scale error is the difference between a transition point of the ideal last output code and the actual last output code.

5.5 Temperature Sensor Characteristics

Table 5.40 Temperature Sensor Characteristics

Conditions: 2.0 V ≤ VCC ≤ 3.6 V, 2.0 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Relative accuracy	—	—	±1.5	—	°C	2.4 V or above
		—	±2.0	—		Below 2.4 V
Temperature slope	—	—	–3.65	—	mV/°C	
Output voltage (at 25°C)	—	—	1.05	—	V	VCC = 3.3 V
Temperature sensor start time	t_{START}	—	—	5	µs	
Sampling time	—	5	—	—	µs	

5.6 Power-On Reset Circuit and Voltage Detection Circuit Characteristics

Table 5.41 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Power-on reset (POR)	V_{POR}	1.35	1.50	1.65	V	Figure 5.49, Figure 5.50
	Voltage detection circuit (LVD1)*1	V_{det1_4}	3.00	3.10	3.20	V	Figure 5.51 At falling edge VCC
		V_{det1_5}	2.91	3.00	3.09		
		V_{det1_6}	2.81	2.90	2.99		
		V_{det1_7}	2.70	2.79	2.88		
		V_{det1_8}	2.60	2.68	2.76		
		V_{det1_9}	2.50	2.58	2.66		
		V_{det1_A}	2.40	2.48	2.56		
		V_{det1_B}	1.99	2.06	2.13		
		V_{det1_C}	1.90	1.96	2.02		
		V_{det1_D}	1.80	1.86	1.92		

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD2), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet1_n denotes the value of the LVDLVLR.LVD1LVL[3:0] bits.

Table 5.42 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Voltage detection circuit (LVD2)*1	V_{det2_0}	2.71	2.90	3.09	V	Figure 5.52 At falling edge VCC
		V_{det2_1}	2.43	2.60	2.77		
		V_{det2_2}	1.87	2.00	2.13		
		V_{det2_3}*2	1.69	1.80	1.91		
Wait time after power-on reset cancellation	At normal startup*3	t_{POR}	—	9.1	—	ms	Figure 5.50
	During fast startup time*4	t_{POR}	—	1.6	—		
Wait time after voltage monitoring 1 reset cancellation	Power-on voltage monitoring 1 reset disabled*3	t_{LVD1}	—	568	—	µs	Figure 5.51
	Power-on voltage monitoring 1 reset enabled*4		—	100	—		
Wait time after voltage monitoring 2 reset cancellation		t_{LVD2}	—	100	—	µs	Figure 5.52
Response delay time		t_{det}	—	—	350	µs	Figure 5.49
Minimum VCC down time*5		t_{VOFF}	350	—	—	µs	Figure 5.49, VCC = 1.0 V or above
Power-on reset enable time		$t_{W(POR)}$	1	—	—	ms	Figure 5.50, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)		$Td_{(E-A)}$	—	—	300	µs	Figure 5.51, Figure 5.52
Hysteresis width (LVD1 and LVD2)		V_{LVH}	—	70	—	mV	Vdet1_4 selected
			—	60	—		Vdet1_5 to 9, LVD2 selected
			—	50	—		When selection is from among Vdet1_A to B.
			—	40	—		When selection is from among Vdet1_C to D.

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD1), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet2_n denotes the value of the LVDLVLR.LVD2LVL[3:0] bits.

Note 2. Vdet2_3 selection can be used only when the CMPA2 pin input voltage is selected and cannot be used when the power supply voltage (VCC) is selected.

Note 3. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.

Note 4. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.

Note 5. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

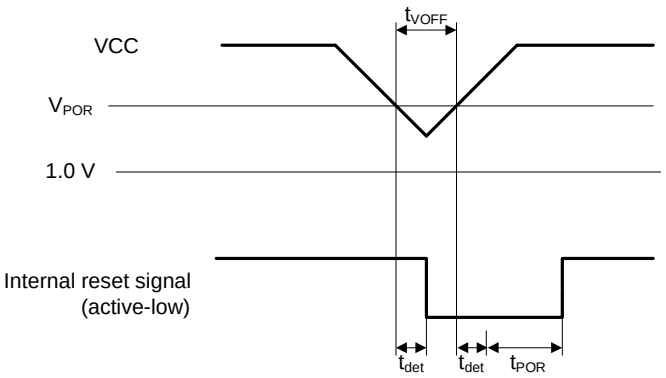
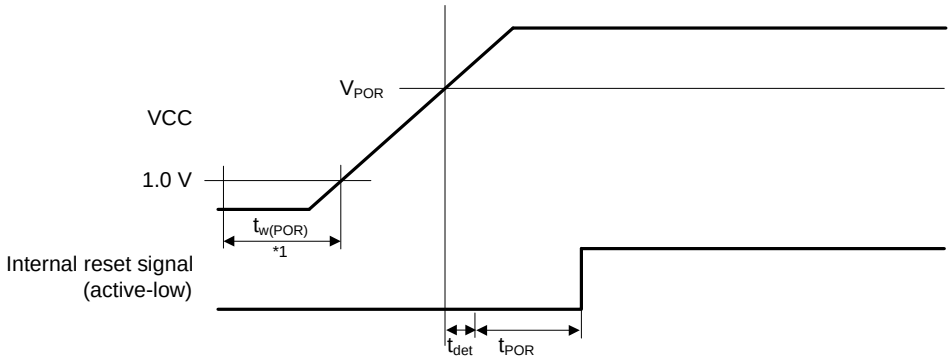


Figure 5.49 Voltage Detection Reset Timing



Note 1. $t_{w(por)}$ is the time required for a power-on reset to be enabled while the external power VCC is being held below the valid voltage (1.0 V).
When VCC turns on, maintain $t_{w(por)}$ for 1.0 ms or more.

Figure 5.50 Power-On Reset Timing

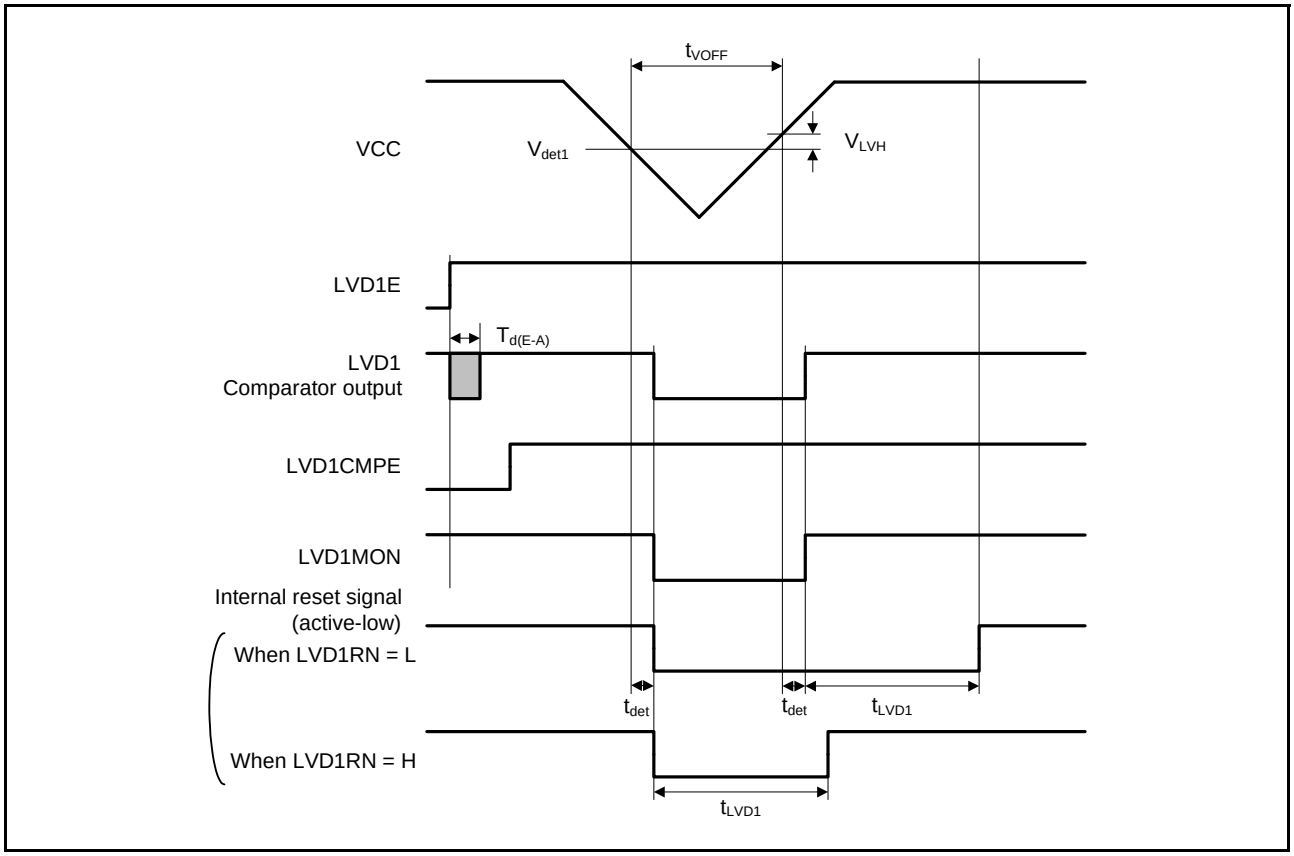


Figure 5.51 Voltage Detection Circuit Timing (V_{det1})

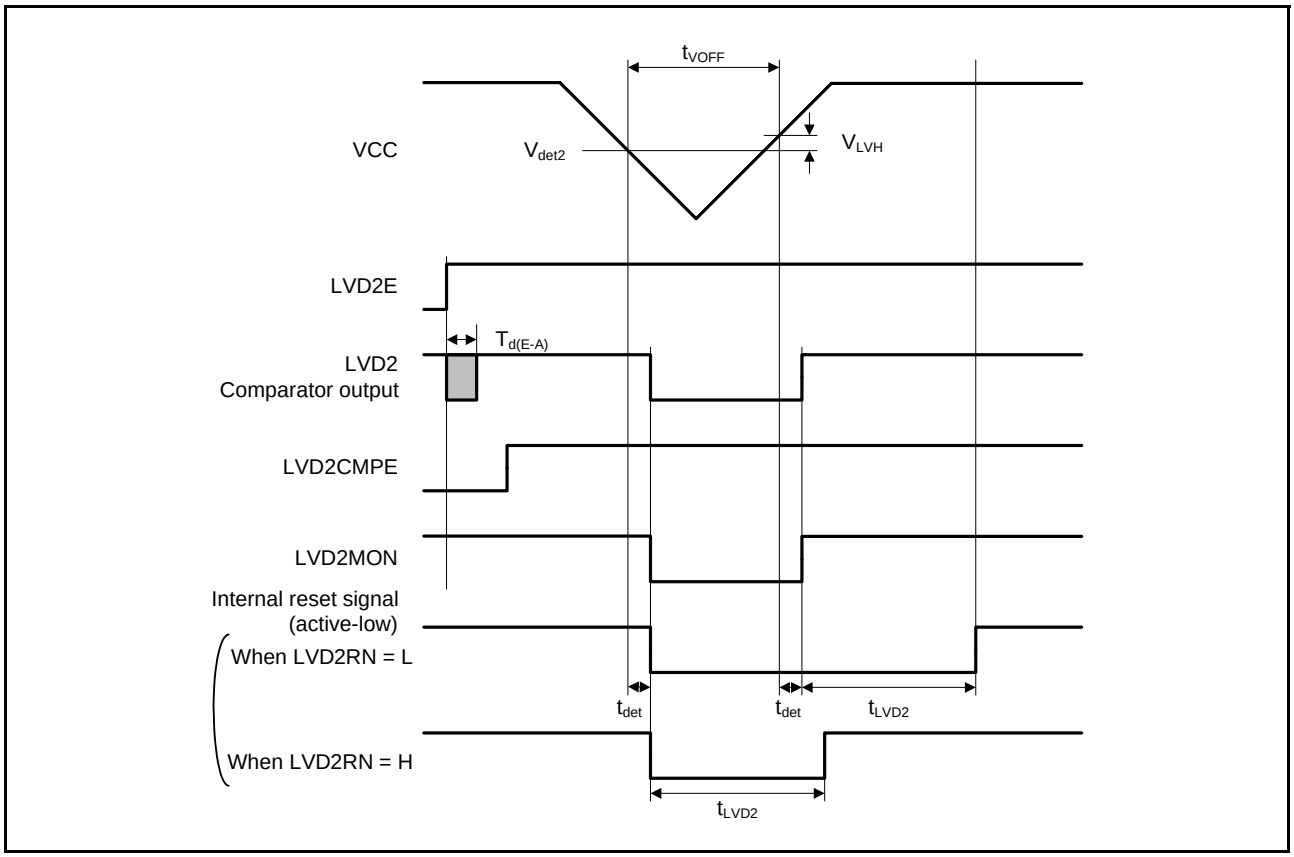


Figure 5.52 Voltage Detection Circuit Timing (V_{det2})

5.7 Oscillation Stop Detection Timing

Table 5.43 Oscillation Stop Detection Circuit Characteristics

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Detection time	t_{dr}	—	—	1	ms	Figure 5.53

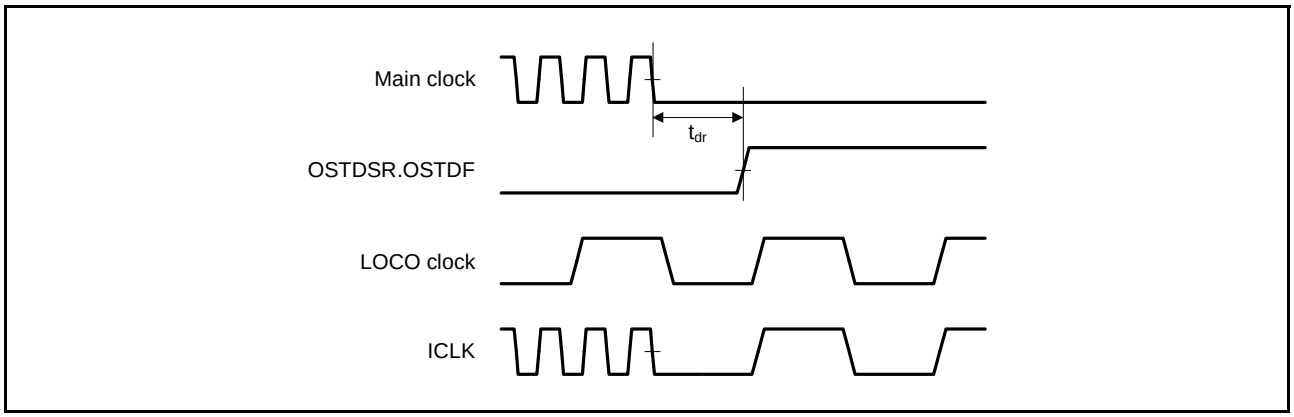


Figure 5.53 Oscillation Stop Detection Timing

5.8 ROM (Flash Memory for Code Storage) Characteristics

Table 5.44 ROM (Flash Memory for Code Storage) Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N_{PEC}	1000	—	—	Times	
Data hold time	After 1000 times of N_{PEC}	t_{DRP}	20*2, *3	—	—	Year	T_a = +85°C

Note 1. Definition of reprogram/erase cycle: The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 1000), erasing can be performed n times for each block. For instance, when 4-byte programming is performed 256 times for different addresses in 1-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).
Note 2. Characteristic when using the flash memory programmer and the self-programming library provided from Renesas Electronics.
Note 3. This result is obtained from reliability testing.

Table 5.45 ROM (Flash Memory for Code Storage) Characteristics (2)

High-speed operating mode Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +105°C

Item		Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	4-byte	t_{P4}	—	103	931	—	52	489	µs
Erasure time	1-Kbyte	t_{E1K}	—	8.23	267	—	5.48	214	ms
	128-Kbyte	t_{E128K}	—	203	463	—	20	228	ms
Blank check time	4-byte	t_{BC4}	—	—	48	—	—	15.9	µs
	1-Kbyte	t_{BC1K}	—	—	1.58	—	—	0.127	ms
Erase operation forcible stop time		t_{SED}	—	—	21.6	—	—	12.8	µs
Start-up area switching setting time		t_{SAS}	—	12.6	543	—	6.16	432	ms
Access window time		t_{AWS}	—	12.6	543	—	6.16	432	ms
ROM mode transition wait time 1		t_{DIS}	2	—	—	2	—	—	µs
ROM mode transition wait time 2		t_{MS}	5	—	—	5	—	—	µs

Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

Table 5.46 ROM (Flash Memory for Code Storage) Characteristics (3)

Middle-speed operating mode Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +85°C

Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	4-byte	t_{P4}	—	143	1330	—	96.8	932	µs
Erasure time	1-Kbyte	t_{E1K}	—	8.3	269	—	5.85	219	ms
	128-Kbyte	t_{E128K}	—	203	464	—	40	260	ms
Blank check time	4-byte	t_{BC4}	—	—	78	—	—	50	µs
	1-Kbyte	t_{BC1K}	—	—	1.61	—	—	0.369	ms
Erase operation forcible stop time		t_{SED}	—	—	33.6	—	—	25.6	µs
Start-up area switching setting time		t_{SAS}	—	13.2	549	—	7.6	445	ms
Access window time		t_{AWS}	—	13.2	549	—	7.6	445	ms
ROM mode transition wait time 1		t_{DIS}	2	—	—	2	—	—	µs
ROM mode transition wait time 2		t_{MS}	3	—	—	3	—	—	µs

Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

5.9 Usage Notes

5.9.1 Connecting VCL Capacitor and Bypass Capacitors

This MCU integrates an internal voltage-down circuit, which is used for lowering the power supply voltage in the internal MCU to adjust automatically to the optimum level. A 4.7-µF capacitor needs to be connected between this internal voltage-down power supply (VCL pin) and VSS pin. Figure 5.54 to Figure 5.55 shows how to connect external capacitors. Place an external capacitor close to the pins. Do not apply the power supply voltage to the VCL pin. Insert a multilayer ceramic capacitor as a bypass capacitor between each pair of the power supply pins. Implement a bypass capacitor to the MCU power supply pins as close as possible. Use a recommended value of 0.1 µF as the capacitance of the capacitors. For the capacitors related to crystal oscillation, see section 9, Clock Generation Circuit in the User's Manual: Hardware. For the capacitors related to analog modules, also see section 27, 12-Bit A/D Converter (S12ADb) in the User's Manual: Hardware.
For notes on designing the printed circuit board, see the descriptions of the application note "Hardware Design Guide" (R01AN1411EJ). The latest version can be downloaded from Renesas Electronics Website.

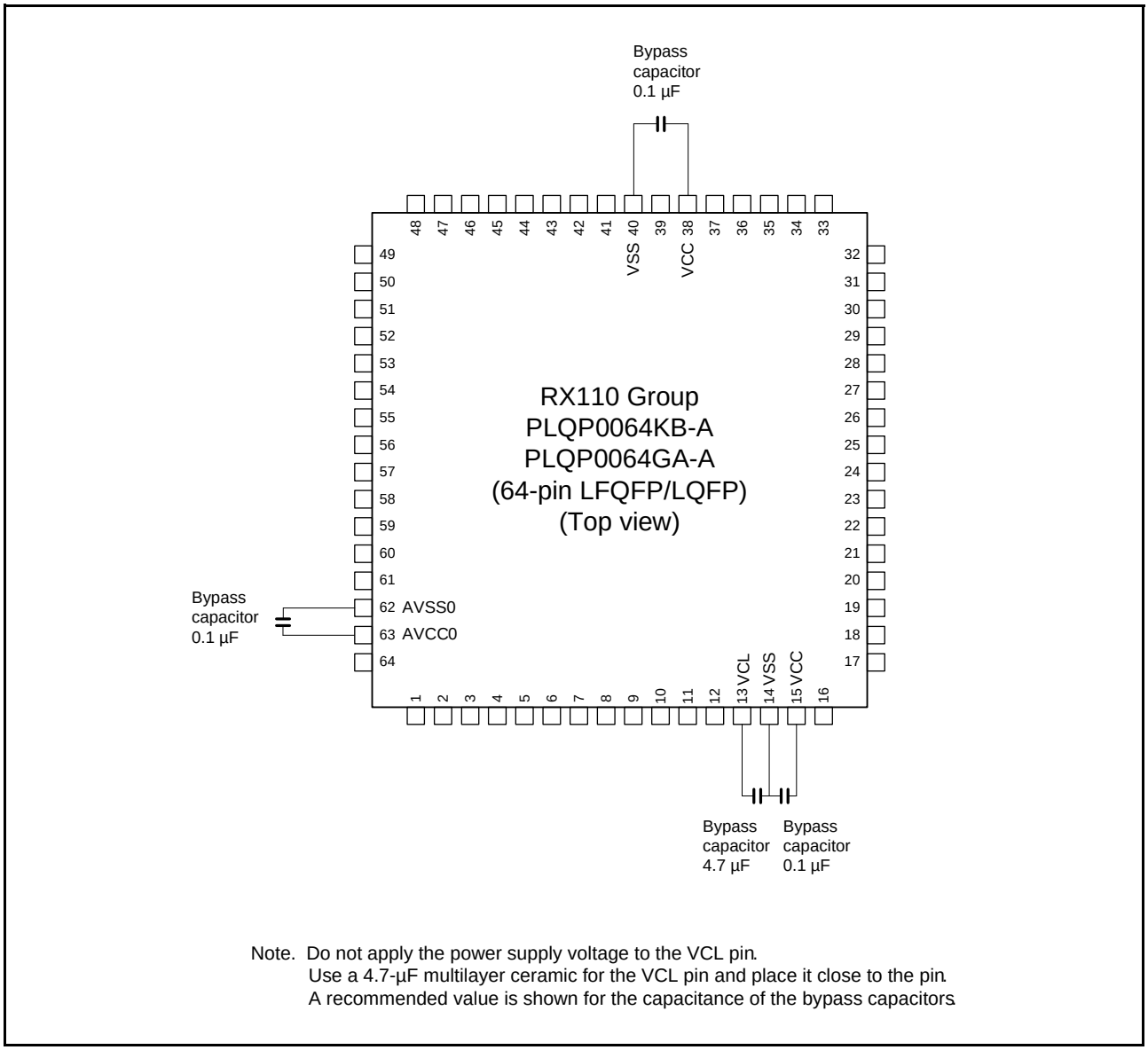
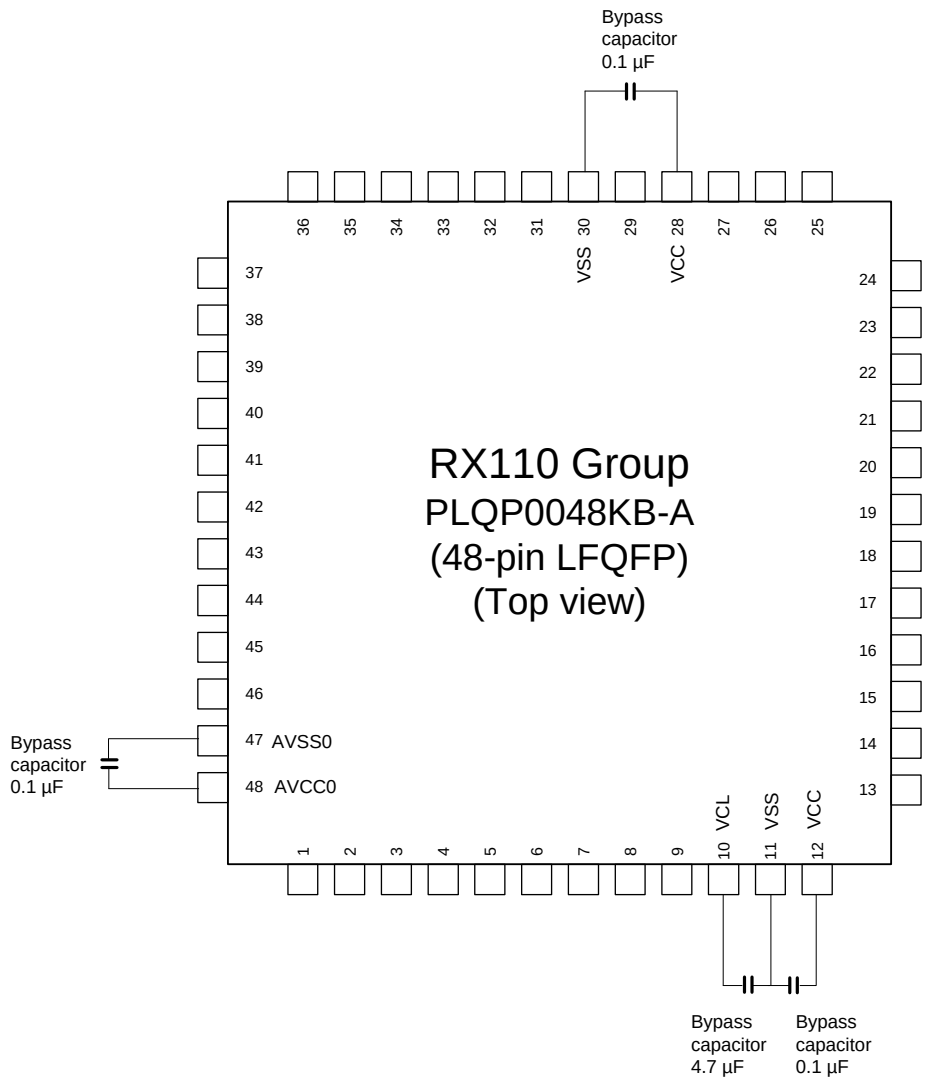


Figure 5.54 Connecting Capacitors (64 Pins)



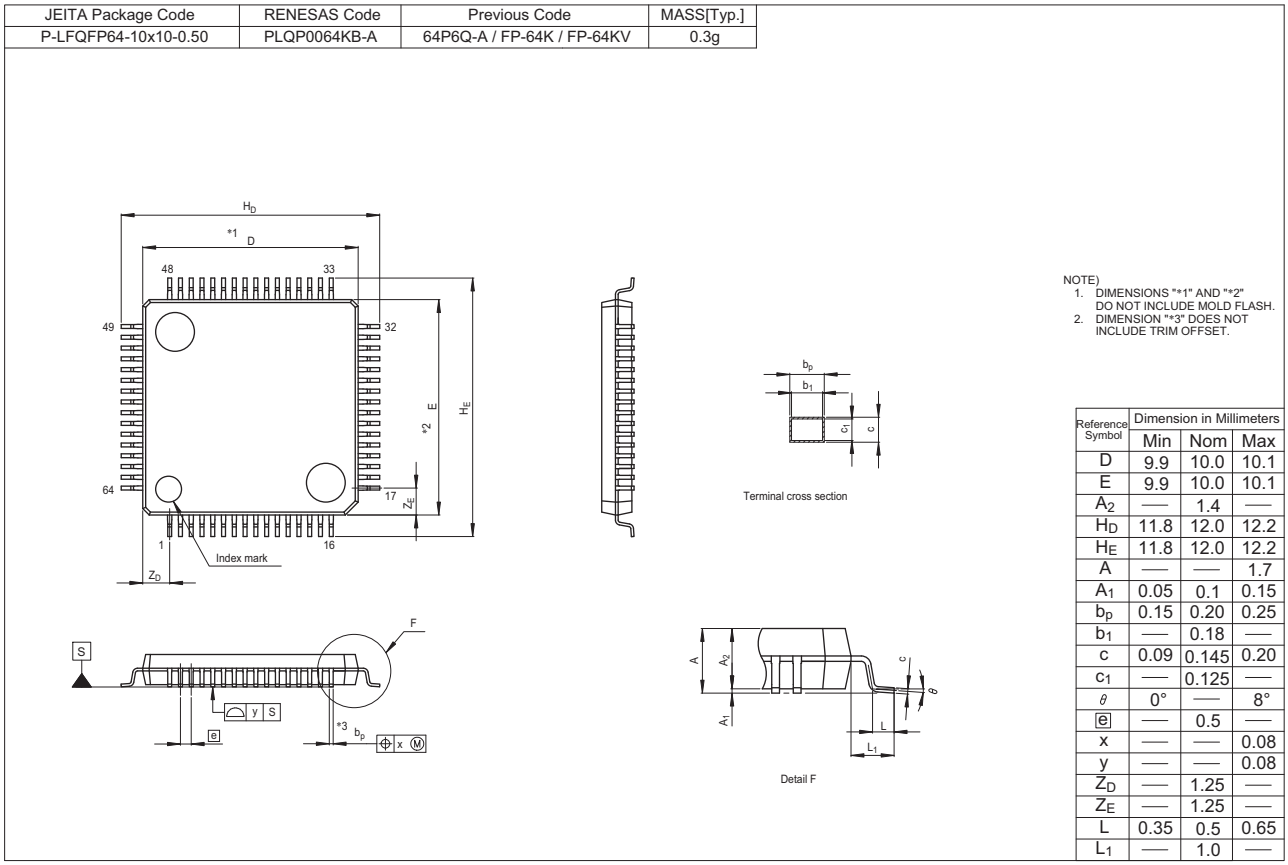
Note. Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

Figure 5.55 Connecting Capacitors (48-pin LFQFP)

Appendix 1. Package Dimensions

Information on the latest version of the package dimensions or mountings has been displayed in “Packages” on Renesas Electronics Corporation website.

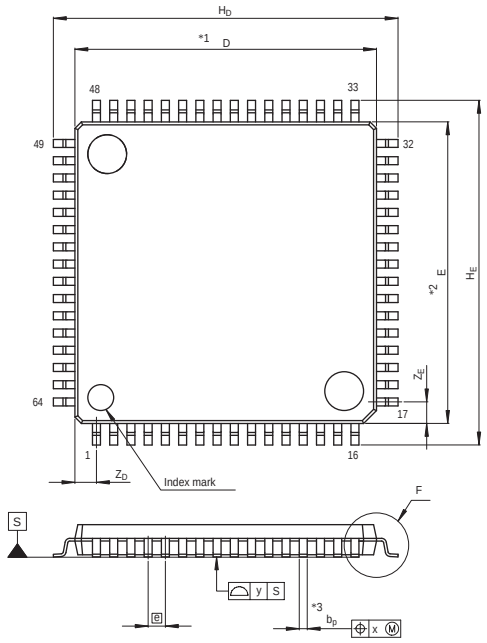
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g



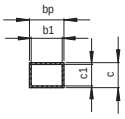
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure A 64-Pin LFQFP (PLQP0064KB-A)

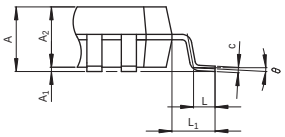
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g







Terminal cross section

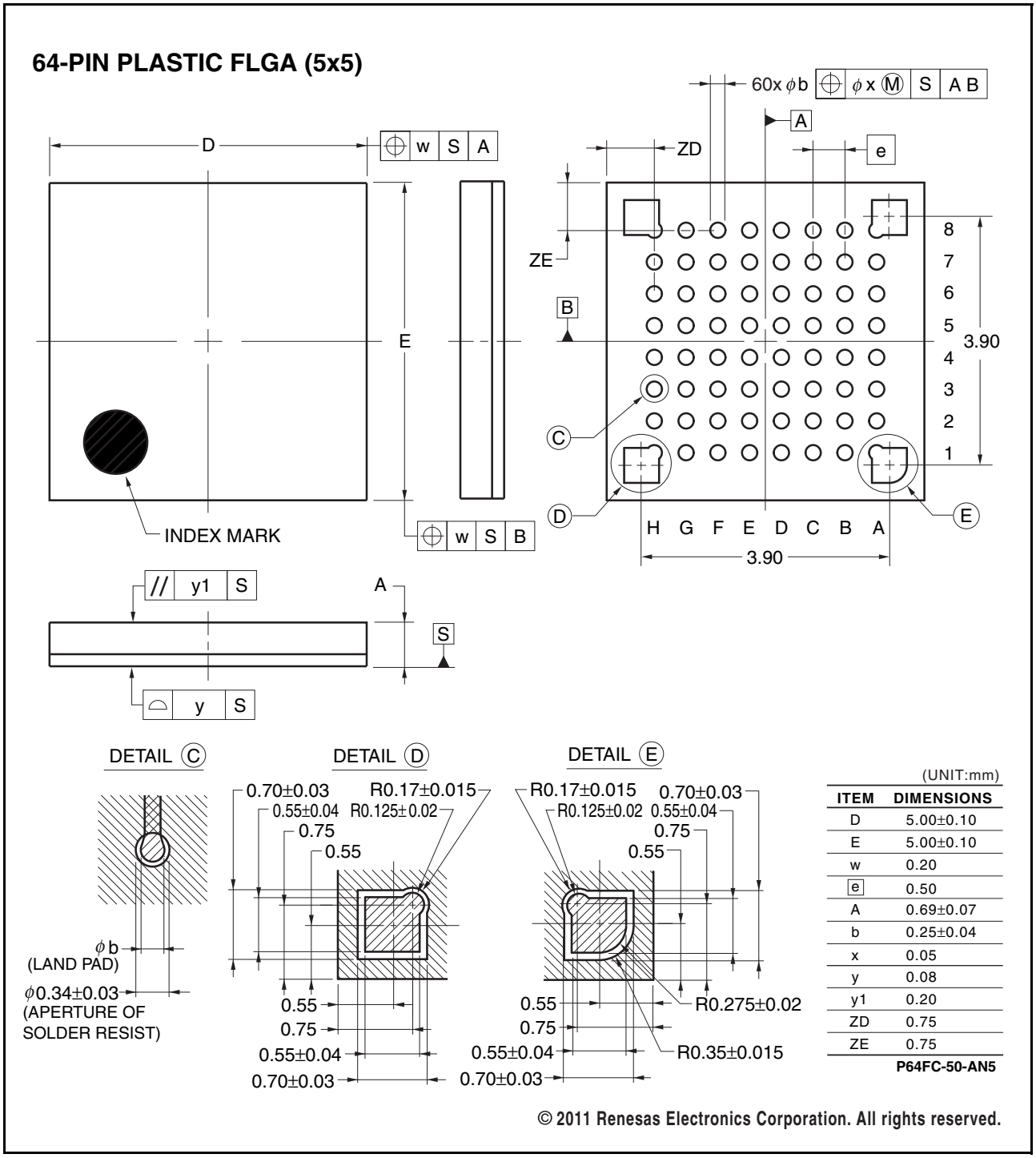


Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

Figure B 64-Pin LQFP (PLQP0064GA-A)



(UNIT:mm)

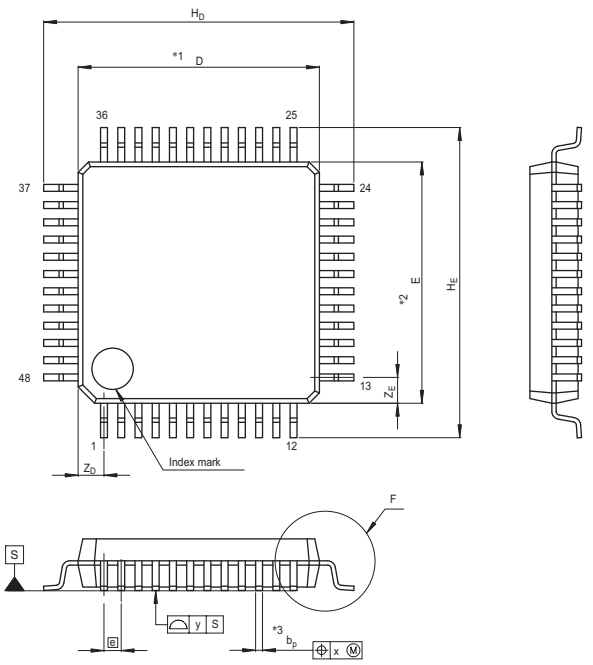
ITEM	DIMENSIONS
D	5.00±0.10
E	5.00±0.10
w	0.20
e	0.50
A	0.69±0.07
b	0.25±0.04
x	0.05
y	0.08
y1	0.20
ZD	0.75
ZE	0.75

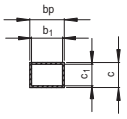
P64FC-50-AN5

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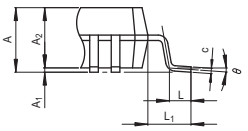
Figure C 64-Pin WFLGA (PWLG0064KA-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP48-7x7-0.50	PLQP0048KB-A	48P6Q-A	0.2g





Terminal cross section



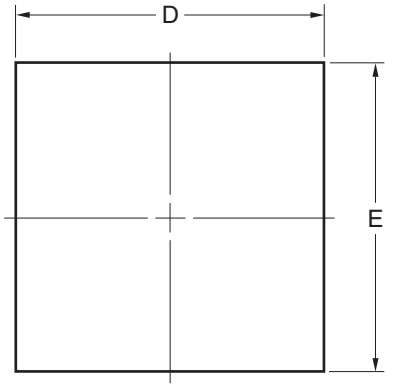
Detail F

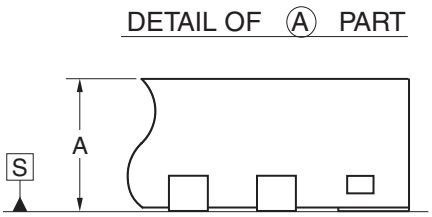
NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

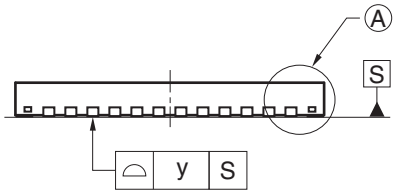
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.17	0.22	0.27
b_1	—	0.20	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z_D	—	0.75	—
Z_E	—	0.75	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure D 48-Pin LFQFP (PLQP0048KB-A)

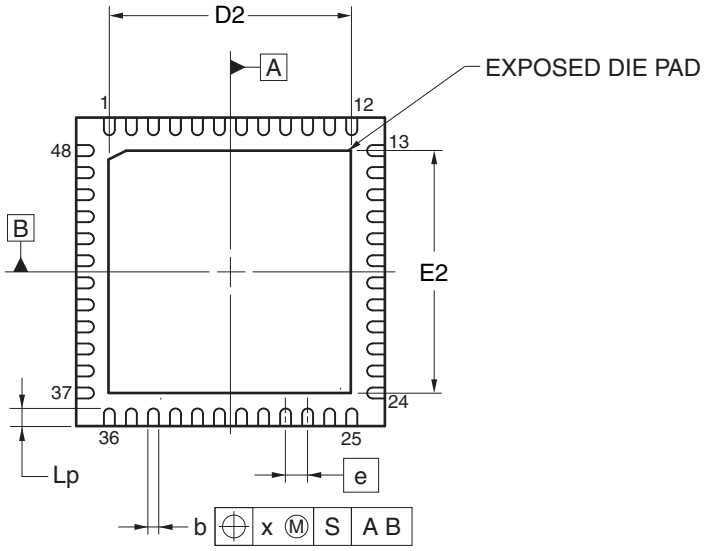
JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PJN-A P48K8-50-5B4-5	0.13







Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.95	7.00	7.05
E	6.95	7.00	7.05
A	0.70	0.75	0.80
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05

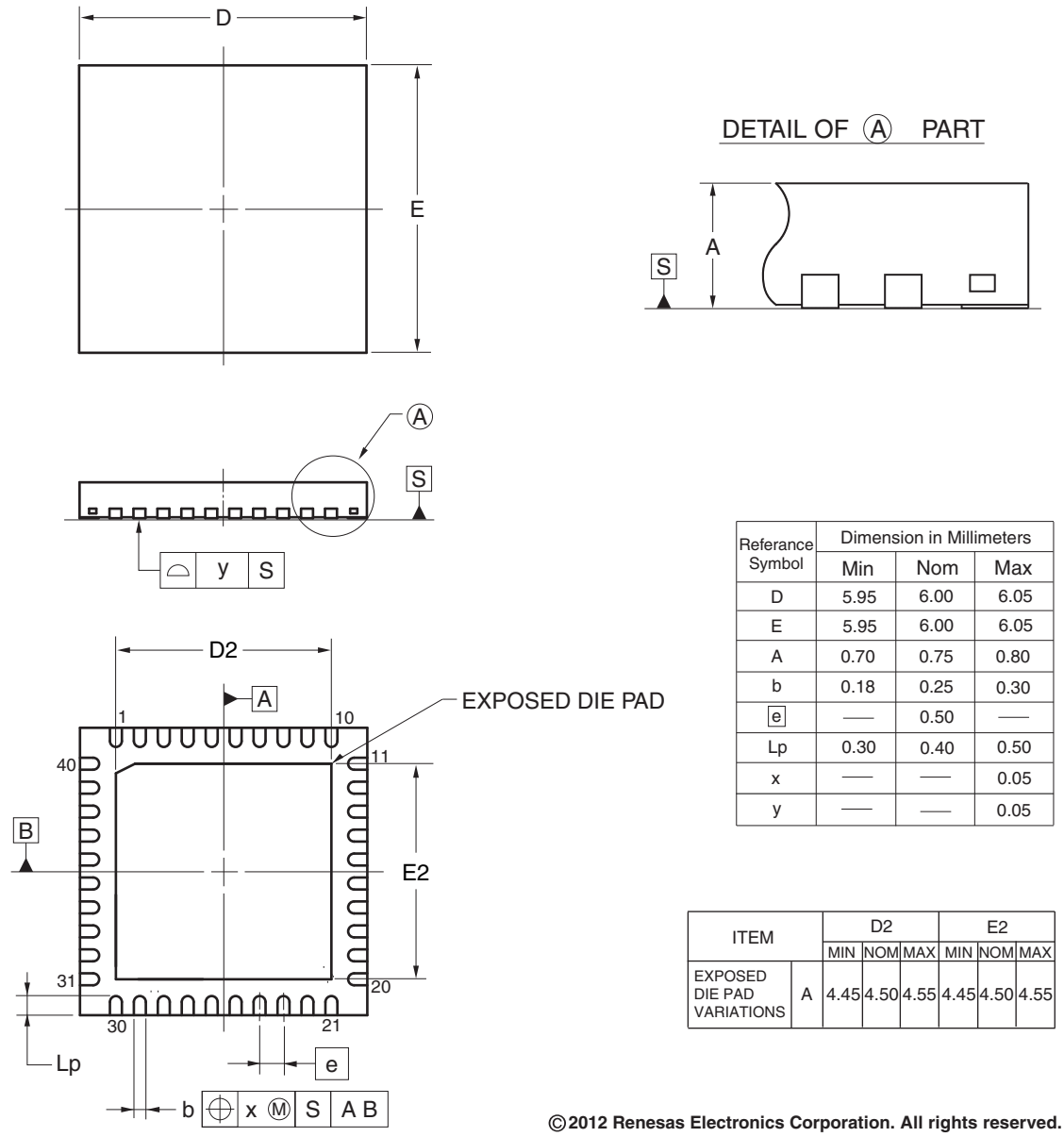


ITEM		D2			E2		
		MIN	NOM	MAX	MIN	NOM	MAX
EXPOSED DIE PAD VARIATIONS	A	5.45	5.50	5.55	5.45	5.50	5.55

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Figure E 48-Pin HWQFN (PWQN0048KB-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-HWQFN40-6x6-0.50	PWQN0040KC-A	P40K8-50-4B4-4	0.09



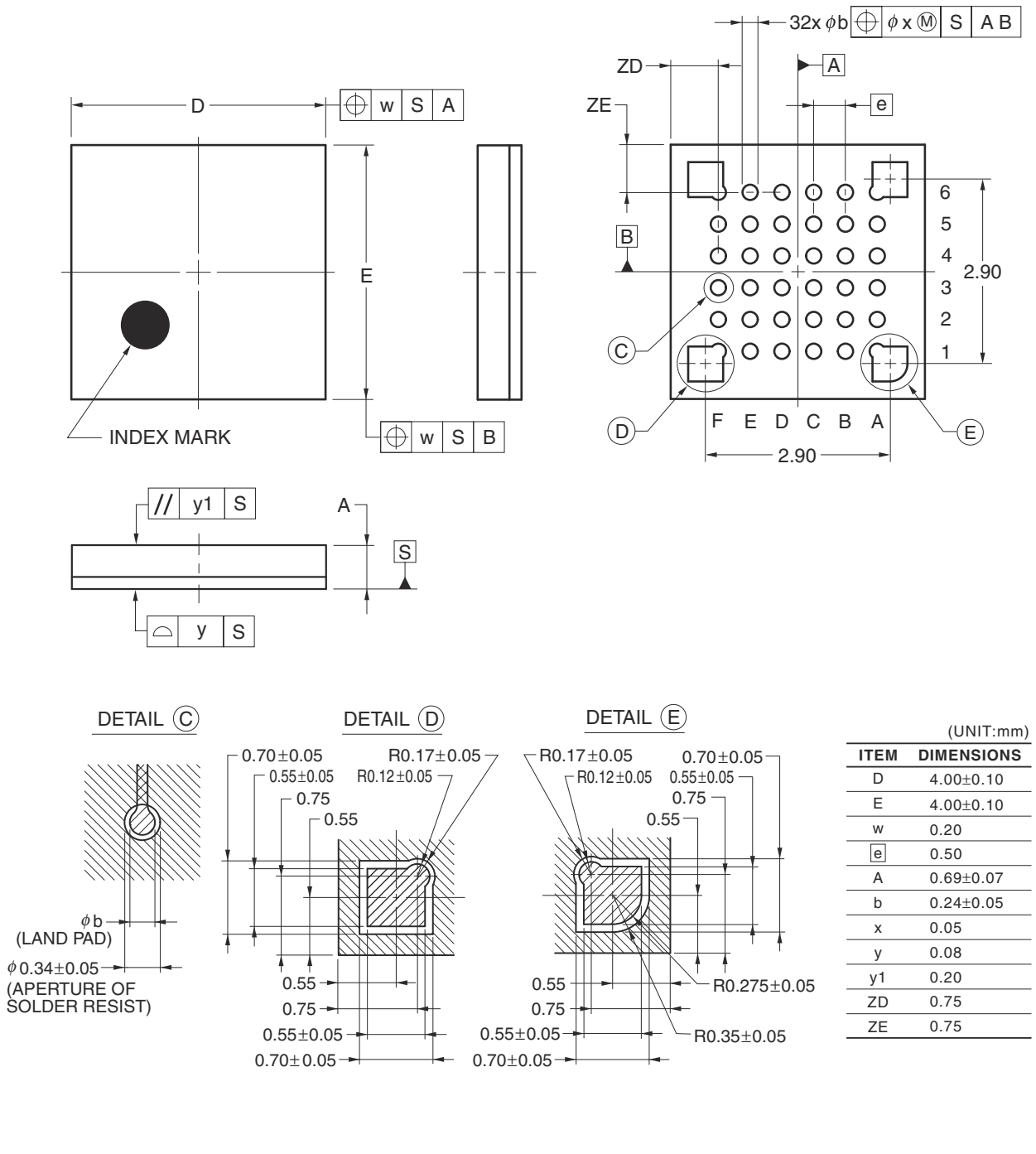
Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	5.95	6.00	6.05
E	5.95	6.00	6.05
A	0.70	0.75	0.80
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05

ITEM		D2			E2		
		MIN	NOM	MAX	MIN	NOM	MAX
EXPOSED DIE PAD VARIATIONS	A	4.45	4.50	4.55	4.45	4.50	4.55

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Figure F 40-Pin HWQFN (PWQN0040KC-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA36-4x4-0.50	PWLG0036KA-A	P36FC-50-AA4-2	0.023



(UNIT:mm)

ITEM	DIMENSIONS
D	4.00±0.10
E	4.00±0.10
w	0.20
e	0.50
A	0.69±0.07
b	0.24±0.05
x	0.05
y	0.08
y1	0.20
ZD	0.75
ZE	0.75

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Figure G 36-Pin WFLGA (PWLG0036KA-A)

REVISION HISTORY	RX110 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.51	Jul 03, 2013	—	First edition, issued
1.00	Dec , 2013	1. Overview	
		6, 7	Table 1.3 List of Products changed
		8	Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type changed
		9	Figure 1.2 Block Diagram changed
		4. I/O Registers	
		44	Table 4.1 List of I/O Registers (Address Order) changed
		5. Electrical Characteristics	
		45 to 91	Changed

Classifications

- Items with Technical Update document number: Changes according to the corresponding issued Technical Update
- Items without Technical Update document number: Minor changes that do not require Technical Update to be issued

Rev.	Date	Description		Classification
		Page	Summary	
1.20	Jul 29, 2016	1. Overview		
		18 to 25	Table 1.5 to 1.9 Note 1 regarding I/O power source is AVCC0 for the ports (P4, PJ6, and PJ7), added	
		5. Electrical Characteristics		
		45	Table 5.1 Absolute Maximum Ratings, Analog power supply voltage added	
		45	Table 5.2 Recommended Operating Conditions, VREFH0 / VREFL0 added	
		51	Table 5.8 DC Characteristics (6), Increment for IWDT operation added	
		52	Table 5.9 DC Characteristics (7) Permissible total consumption power added	TN-RX*-A135A/E
		53	Table 5.10 DC Characteristics (8), LDV1,2 added	
		54, 55	Table 5.15 Permissible Output Currents is divided into D version and G version	
		93	Table 5.45 ROM (Flash Memory for Code Storage) Characteristics (2), Erasure time - 128-Kbyte added	TN-RX*-A132A/E
		94	Table 5.46 ROM (Flash Memory for Code Storage) Characteristics (3), Temperature range for the programming/erasure operation changed and Erasure time - 128-Kbyte added	TN-RX*-A132A/E
		95, 96	5.9 Usage Notes added	

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NOTES FOR CMOS DEVICES

(1) VOLTAGE APPLICATION WAVEFORM AT INPUT PIN: Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between VIL (MAX) and VIH (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between VIL (MAX) and VIH (MIN).

(2) HANDLING OF UNUSED INPUT PINS: Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

(3) PRECAUTION AGAINST ESD: A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

(4) STATUS BEFORE INITIALIZATION: Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

(5) POWER ON/OFF SEQUENCE: In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

(6) INPUT OF SIGNAL DURING POWER OFF STATE : Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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